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HOW TO SOLDER - THE QUICK, THOROUGH GUIDE

Technology (/technology/) > Soldering | by loTalabs (/member/loTalabs/)

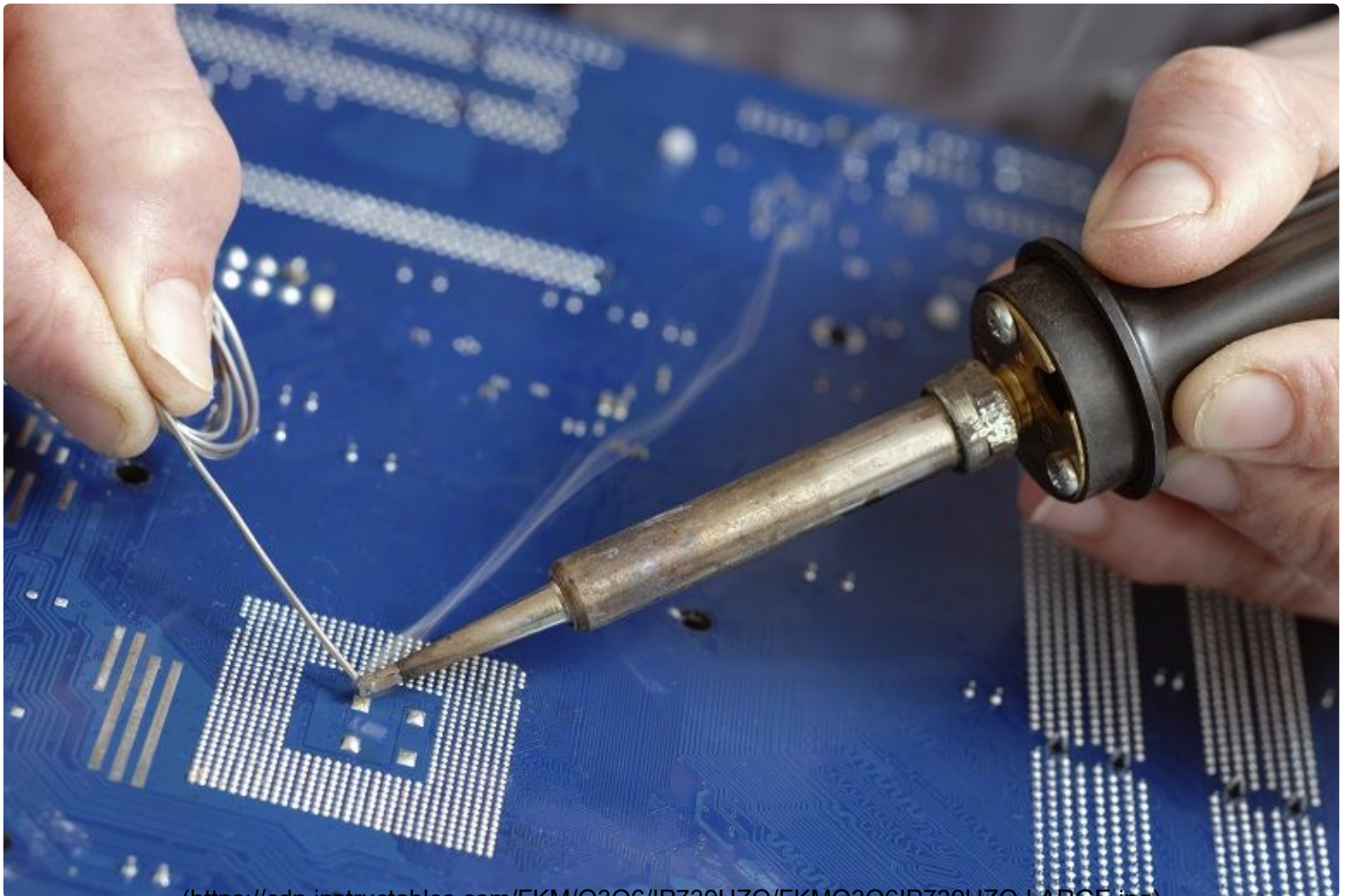
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We are IoTalabs and we are a group of Internet of Things enthusiasts that love hacking together different devices. Over the past few months we have immersed ourselves in the wonderful world of hardware! In our journey, we learned the best soldering practices around.

We've been working on many projects (check out our current project <http://doteverything.co/>) and we wanted to share our experience on safely and correctly soldering connections!

Add Tip

Ask Question

Step 1: What Is Soldering?

Soldering accomplishes a strong bond between two pieces of metal by joining them together. In this procedure, a material called solder, an alloy mixture of tin and lead, flows over two pre-heated pieces of metal and holds them together. The process is similar to welding but differs because when you weld you are fusing and melting two pieces together to make one. When you solder you are essentially 'gluing' two parts together with molten metal. Most metals with the exception of aluminum, white metal and porous cast iron can be soldered. Below, you will find instructions and illustrations that show you how to use a soldering iron.

Add Tip

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Step 2: Materials for Soldering



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Soldering Iron

Modeler's Vise or Frame (optional)

Solder

Damp Sponge

Flux to remove oxides

Add Tip

Ask Question

Step 3: Prepare Your Workspace

Make sure your table or bench top is clear and free of obstructions. You will want as much freedom as possible to move your hand around and make adjustments.

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Step 4: Turn on the Soldering Iron

The soldering iron needs to be warmed up properly before it can be used to ensure clean application of the solder. Some soldering irons heat up in seconds while others take minutes. Turn it on and leave it in the stand for 2-3 minutes to be safe.

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Step 5: (Optional) Secure the Items You Are Soldering

Because we only have two hands, it would be nice to stabilize the item we want to solder. This is where a vice or clamp that can hold your item sturdily would come in handy. This is not required, but can greatly increase the ease and quality of your solder joints.

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Step 6: Cleaning the Soldering Iron



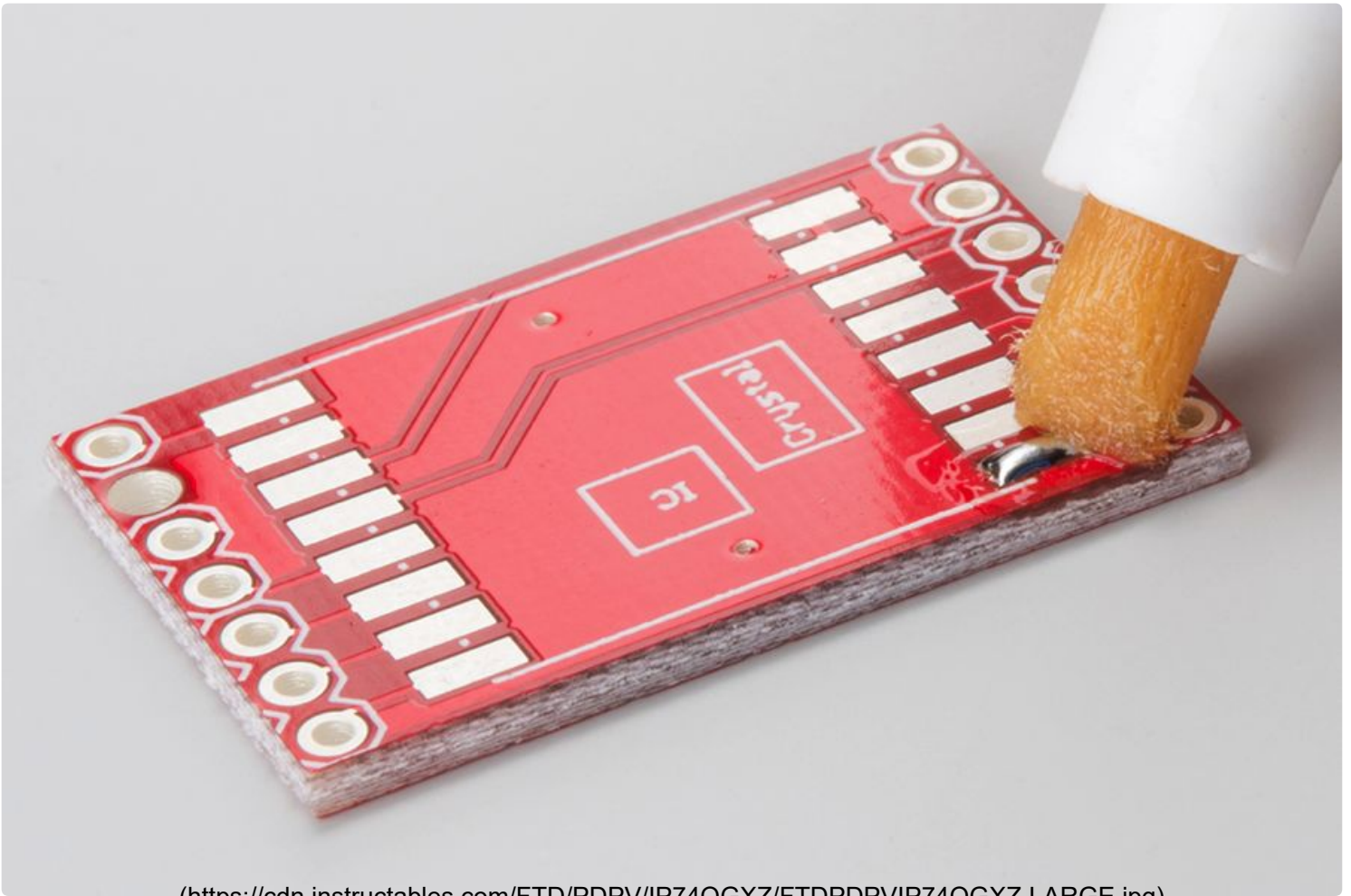
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Because soldering irons get so hot, they oxidize and become dirty quickly. The key to reliable connections is clean components so make sure that your soldering tip and parts you are joining are clean. To accomplish this, pass the tip of your soldering iron on a wet sponge until it shines.

Add Tip

Ask Question

Step 7: Apply Flux

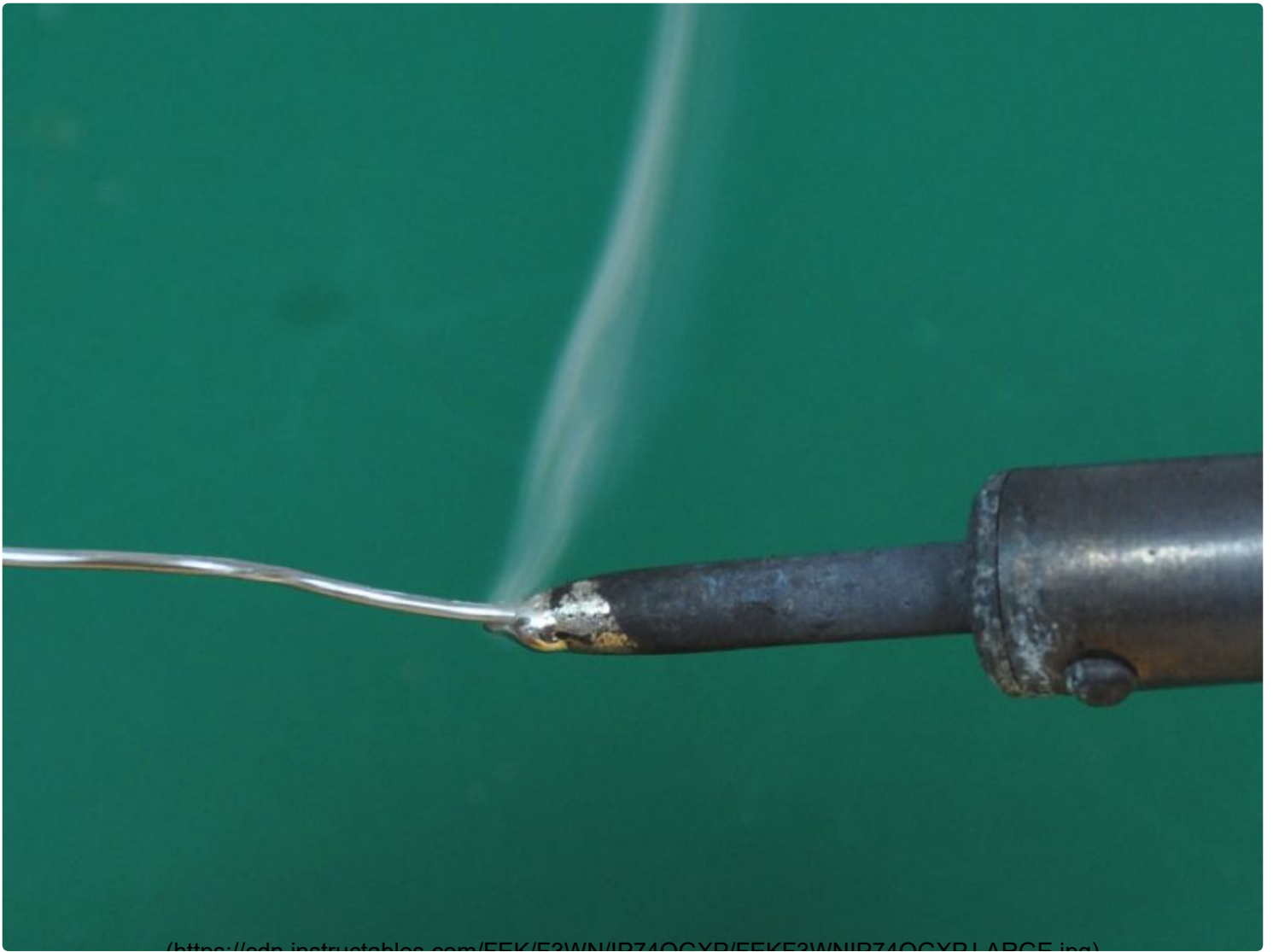


In soldering it often becomes necessary to use materials called fluxes to help remove oxides and keep them absent while you solder. Flux needs to melt at a temperature lower than solder so that it can do its job prior to the soldering action. There are different methods to apply flux. The method you choose will be dependent on the items you are soldering.

Add Tip

Ask Question

Step 8: Tin the Soldering Iron



If you want to know everything there is to know about how to use a soldering iron, you'll need to know how to tin. Tinning is the process of coating a soldering tip with a thin coat of solder. Melt a thin layer of solder on your iron's tip. This aids in heat transfer between the tip and the component you are soldering, and also gives the solder a base from which to flow from. This process may need to be repeated as you solder. You will only touch the tip of the soldering iron to the solder when you tin. Do not touch the tip of the iron to the solder while you are actually soldering.

Add Tip

Ask Question

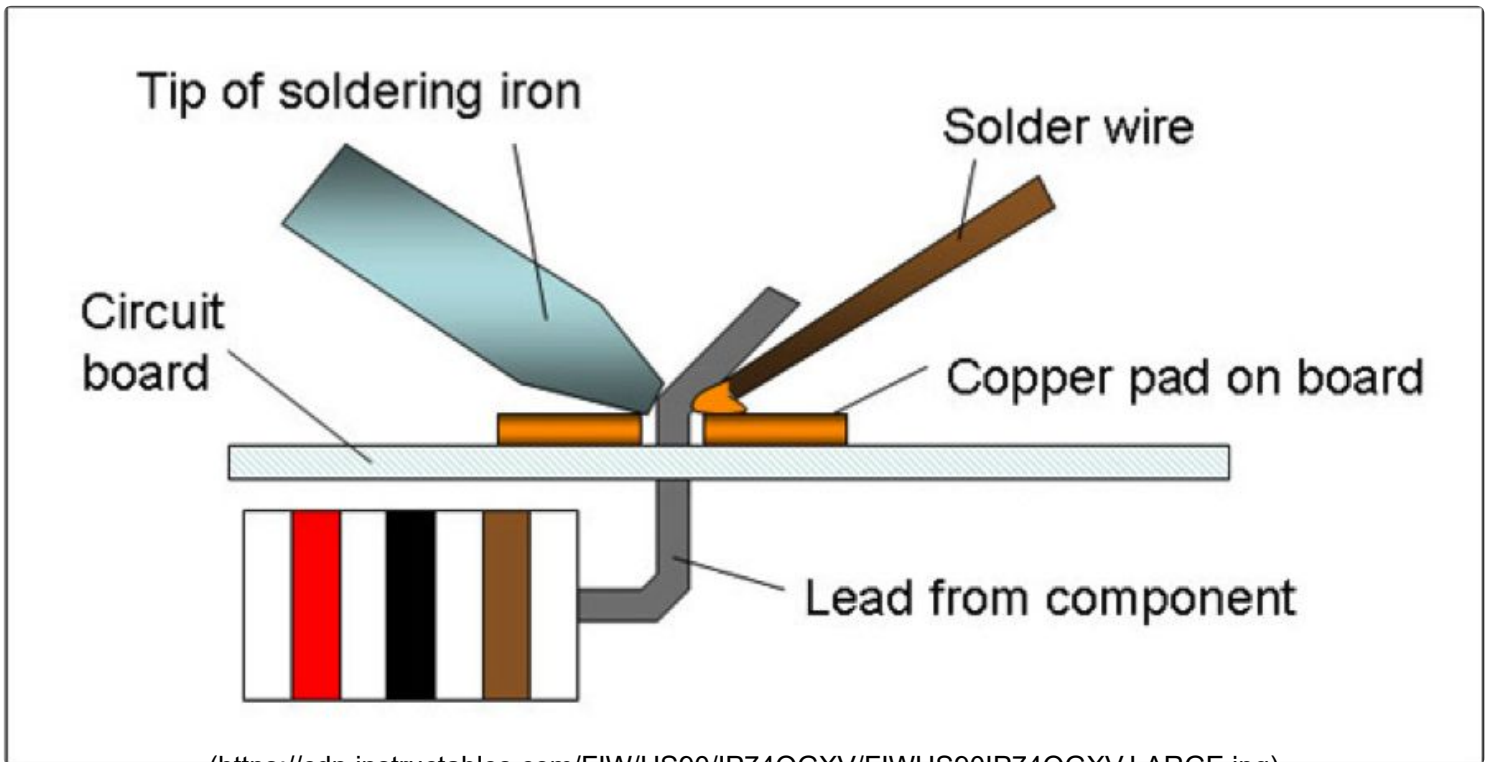
Step 9: Start Soldering

Hold the soldering iron like you would a pen in the hand you write with and the solder in the other. Then place the tip of the soldering iron. The tip needs to touch both the wire lead and the surface so they achieve the same temperature.

Add Tip

Ask Question

Step 10: Feeding the Solder



Touch the solder to the side of the connection opposite the soldering iron after heating the area for 2-3 seconds. Then, let the solder flow only until the connection is covered.

Add Tip

Ask Question

Step 11: Removing the Solder

Remove the solder first, then the iron otherwise your solder will get stuck to your connection point without the appropriate heat. Make sure the joint remains stationary while it cools.

Add Tip

Ask Question

Step 12: Check to See If the Connection Is Solid

A smooth, shiny and volcano shaped joint is what you are looking for. If this isn't what you see, you'll need to reheat and feed in more solder.

Add Tip

Ask Question

Step 13: Warnings

- DO NOT lay a soldering iron down on any surface. A soldering iron should either be placed on a stand or sealed with a heat resistant cap after every use.
- Soldering should be completed in a well ventilated area.
- Lead is present in most solders. Be sure to wash your hands after your project, or better yet wear gloves.
- Try not to inhale any of the solder smoke that comes off the solder. This is lead and can be dangerous.
- The tip of a soldering iron is very hot. Contact with the tip of a soldering iron would result in a nasty burn.
- Your soldering iron will perform better if kept clean. A damp sponge can be used to clean residue caused by flux material. A very small skim of flux should be applied to the iron after the cleaning.

THE BASICS OF HOW TO SOLDER

Soldering Tutorial for Beginners: Five Easy Steps



Table of Contents:

- [Before you begin](#)
- [Step 1: Heat your iron to the appropriate temperature](#)
- [Step 2: Make your connection mechanically stable](#)
- [Step 3: Clean the tip of your iron](#)
- [Step 4: Apply heat and solder](#)
- [Step 5: Inspect the joint](#)
- [Common mistakes](#)

Before you begin

You will need the following equipment:

A temperature-controlled soldering iron of 25W or more

A tip cleaner such as a brass sponge or a wet sponge

Solder (lead is easier to work with than lead-free)

(Optional) Helping hands

Safety glasses

Note: molten solder is extremely hot! Irons heat up to around twice the boiling point of water, so be extremely careful. Wear safety glasses when soldering.

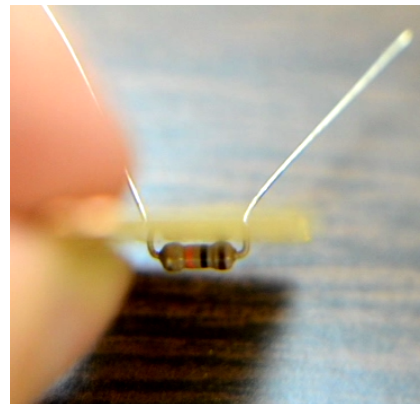
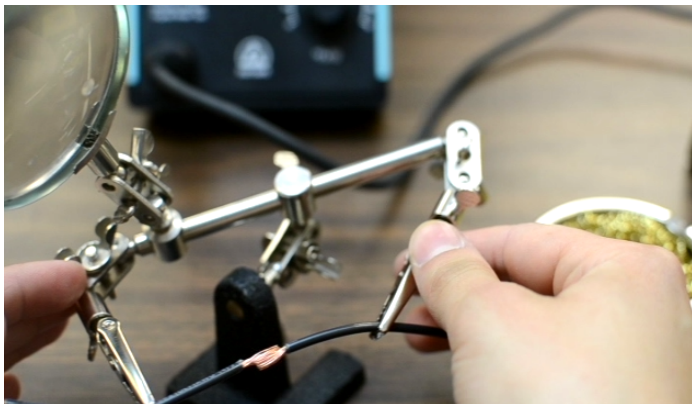
Step 1: Heat your iron to the appropriate temperature



For through-hole components in a circuit board, you will want 600-700 degrees fahrenheit.

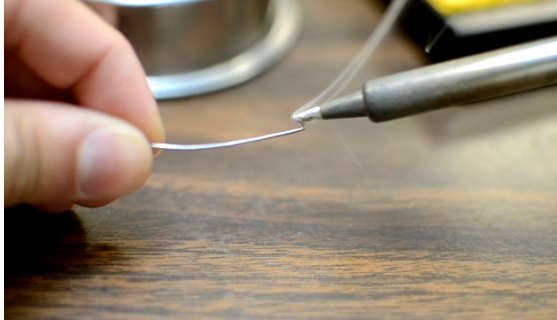
If you're soldering a larger connections, with more copper that's dissipating heat, then you may want a slightly higher temperature. With a temperature-adjustable iron you can see what works and adjust accordingly.

Step 2: Make your connection mechanically stable



While your iron is heating up, you can work on making your components stay in place without your help. This is where your helping hands may come in handy. Use them to help you arrange your components to be stable without you needing to hold anything. If you're soldering a through-hole component in a circuit board, you can bend the leads of the component into a V-shape so that it stays in place flush against the board. For components without long leads, you can use a piece of tape to hold them in place.

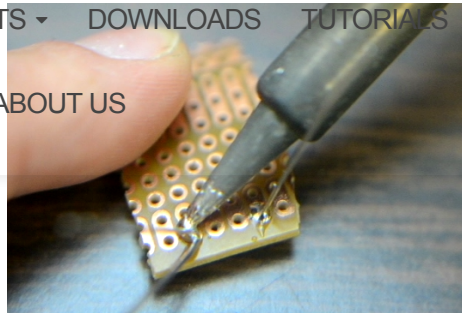
Step 3: Clean the tip of your iron



You can check whether your iron is close to its final temperature by touching your solder to the end of the iron and seeing if it melts. When you do this, you'll see some smoke come out. This is not the metal vaporizing, but rather the flux inside of it is burning. Flux is a mild acid that eats away at the oxidation layer that forms on the surface of hot metals. Without flux in the solder to clean your surfaces, you would have a very hard time getting the solder to wet.

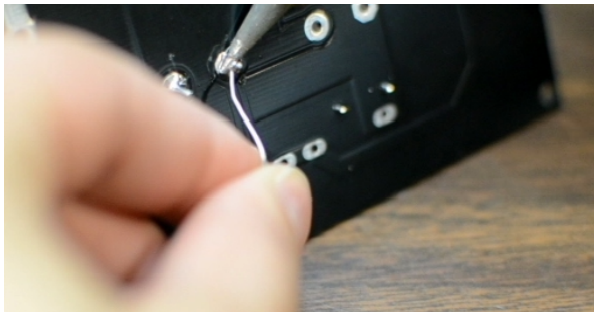
Clean your iron using a brass sponge or a wet sponge to remove any oxidation or excess solder from the tip. Remember to always keep your tip clean while you're soldering. A dirty tip is covered in metal oxides that transfer heat badly and can result in poorly soldered joints.

Step 4: Apply heat and solder



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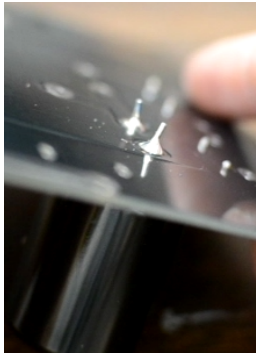
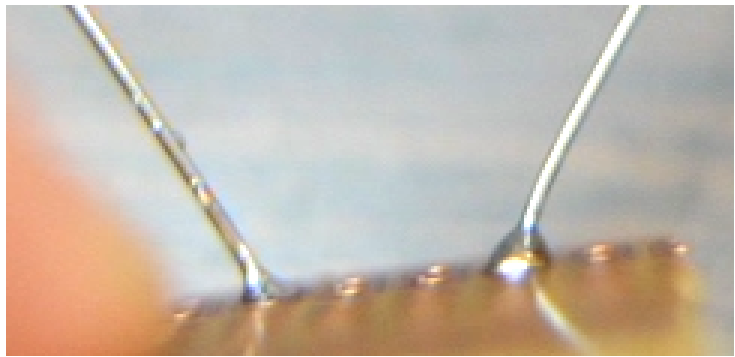
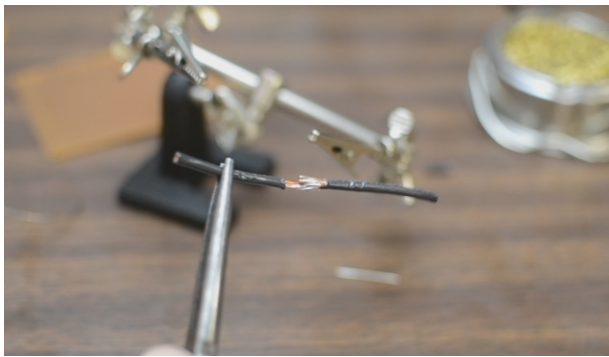
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Touch the flat part of your iron's tip to one side of the joint, while feeding solder from the other side of the joint. The idea is to heat up the entire joint to the melting temperature of solder, so when you touch the solder to the surfaces it melts right on. The only way you can ensure a good electrical connection is by letting the solder flow over the components you're joining. Don't apply the solder directly to the tip of the iron. For through-hole components, hold the iron against both the lead and the pad.

Small joints can heat up within a few seconds, but larger joints can take a minute or two. Keep the joint steady for a few seconds after removing the iron, as the solder needs time to cool. Remember that the joint is hot now! don't touch it with your fingers right away.

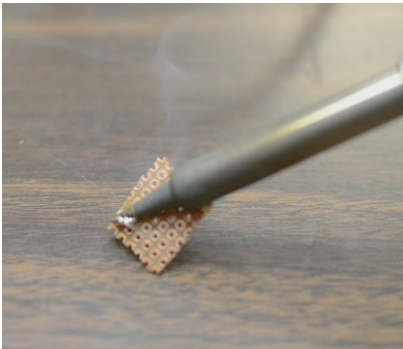
Step 5: Inspect the joint



The solder should have wetted to both surfaces. On pads of a printed circuit board, the solder should be covering the entire pad, and it should make a volcano shape between the pad and the lead, indicating good adhesion. Once the joint is perfect, clip the leads of through-hole components.

Common mistakes, or what NOT to do

Now that we've gone over what to do, let me tell you what NOT to do.



Don't put a blob of solder on the iron and then try to transfer it to your joint. This burns away all of the flux in the solder, which prevents the flux from cleaning the metal surfaces. Furthermore, it's easy to transfer the solder blob away from the iron without actually making it wet to the joint. I guarantee you that this will result in an awful electrical connection, so don't do it.

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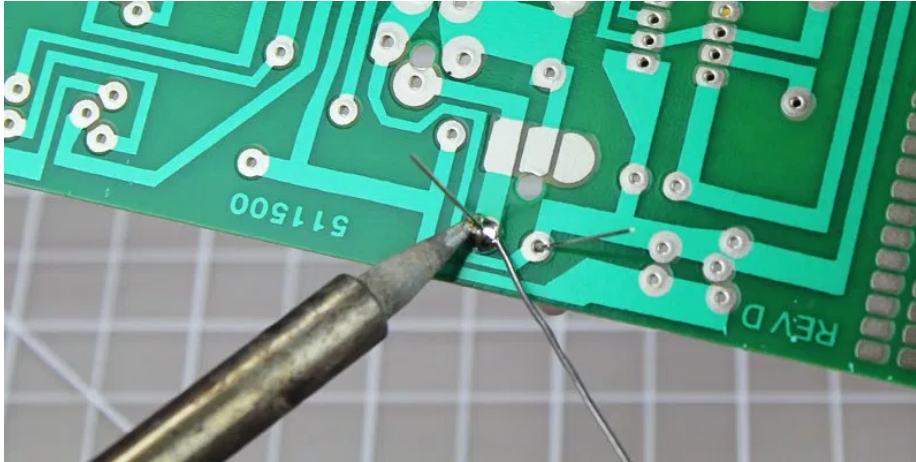
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How To Solder: A Beginner's Guide



Learning how to solder w/ proper soldering techniques is a fundamental skill every maker should master. In this tutorial, we outline the basics of soldering irons, soldering stations, types of solder, desoldering and safety tips.

Whether you're building a robot or working with Arduino, knowing how to solder will come in handy.

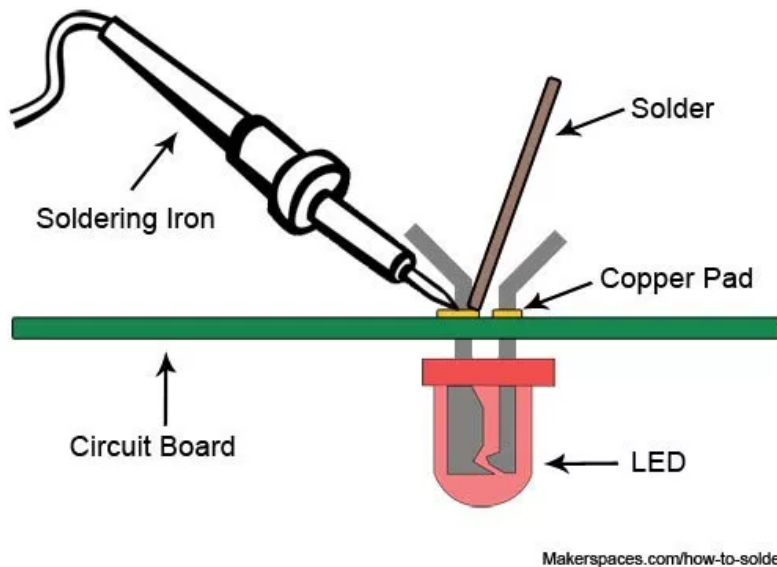
FREE EBOOK (PDF) – [Learn To Solder Guide \(17 pages\)](#)

What Is Soldering?

If you were to take apart any electronic device that contains a circuit board, you'll see the components are attached using soldering techniques. Soldering is the process of joining two or more electronic parts together by melting solder around the connection. Solder is a



using a desoldering tool as described below.



Soldering Tools

The good thing about learning how to solder is the fact that you don't need a lot to get started. Below we'll outline the basic tools and materials you will need for most of your soldering projects.

Soldering Iron

A [soldering iron](#) is a hand tool that plugs into a standard 120v AC outlet and heats up in order to melt solder around electrical connections. This is one of the most important tools used in soldering and it can come in a few variations such as pen or gun form. For beginners, it's recommended that you use the pen style soldering iron in



type of soldering iron because it can heat up to 896° F which is extremely hot.



Soldering Station

A [soldering station](#) is a more advanced version of the basic standalone soldering pen. If you are going to be doing a lot of soldering, these are great to have as they offer more flexibility and control. The main benefit of a soldering station is the ability to precisely adjust the temperature of the soldering iron which is great for a range of projects. These stations can also create a safer workspace as some include advanced temperature sensors, alert settings and even password protection for safety.



Soldering Iron Tips

At the end of most soldering irons is an interchangeable part known as a soldering tip. There are many variations of this tip and they come in a wide variety of shapes and sizes. Each tip is used for a specific purpose and offers a distinct advantage over another. The most common tips you will use in electronics projects are the [conical tip](#) and the [chisel tip](#).

Conical Tip – Used in precision electronics soldering because of the fine tip. Because of its pointed end, it's able to deliver heat to smaller areas without affecting its surroundings.

Chisel Tip – This tip is well-suited to soldering wires or other larger components because of its broad flat tip.

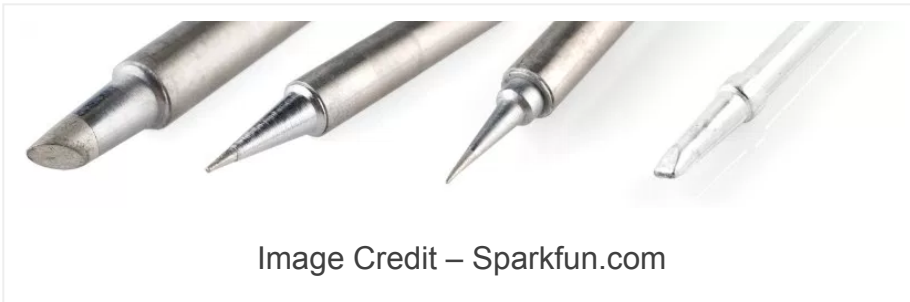


Image Credit – Sparkfun.com

Brass or Conventional Sponge



it did when it was new. You could use a conventional wet sponge but this tends to shorten the lifespan of the tip due to expansion and contraction. Also, a wet sponge will drop the temperature of the tip temporarily when wiped. A better alternative is to use a [brass sponge](#) as shown on the left.



Soldering Iron Stand

A [soldering iron stand](#) is very basic but very useful and handy to have. This stand helps prevent the hot iron tip from coming in contact with flammable materials or causing accidental injury to your hand. Most soldering stations come with this built in and also include a sponge or brass sponge for cleaning the tip.



Solder

Solder is a metal alloy material that is melted to create a permanent bond between electrical parts. It comes in both lead and lead-free variations with diameters of .032" and .062" being the most common. Inside the solder core is a material known as flux which helps improve electrical contact and its mechanical strength.

For electronics soldering, the most commonly used type is [lead-free rosin core solder](#). This type of solder is usually made up of a Tin/Copper alloy. You can also use leaded 60/40 (60% tin, 40% lead) rosin core solder but it's becoming less popular due to health concerns. If you do use lead solder, make sure you have proper ventilation and that you wash your hands after use.



When buying solder, make sure NOT to use acid core solder as this will damage your circuits and components.

Acid core solder is sold at home improvement stores and is mainly used for plumbing and metal working.

As mentioned earlier, solder does come in a few different diameters. The thicker diameter solder (.062") is good for soldering larger joints more quickly but it can make soldering smaller joints difficult. For this reason, it's always a good idea to have both sizes on hand for your different projects.

Helping Hand (Third Hand)

A [helping hand](#) is a device that has 2 or more alligator clips and sometimes a magnifying glass/light attached.

This clips will assist you by holding the items you are trying to solder while you use the soldering iron and solder. A very helpful tool to have in your makerspace.



Soldering Safety

Now that you know what tools and materials are required, it's time to briefly discuss ways of staying safe while soldering.

Soldering irons can reach temperatures of 800' F so it's very important to know where your iron is at all times.

We always recommend you use a soldering iron stand to help prevent accidental burns or damage.



Make sure you are soldering in a well ventilated area.

When solder is heated, there are fumes released that are harmful to your eyes and lungs. It's recommended to use a [fume extractor](#) which is a fan with a charcoal filter that absorbs the harmful solder smoke.

It's always a good idea to wear protective eye wear in case of accidental splashes of hot solder. Lastly, make sure to wash your hands when done soldering especially if using lead solder.

Tinning The Tip

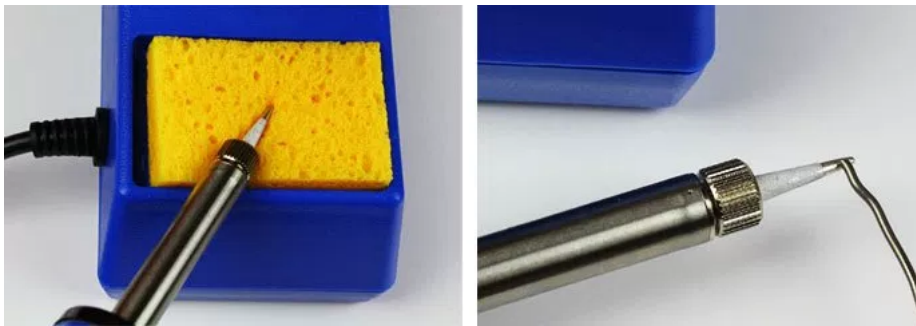
Before you can start soldering, you need to prep your soldering iron by tinning the tip with solder. This process will help improve the heat transfer from the iron to the item you're soldering. Tinning will also help to protect the tip and reduce wear.

Step 1: Begin by making sure the tip is attached to the iron and screwed tightly in place.



Step 3: Wipe the tip of the soldering iron on a damp wet sponge to clean it. Wait a few seconds to let the tip heat up again before proceeding to step 4.

Step 4: Hold the soldering iron in one hand and solder in the other. Touch the solder to the tip of the iron and make sure the solder flows evenly around the tip.



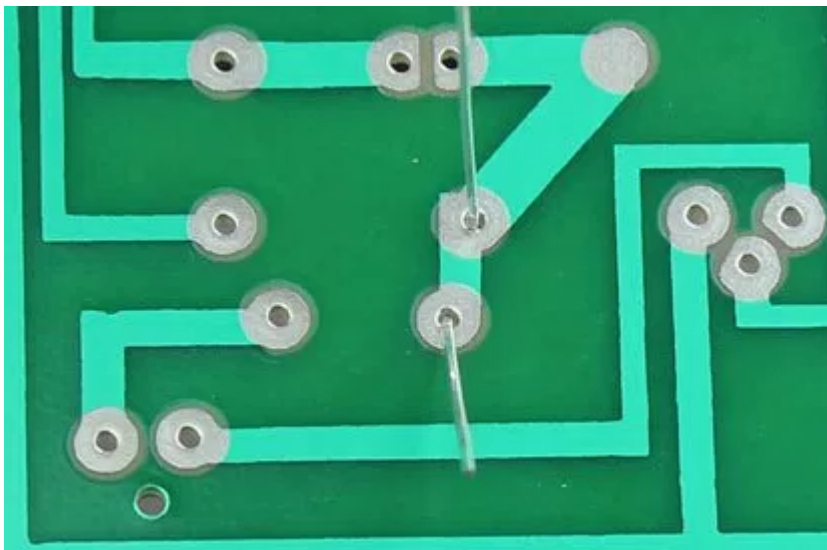
You should tin the tip of your iron before and after each soldering session to extend its life. Eventually, every tip will wear out and will need replacing when it becomes rough or pitted.

How To Solder

To better explain how to solder, we're going to demonstrate it with a real world application. In this example, we're going to solder an LED to a circuit board.

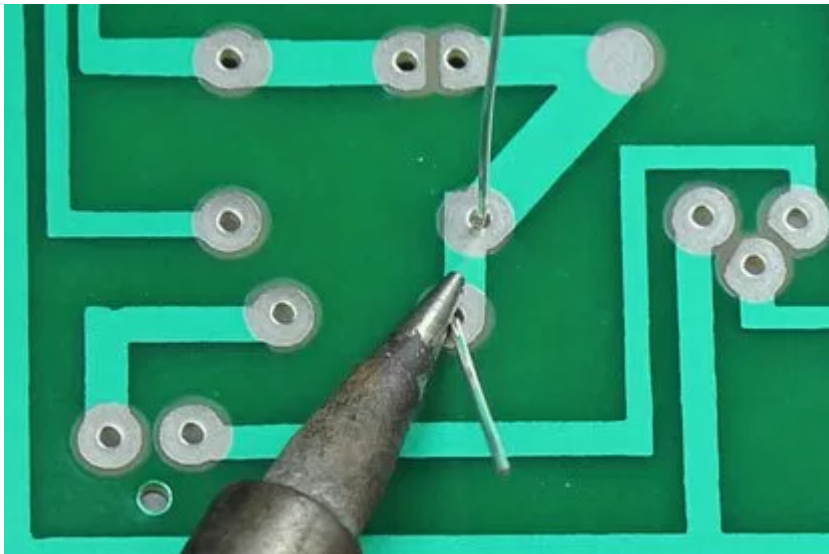


Step 1: Mount The Component – Begin by inserting the leads of the LED into the holes of the circuit board. Flip the board over and bend the leads outward at a 45° angle. This will help the component make a better connection with the copper pad and prevent it from falling out while soldering.





resistor lead at the same time. You need to hold the soldering iron in place for 3-4 seconds in order to heat the pad and the lead.

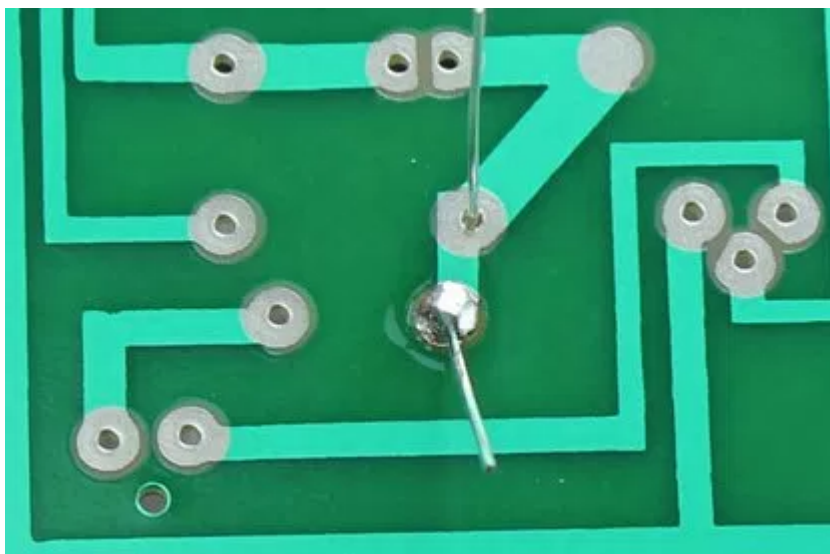


Step 3: Apply Solder To Joint – Continue holding the soldering iron on the copper pad and the lead and touch your solder to the joint. **IMPORTANT** – Don't touch the solder directly to the tip of the iron. You want the joint to be hot enough to melt the solder when it's touched. If the joint is too cold, it will form a bad connection.



Step 4: Snip The Leads – Remove the soldering iron and let the solder cool down naturally. Don't blow on the solder as this will cause a bad joint. Once cool, you can snip the extra wire from leads.

A proper solder joint is smooth, shiny and looks like a volcano or cone shape. You want just enough solder to cover the entire joint but not too much so it becomes a ball or spills to a nearby lead or joint.



How To Solder Wires



Begin by removing the insulation from the ends of both wires you are soldering together. If the wire is stranded, twist the strands together with your fingers.



Make sure your soldering iron is fully heated and touch the tip to the end of one of the wires. Hold it on the wire for 3-4 seconds.



Keep the iron in place and touch the solder to the wire until it's fully coated. Repeat this process on the other wire.



Hold the two tinned wires on top of each other and touch the soldering iron to both wires. This process should melt the solder and coat both wires evenly.



Remove the soldering iron and wait a few seconds to let the soldered connection cool and harden. Use heat shrink to cover the connection.



Desoldering

The good thing about using solder is the fact that it can be removed easily in a technique known as desoldering.

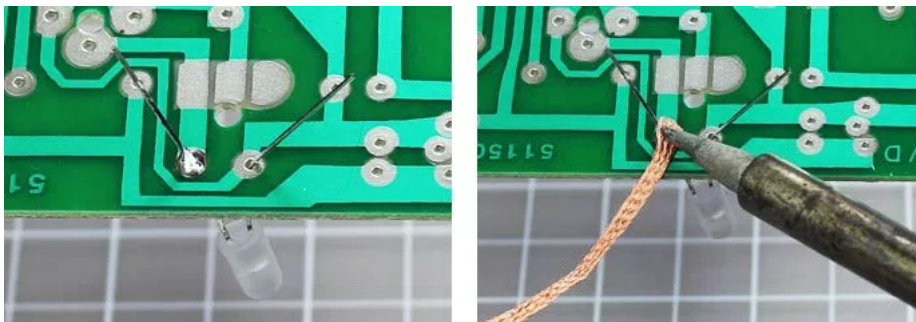


to desolder a joint, you will need solder wick which is also known as [desoldering braid](#).



Step 1 – Place a piece of the desoldering braid on top of the joint/solder you want removed.

Step 2 – Heat your soldering iron and touch the tip to the top of the braid. This will heat the solder below which will then be absorbed into the desoldering braid. You can now remove the braid to see the solder has been extracted and removed. Be careful touching the braid when you are heating it because it will get hot.





solder with a press of a button.

To use, press the plunger down at the end of the solder sucker. Heat the joint with your soldering iron and place the tip of the solder sucker over the hot solder. Press the release button to suck up the liquid solder. In order to empty the solder sucker, press down on the plunger.



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Adafruit Guide To Excellent Soldering

Created by Bill Earl



Last updated on 2014-06-28 08:30:54 PM EDT

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Basic Irons

There are many basic pencil style irons that are suitable for hobbist use. But you will need one that is capable of heating the joints quickly enough. Choose an iron with 25 watts at a minimum.



Better Irons

An adjustable temperature iron with a little more power will give you a bit more control and allow you to work faster. The [Adjustable 30W 110v Soldering Iron](http://adafru.it/180) (<http://adafru.it/180>) in the store is an excellent choice.

This iron is also available as part of [Ladyada's Electronics Toolkit](http://adafru.it/136) (<http://adafru.it/136>), which contains many other essential soldering tools.



Best Irons

A professional-style temperature-controlled iron with interchangeable tips and 50 watts or more of power is a joy to work with. Feedback control keeps the tip temperature at precisely the level you set. The extra watts speed recovery time so that you can work faster. Interchangeable tips let you select the ideal tip shape for specialized work.

The 65 watt [Hakko FX-888](http://adafru.it/303) (<http://adafru.it/303>) is an excellent professional quality soldering iron. The Weller WES51 or WESD51 are also excellent choices for serious electronics work.

Irons to avoid

In addition to underpowered irons, there are several types of irons to avoid for general circuit-board work.



For emergencies only:

These irons are handy for occasions when you have no place to plug in a regular soldering iron. But they are not the best choice for a primary soldering tool:

- **Butane Powered Irons** have plenty of power but are difficult to control.
- **Battery Powered Irons** are generally underpowered for most work.



Not for circuit board use:

These tools are not suitable for circuit board work:

- **Torches** of any kind are not suitable for electronics work and will damage your circuit boards.
- **Soldering Guns** are OK for working with heavy gauge wires, but don't have the precision necessary for soldering delicate electronics components.
- **Cold-Heat™** Irons inject current into the joint to heat the tip. This current can be damaging to sensitive electronic components. Avoid these irons for electronics work.

Essential Tools and Supplies:

These tools are the bare-minimum essentials required for soldering:



Stand

If your soldering iron does not have a built-in stand, you will need a safe place to rest the hot iron between uses. A [Soldering Iron Stand](http://adafruit.it/150) (<http://adafruit.it/150>) will keep your iron from rolling around and protect both you and your work surface from burns.

Most stand holders come with a sponge and tray for cleaning your soldering iron.



Solder

Standard [60/40 lead/tin Rosin Core Solder](http://adafruit.it/145) (<http://adafruit.it/145>) is the easiest type to work with.



Diagonal Cutters

You will also need a pair of [Diagonal Cutters](http://adafruit.it/152) (<http://adafruit.it/152>) for trimming component leads after soldering.

Other Handy Tools and Supplies

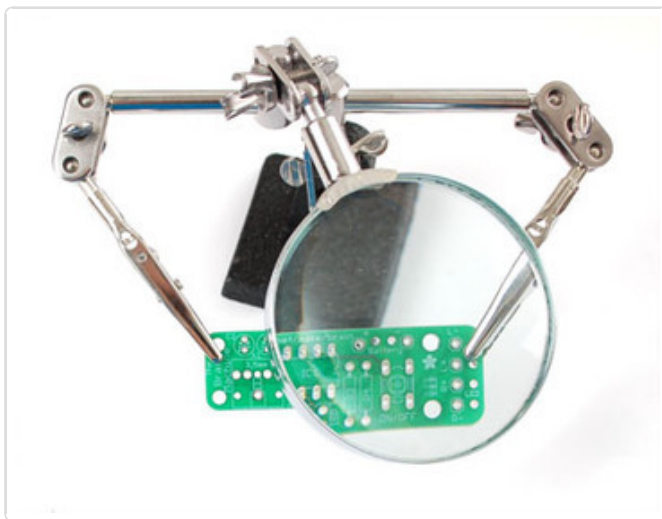
These are some other tools and supplies you might find useful when working on soldering projects.



Vise

A vise holds your work steady as you solder.

This is important for both safety and sound joints. The [Panavise Jr \(http://adafru.it/151\)](http://adafru.it/151) is an ideal size for most Adafruit kits and projects.



Third Hand

A [Helping Third Hand \(http://adafru.it/291\)](http://adafru.it/291) Tool is a good for smaller boards, or to hold things in place while terminating or splicing wires.



Solder Sucker

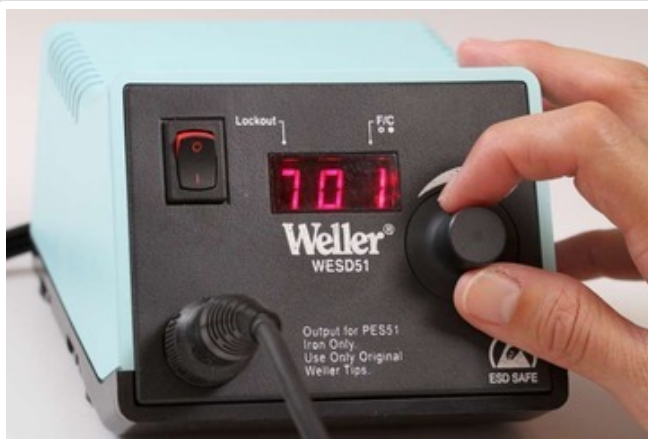
A [Solder Sucker \(http://adafruit.it/148\)](http://adafruit.it/148) is a very helpful tool for removing excess solder or when you need to de-solder a joint. As the name implies, this device literally sucks the solder out of the joint.



Solder Wick

[Solder Wick \(http://adafruit.it/149\)](http://adafruit.it/149) is another way to clean excess solder from a joint. Unlike the solder sucker, the wick soaks up the molten solder.

Preparation



Heat the Iron

Plug in and/or turn on your soldering iron to warm up. If you are using a temperature controlled iron, set it to 700F/370C for 60/40 or 750F/400C for lead-free solder.

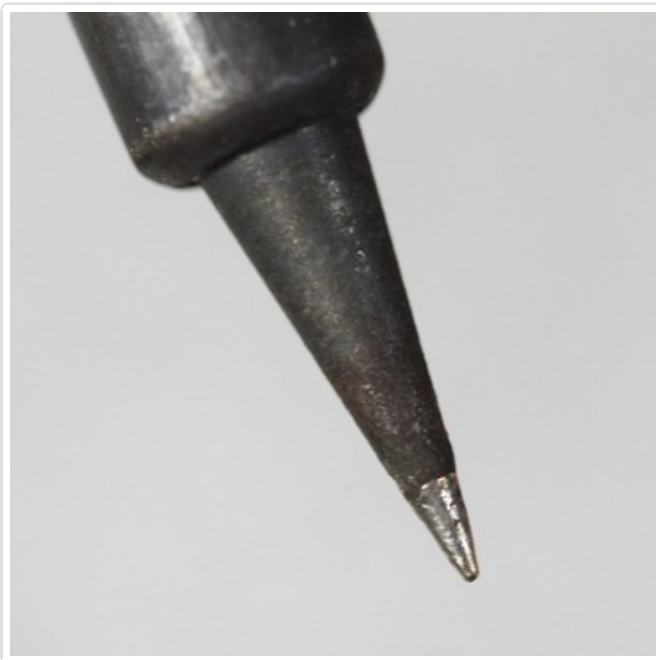
While the iron is heating dampen the sponge with a little bit of water.



Clean the Iron

Wipe the tip of the hot iron on the damp sponge to clean off any oxidation.

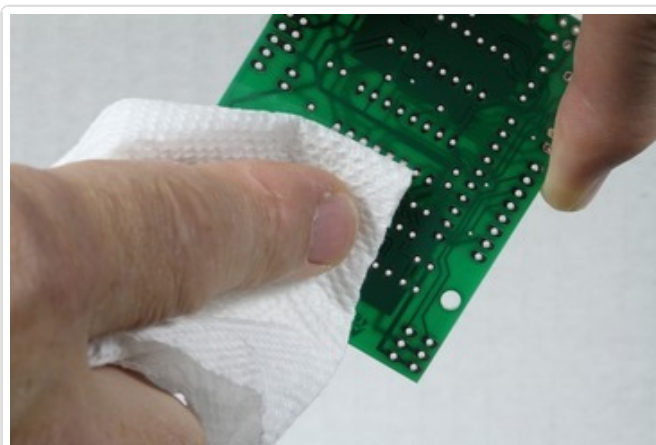
Do not use files or abrasives to clean the tip. It will damage the plating and ruin the tip.



Tin the Tip

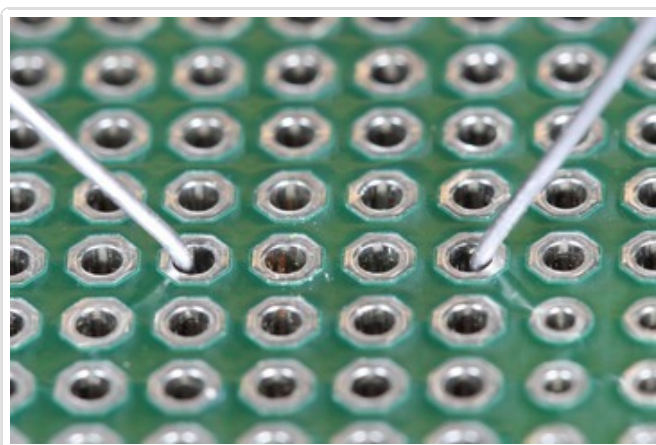
Apply a small amount of solder to the tip and wipe again to tin the tip. You should have a thin, shiny layer of molten solder on the tip of your iron.

If the tip is badly oxidized and difficult to tin, it can usually be reconditioned with some tip-tinning paste.



Make sure that the joint is clean

Dirt, oxidation and oily fingerprints can prevent the solder from wetting the solder-pad to create a solid joint. All Adafruit boards are plated to prevent oxidation, but if your board appears dirty from storage or handling, wipe it down with a little isopropyl alcohol.



Immobilize the Joint

This is very important! The parts being joined must not move during the soldering process. If there is any movement as the molten solder is solidifying, you will end up with an unreliable 'cold joint'.

Most through-hole components can be immobilized by simply bending the leads on the solder-side of the hole.

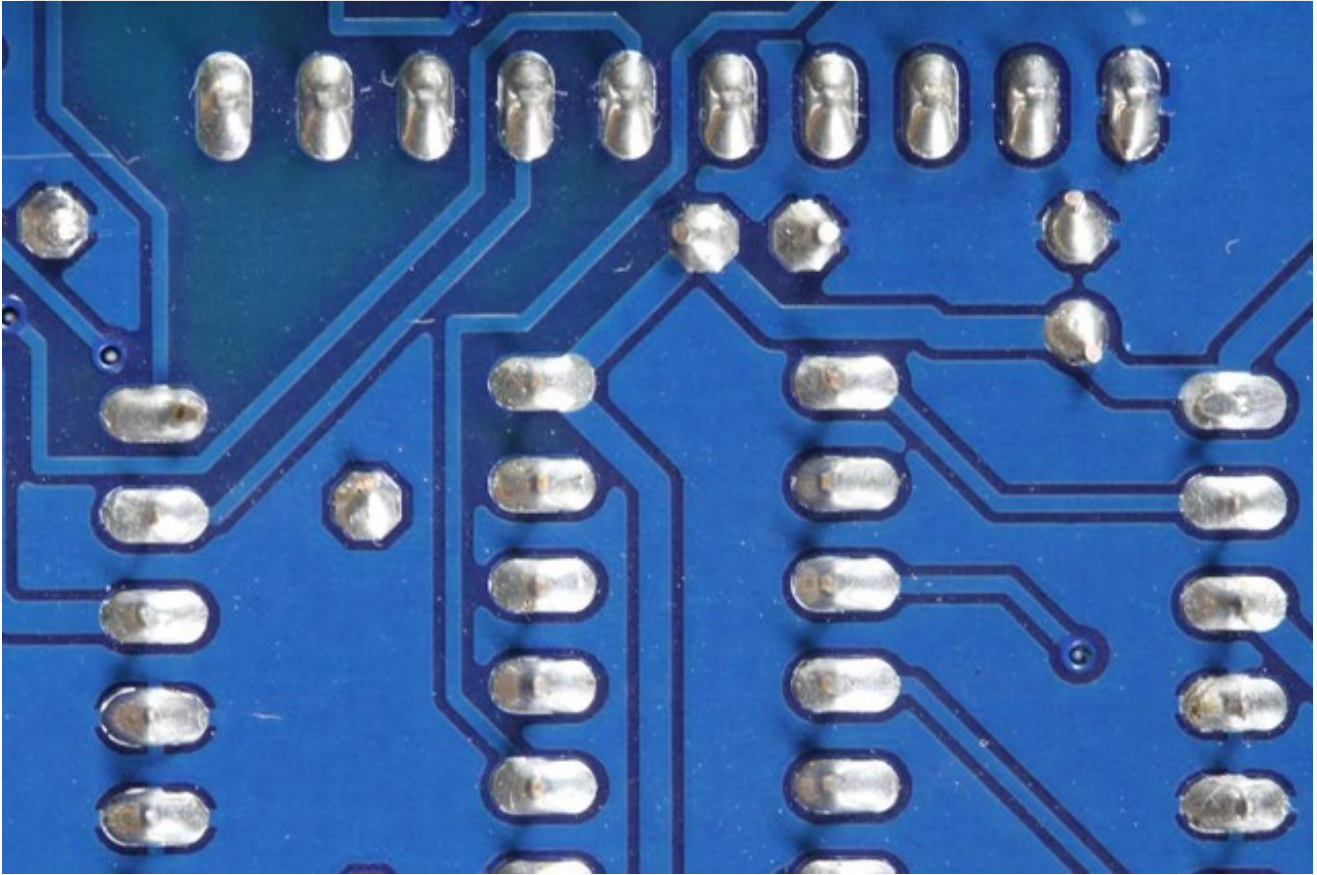


Steady the Board

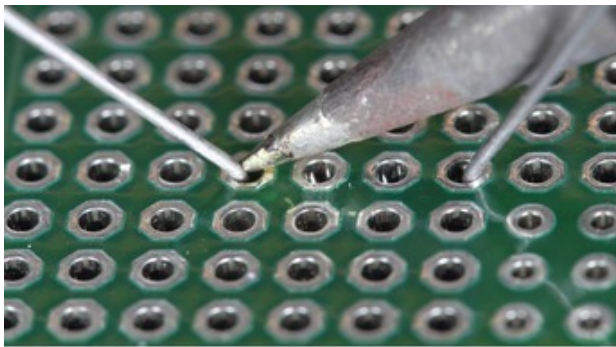
A vise is a good way to keep the board from moving around while you try to solder it.

Once the joint is clean and immobilized, you are ready to apply the solder.

Making a good solder joint

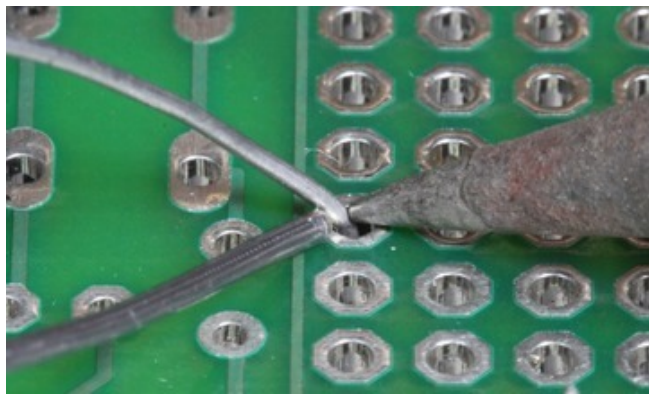


Once you have prepared the your tools and the joint to be soldered, making a good solder joint requires just a few simple steps.



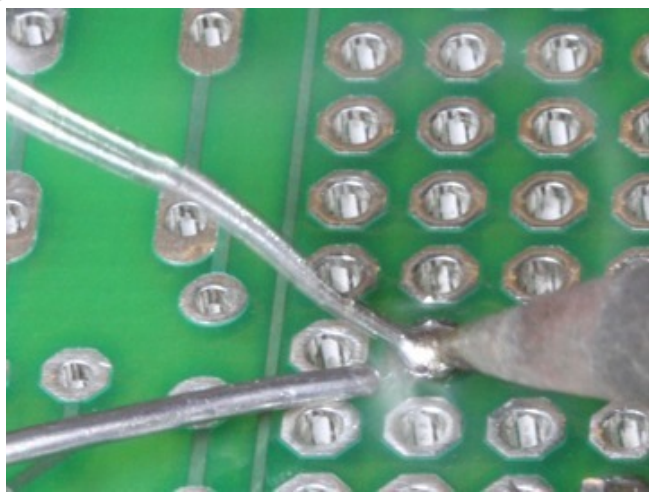
Heat the joint

Heat the joint with the tip of the iron. Be sure to heat both the solder pad and the component lead or pin. A small drop of solder on the tip will help to transfer the heat to the joint quickly.



Apply the solder

Touch the end of the solder to the joint so that it contacts both the solder pad and the component lead or pin. It should melt and flow smoothly onto both the pin and the pad. If the solder does not flow, heat the joint for another second or two and try again.

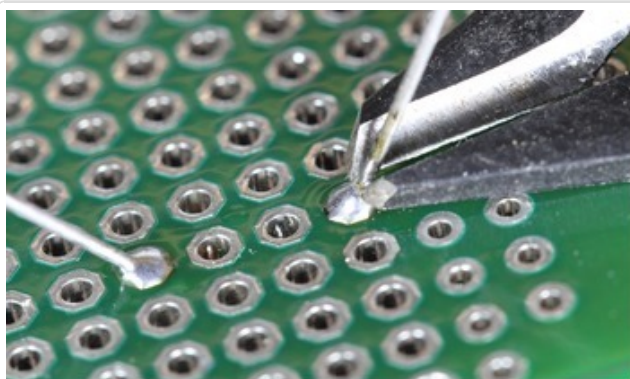


Let It Flow

Keep heating the solder and allow it to flow into the joint. It should fill the hole and flow smoothly onto both the solder pad and the pin or component lead.

Let It Cool

Once enough solder has been added to the joint and it has flowed well onto both the component lead and the solder pad, remove the iron from the joint and allow it to cool undisturbed.



Trim the Lead

Use your diagonal cutters to trim the lead close to the board.

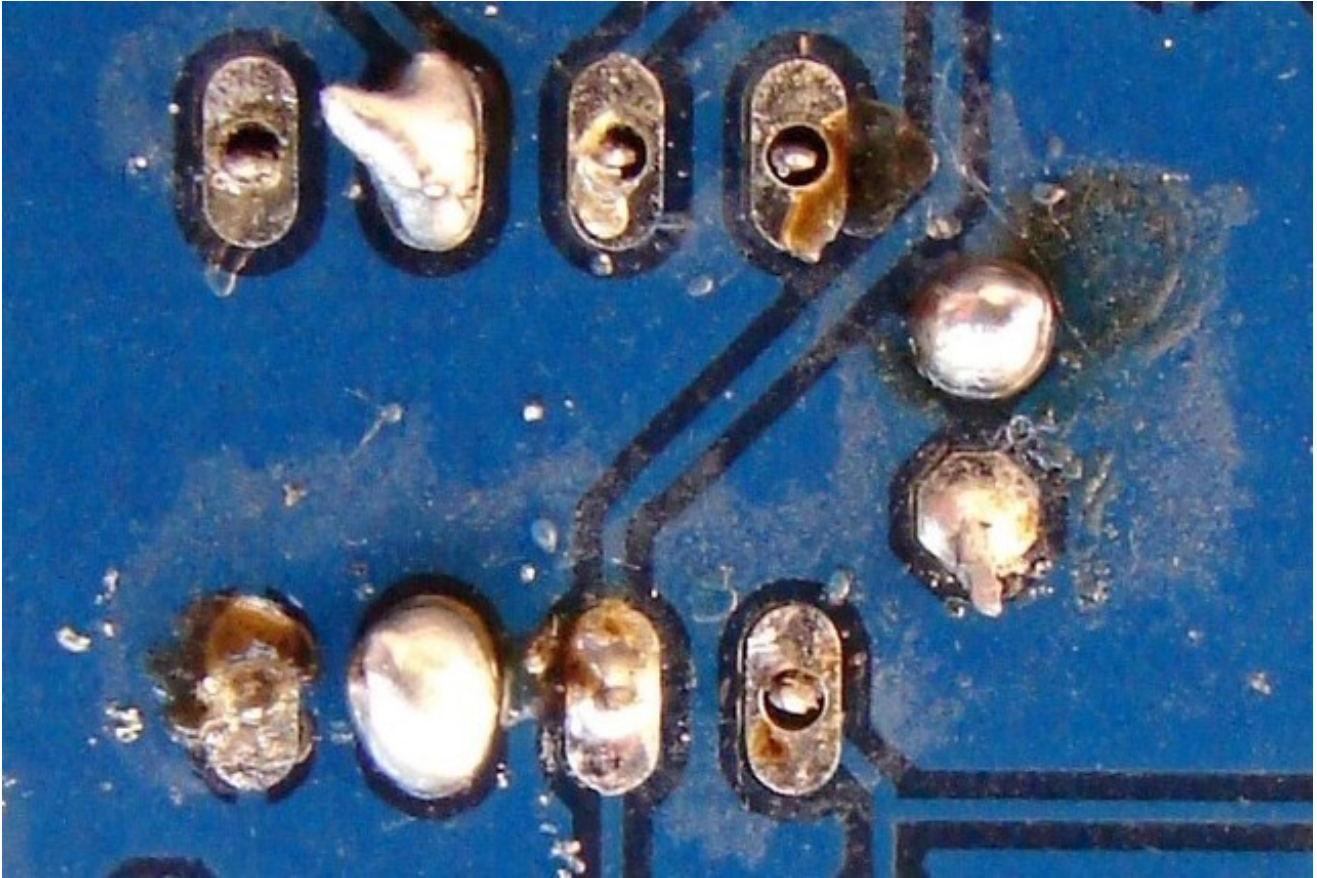
Note: This step applies only to components with wire leads. It is not necessary to trim the pins on Integrated circuit chips or sockets.



Congratulations!
Reward yourself with a [Soldering Badge](http://adafruit.it/465) (<http://adafruit.it/465>).

Problems?

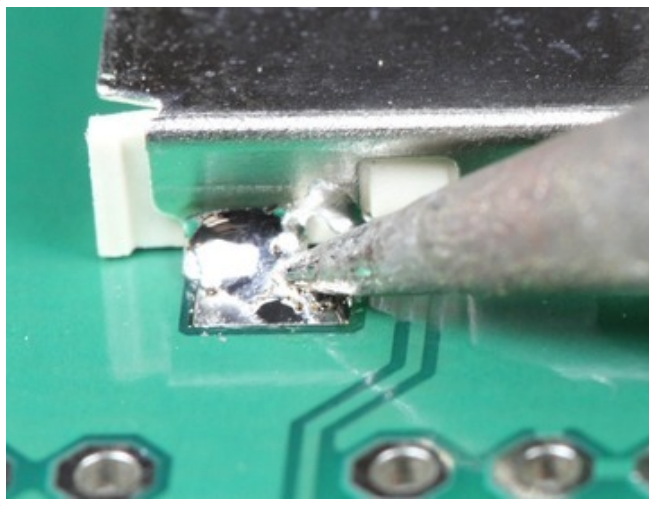
The last page of this guide illustrates a number of common soldering problems with advice on prevention and repair.



Surface Mount Components

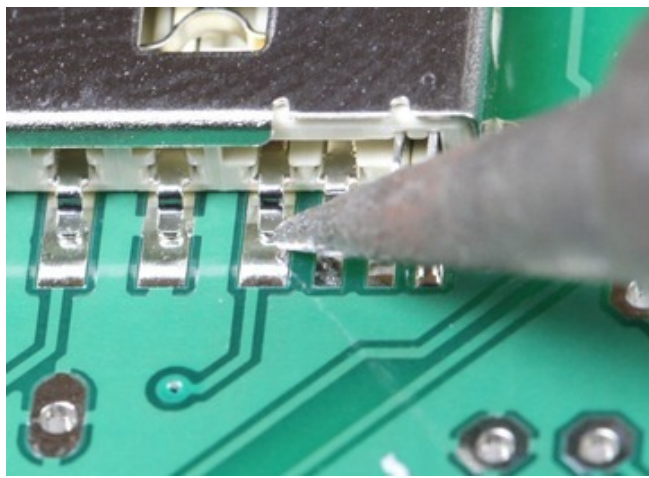
The previous page showed how to make a good through-hole joint. But more and more components are only available in surface mount form these days. Not all surface mount packages are easily worked by hand, but there are plenty that can be managed with the same basic tools used for through-hole soldering.

Let's start with a surface-mount part common to several Adafruit kits: The SD Card Holder:



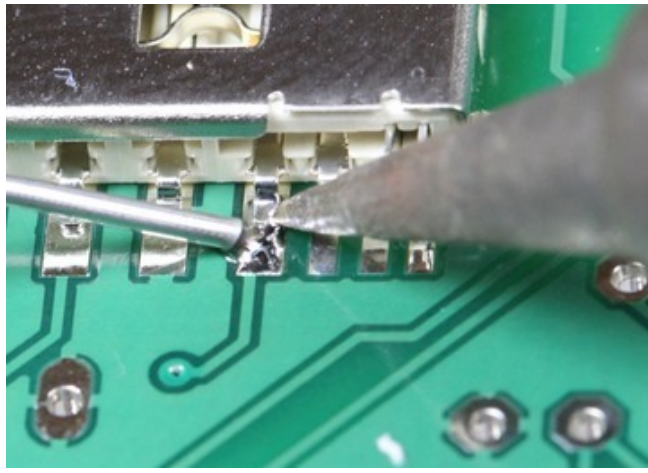
Immobilize the Joint

Unlike many surface mount components, immobilizing the SD card holder is relatively easy. There are small pegs on the back that fit into positioning holes in the board. Once it is in place, solder the four small corner tabs to make it permanent.



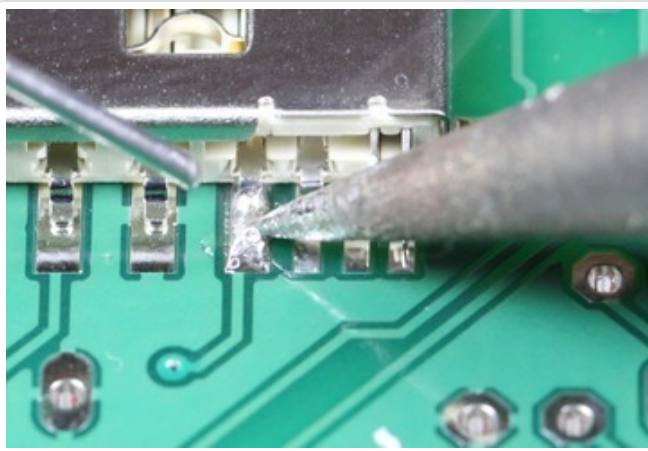
Heat the Joint

Start by putting the tip of the hot iron on the solder pad adjacent to the pin. The pad will take longer to heat, so we apply most of the heat to the pad to start.



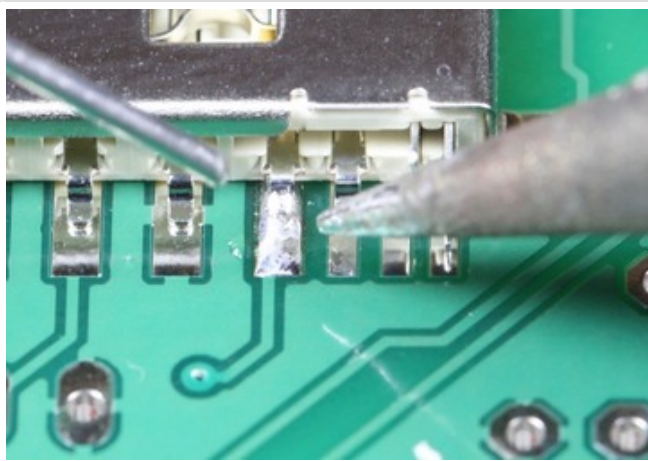
Apply the Solder

When the joint is hot, apply solder to the side opposite the iron. The solder should melt and start to flow into the joint.



Let it Flow

Apply just enough solder to ensure a good joint, then keep the heat on while the solder wicks up between the pin and the pad to make a good electrical bond.



Let it Cool

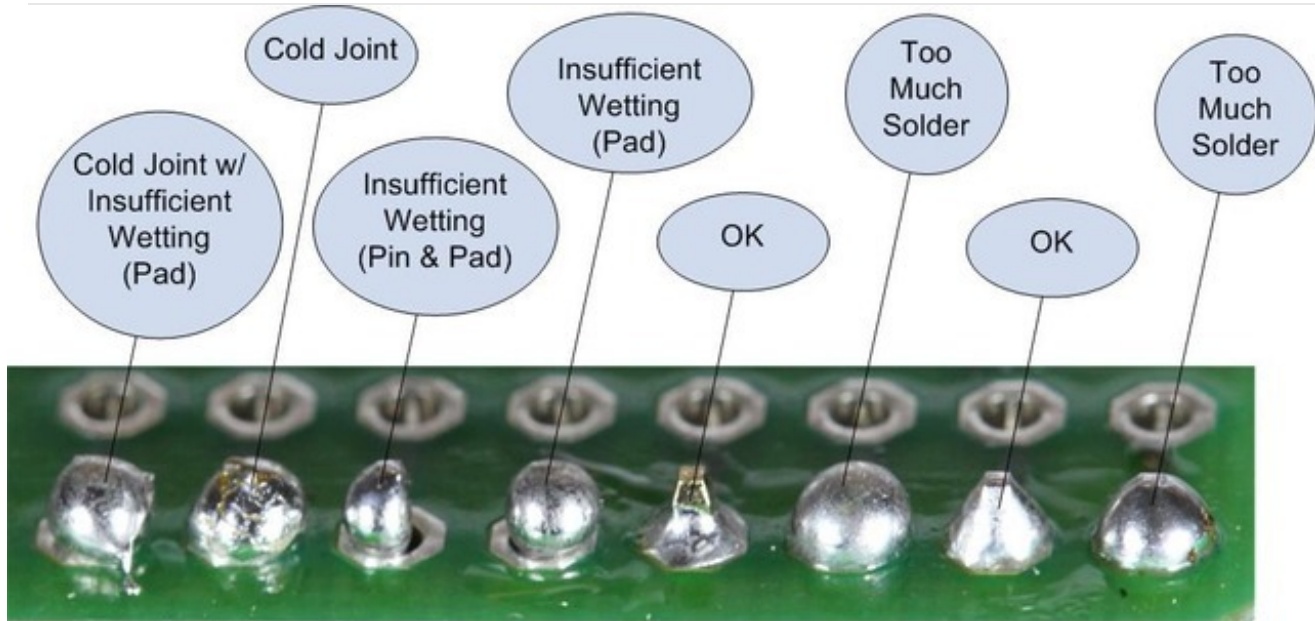
Remove the iron and allow the joint to cool undisturbed.

Problems?

The last page of this guide illustrates a number of common soldering problems with advice

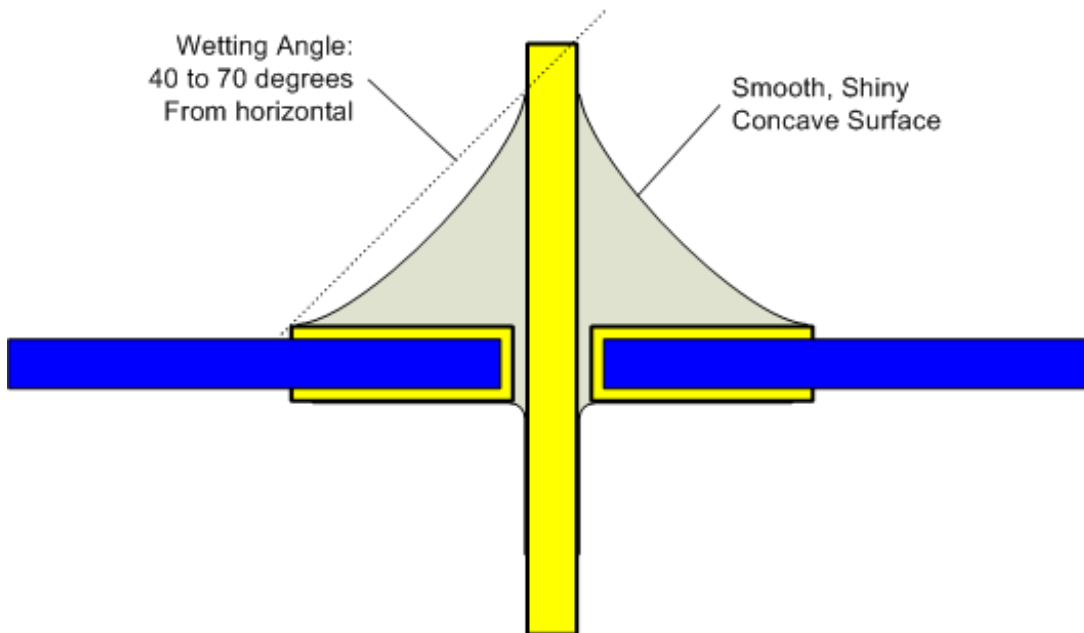
on prevention and repair.

Common Soldering Problems

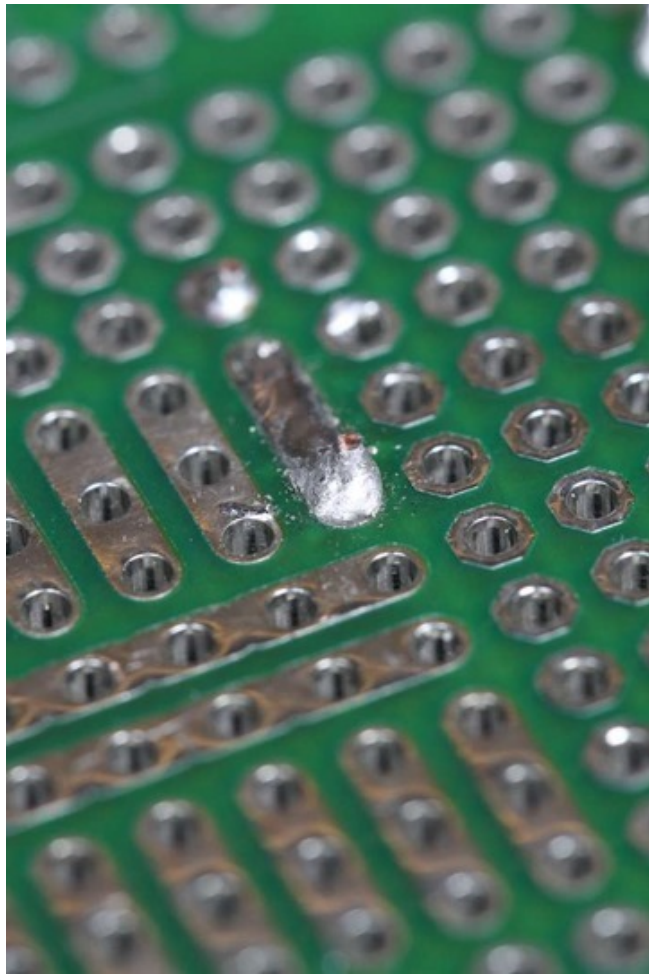


The Ideal Solder Joint

The ideal solder joint for through-hole components should resemble the diagram below.



The photos that follow show some common soldering problems, with suggestions for repair and prevention:



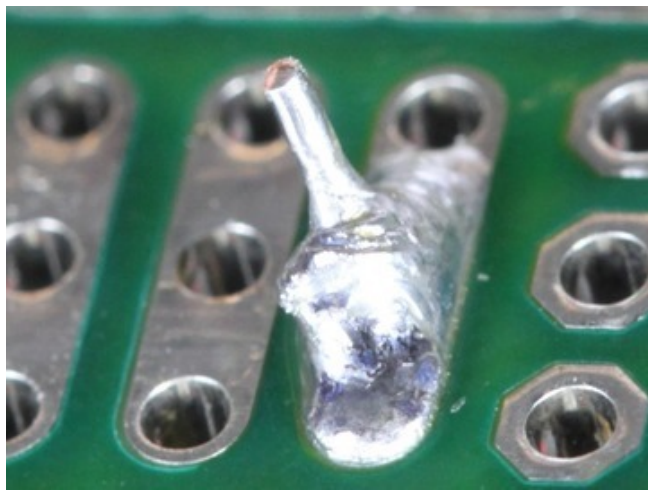
Disturbed Joint

A Disturbed joint is one that has been subjected to movement as the solder was solidifying. The surface of the joint may appear frosted, crystalline or rough.

Often called a 'Cold Joint'. They can look similar to a true cold joint, but the cause is different.

Repair: This joint can be repaired by reheating and allowing it to cool undisturbed.

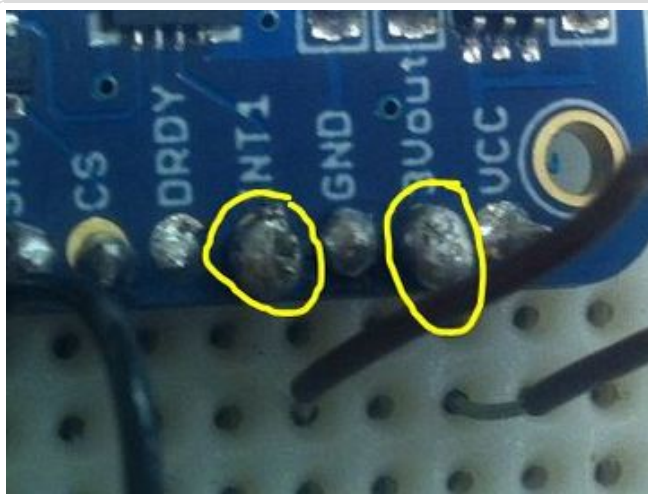
Prevention: Proper preparation, including immobilizing the joint and stabilizing the work in a vise can prevent disturbed joints.



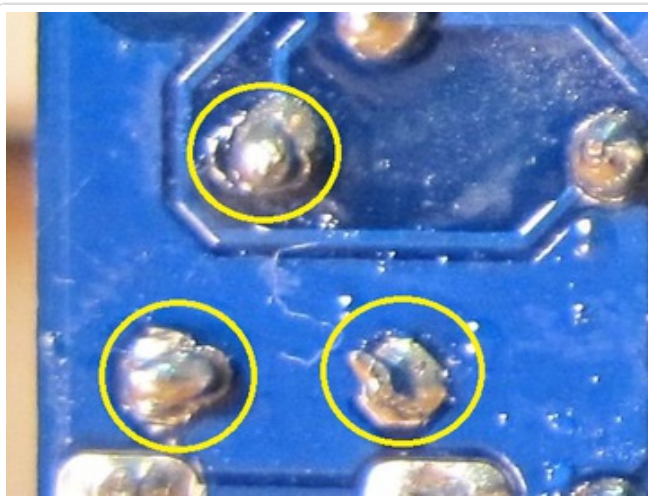
Cold Joint

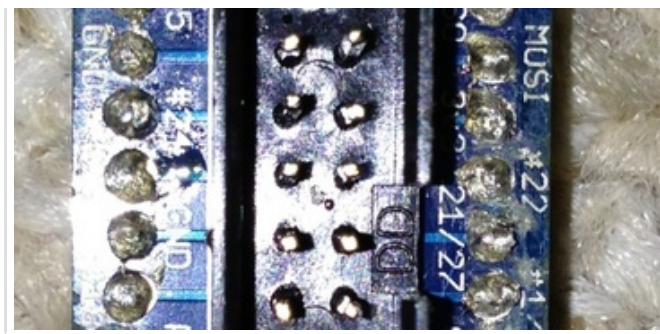
A 'Cold Joint' is one where the solder did not melt completely. It is often characterized by a rough or lumpy surface. Cold joints are unreliable. The solder bond will be poor and the cracks may develop in the joint over time.

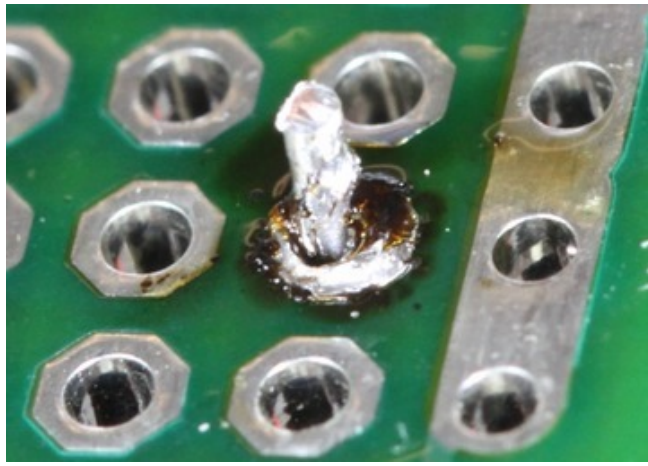
Repair: Cold joints can usually be repaired by simply re-heating the joint with a hot iron until the solder flows. Many cold joints (such as the one pictured) also suffer from too much solder. The excess solder can usually be drawn-off with the tip of the iron.



Prevention: A properly pre-heated soldering iron with sufficient power will help prevent cold joints.





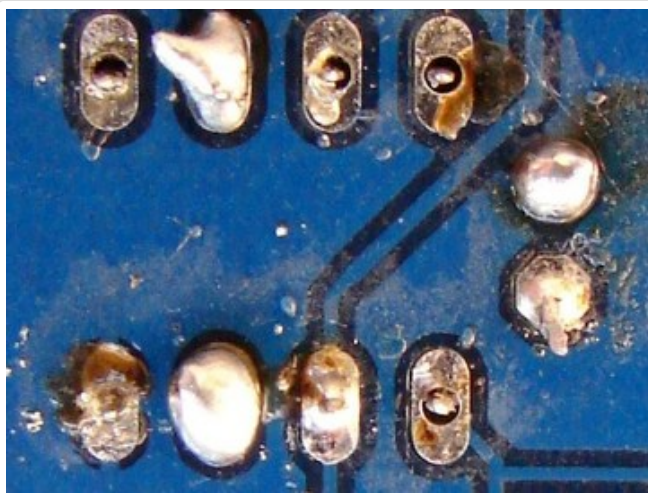


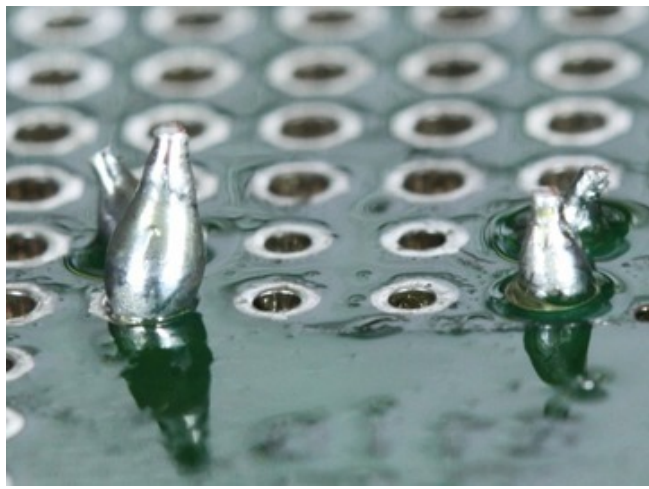
Overheated Joint

At the other extreme, we have the overheated joint. The solder has not yet flowed well and the residue of burnt flux will make fixing this joint difficult.

Repair: An overheated joint can usually be repaired after cleaning. Careful scraping with the tip of a knife, or little isopropyl alcohol & a toothbrush will remove the burnt flux.

Prevention: A clean, hot soldering iron, proper preparation and cleaning of the joint will help prevent overheated joints.



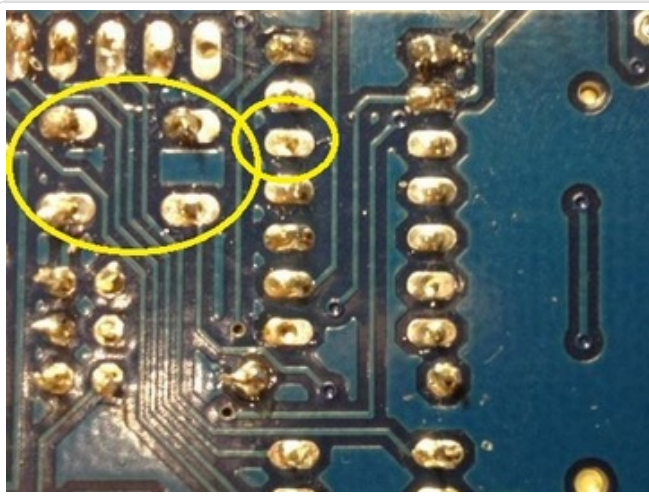
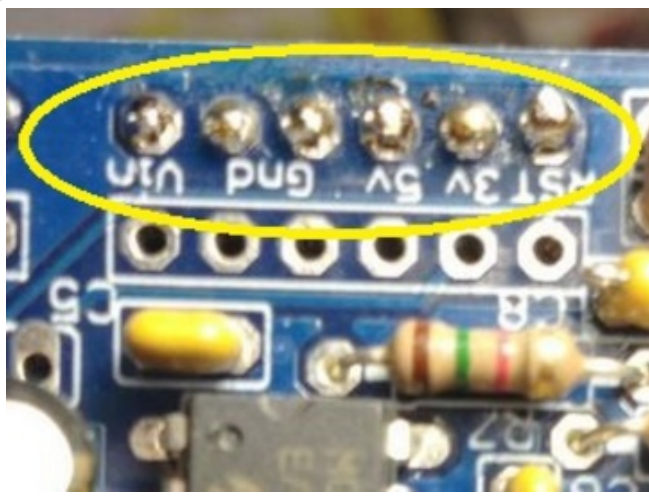


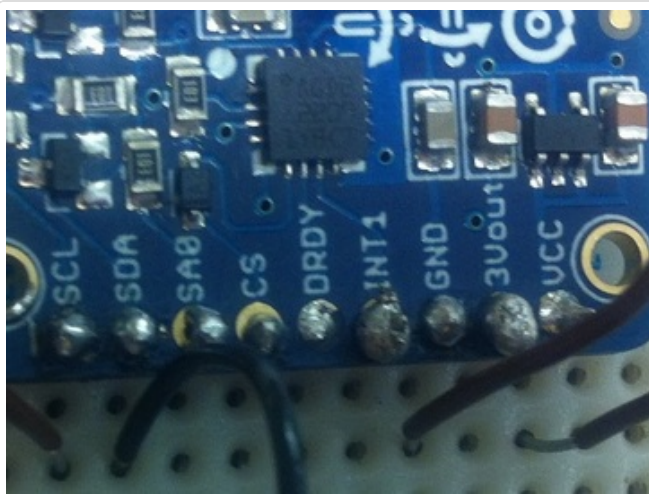
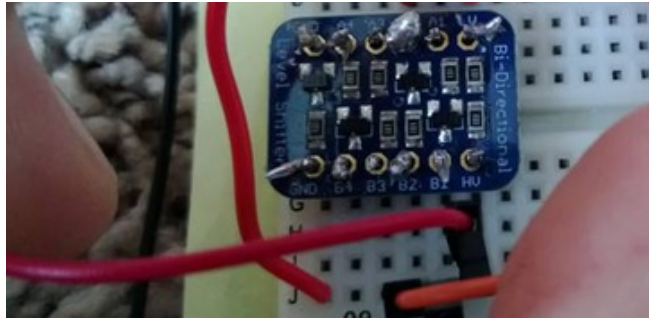
Insufficient Wetting (Pad)

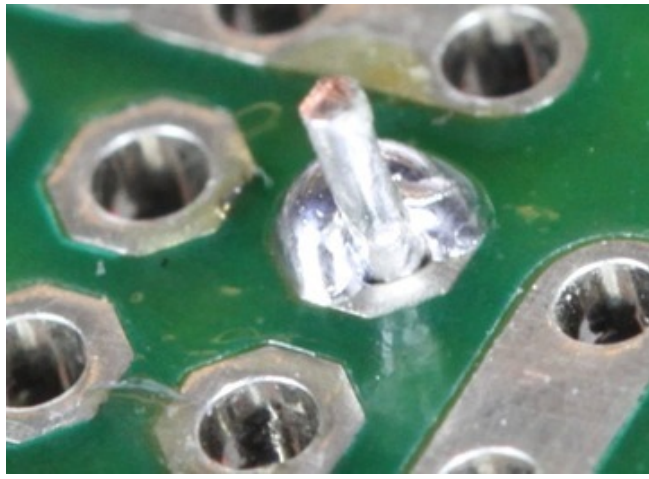
These two joints both show signs of insufficient wetting of the solder pad. The solder has wetted the leads nicely, but it has not formed a good bond with the pad. This can be caused by a dirty circuit board, or by failing to apply heat to the pad as well as the pin.

Repair: This condition can usually be repaired by placing the tip of the hot iron at the base of the joint until the solder flows to cover the pad.

Prevention: Cleaning the board and even heating of both the pad and the pin will prevent this problem.





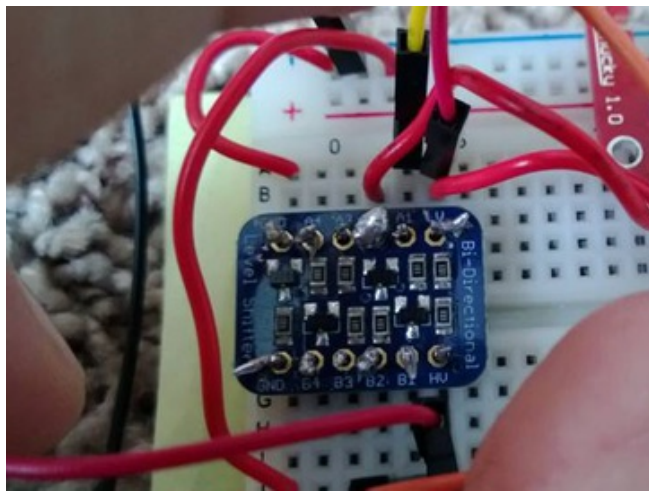


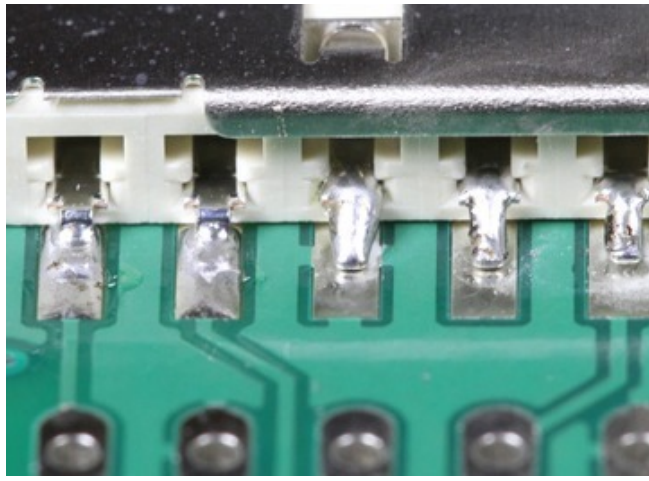
Insufficient Wetting (Pin)

This solder in this joint has not wetted the pin at all and has only partially wetted the pad. In this case, heat was not applied to the pin and the solder was not given adequate time to flow.

Repair: This joint can be repaired by re-heating and applying more solder. Be sure that the tip of the hot iron is touching both the pin and the pad.

Prevention: Even heating of both the pin and the pad will prevent this problem.



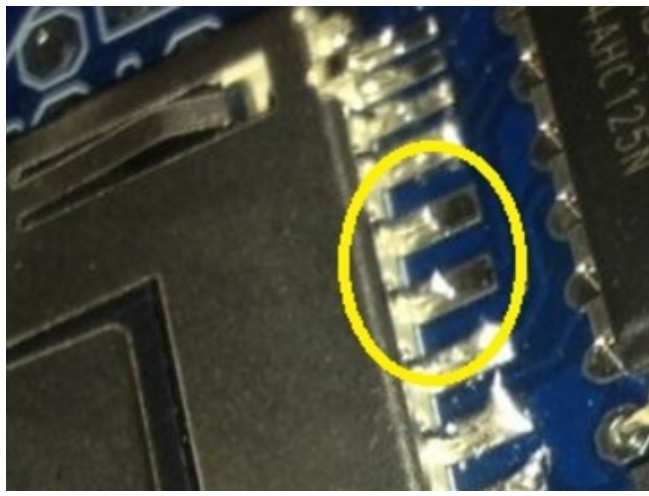


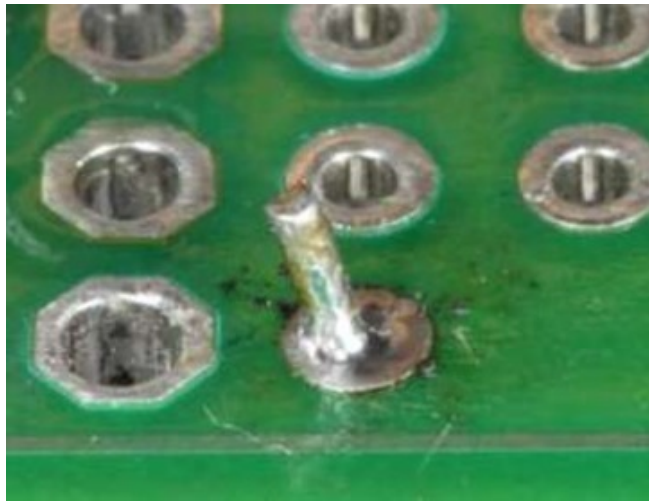
Insufficient Wetting (Surface Mount)

Here we have three pins of a surface mount component where the solder has not flowed onto the solder pad. This is caused by heating the pin instead of the pad.

Repair: This is easily repaired by heating the solder pad with the tip of the iron, then applying solder until it flows and melts together with the solder already on the pin.

Prevention: Heat the pad first.

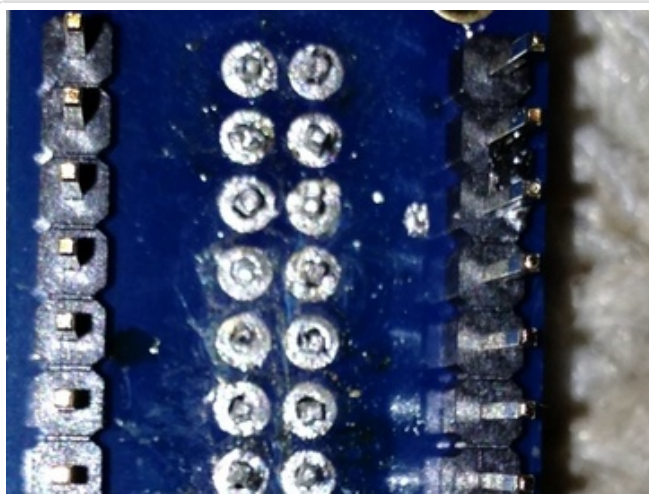


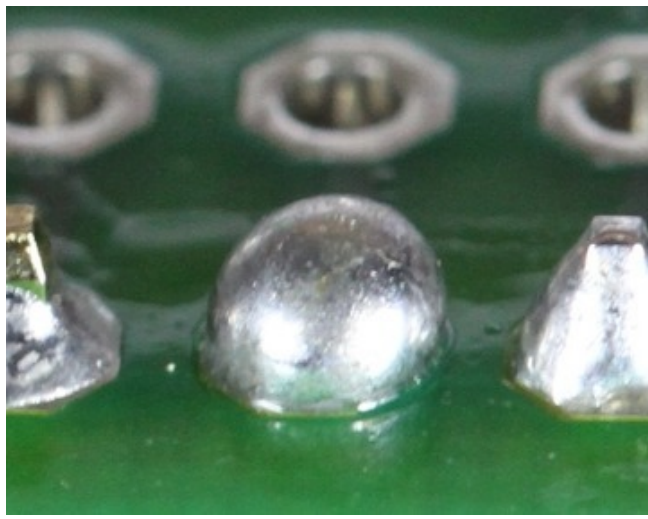


Solder Starved

A solder starved joint simply does not have enough solder. It may make good electrical contact, but it is hard to verify by inspection. In any case, it is not a strong joint and may develop stress cracks and fail over time.

Repair: Re-heat the joint and add more solder to make a good strong joint.



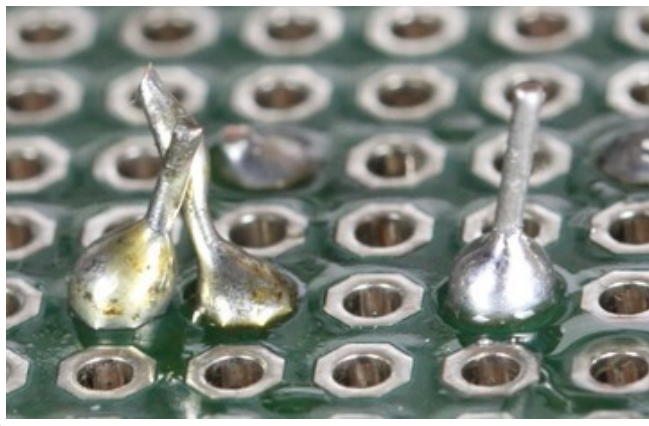


Too Much Solder

This might be a perfectly good joint, but we can't tell for sure. It is entirely possible that this blob of solder wets neither the pin nor the pad and is not a reliable electrical connection. The best evidence of proper wetting (and good electrical contact) is a nice concave surface as on the joint on the far left.

Repair: It is usually possible to draw off some of the excess solder with the tip of a hot iron. In extreme cases, a solder-sucker or some solder wick can be helpful as well.

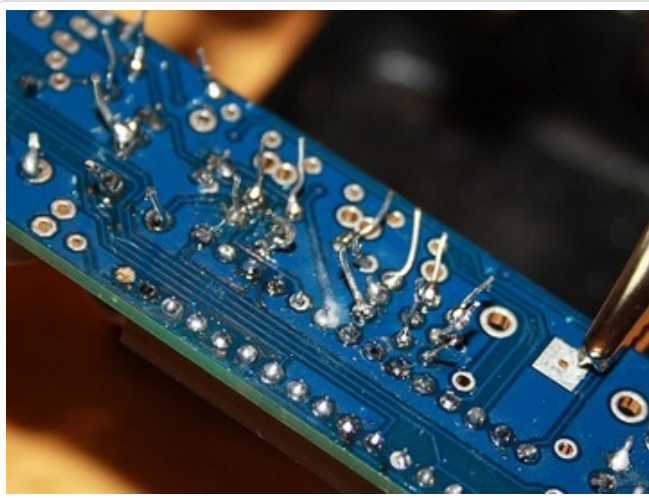
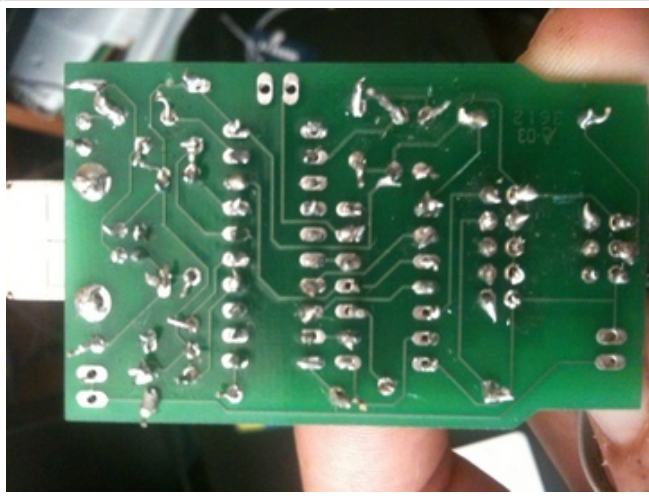


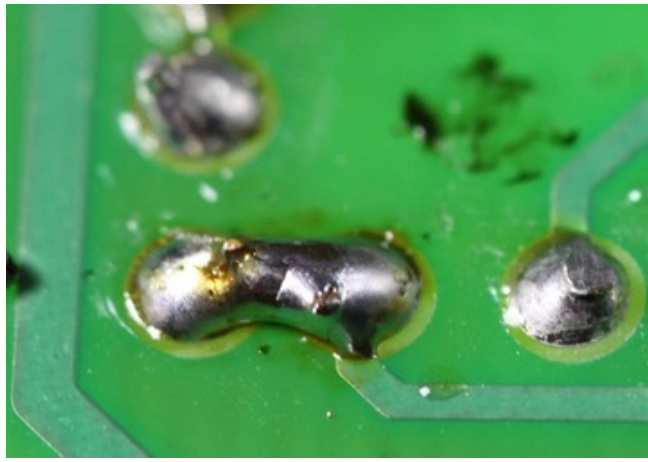


Untrimmed Leads

Leads that are too long are potential short circuits. The two joints on the left are an obvious danger of touching. But the one on the right is long enough to be dangerous as well. It would not take much force to bend that lead over to touch an adjacent trace.

Repair: Trim all leads just at the top of the solder joint.



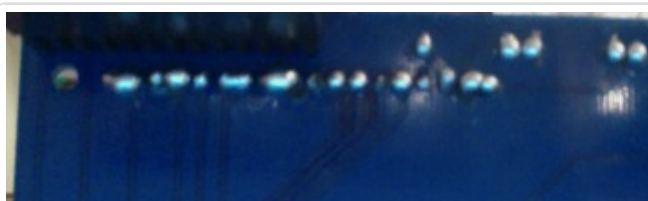
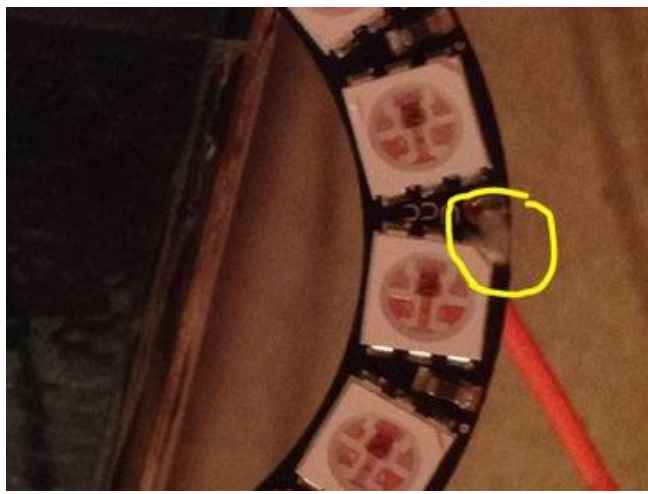


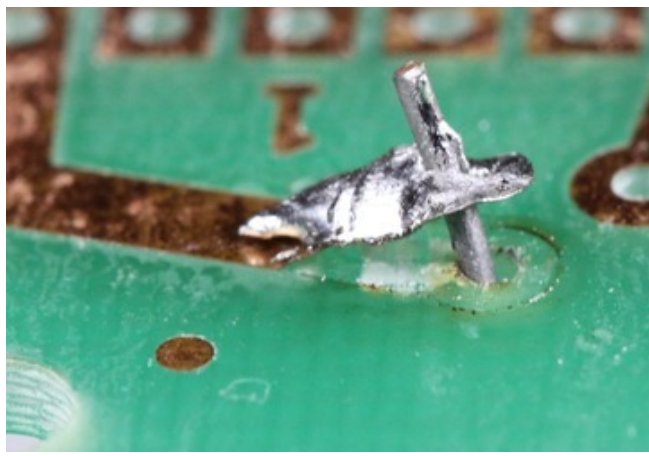
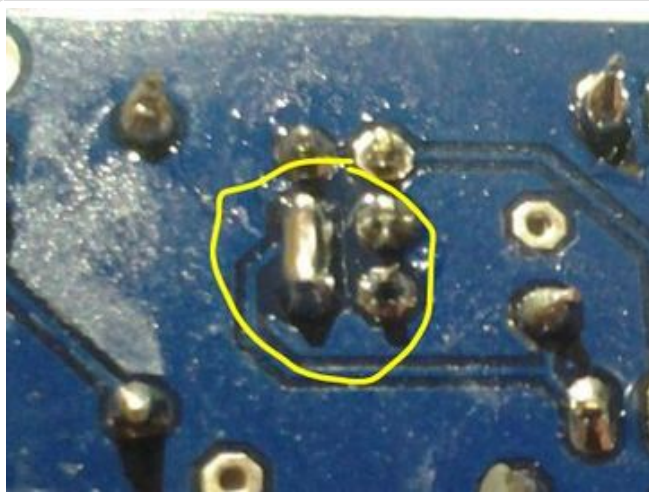
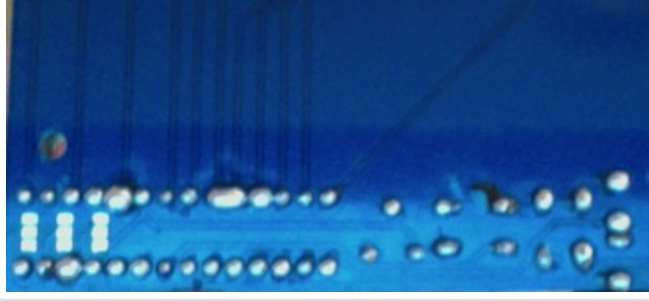
Solder Bridge

The left two solder joints have melted together, forming an unintended connection between the two.

Repair: Sometimes the excess solder can be drawn off by dragging the tip of a hot iron between the two solder joints. If there is too much solder, a solder sucker or solder wick can help get rid of the excess.

Prevention: Solder bridges most often happen between joints with too much solder to begin with. Use only enough solder to make a good joint.





Lifted Pad

This photo shows a solder pad that has become detached from the surface of the circuit board. This most often occurs when trying to de-solder components from the board. But it can result simply from overworking the joint to the point where the adhesive bond between copper and the board is destroyed.

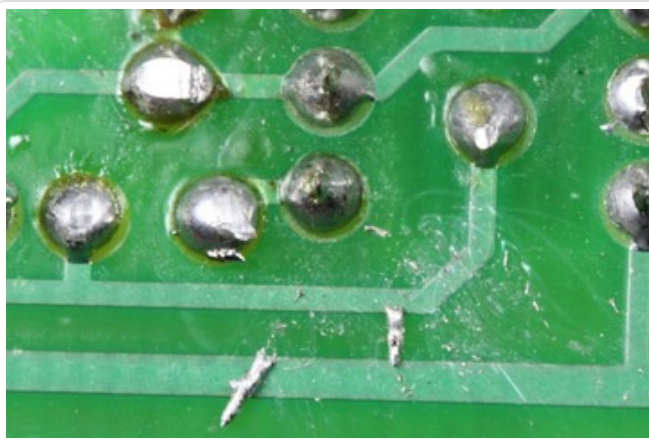
Lifted pads are especially common on boards with thin copper layers and/or no through-plating on the holes.



Repairing a Lifted Pad

It may not be pretty, but a lifted pad can usually be repaired. The simplest repair is to fold the lead over to a still-attached copper trace and solder it as shown to the left. If your board has a solder-mask, you will need to carefully scrape off enough to expose the bare copper.

Other alternatives are to follow the trace to the next via and run a jumper to there. Or, in the worst case, follow the trace to the nearest component and solder your jumper to the leg of that. Not exactly pretty, but functional.

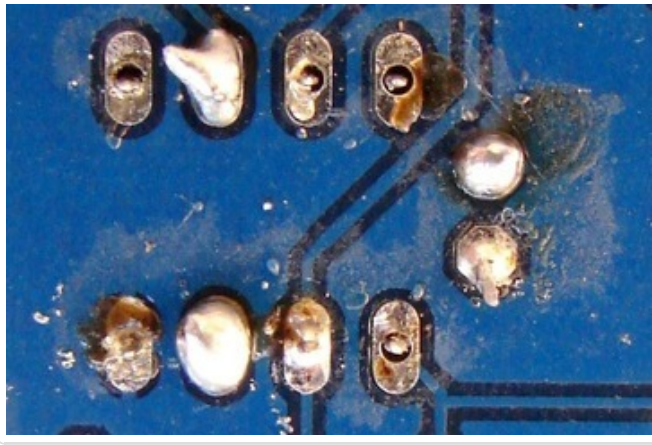


Stray Solder Spatters

These bits of solder are held to the board only by sticky flux residue. If they work loose, they can easily cause a short circuit on the board.

Repair: These are easy to remove with the tip of a knife or tweezers.





All of the Above!

Don't panic. Take your time. Most joints can be repaired with patience. If the solder refuses to flow the way you want it to:

1. Stop and let the joint cool.
2. Clean and tin your iron.
3. Clean off any burnt flux from the joint.
4. Let the iron come back up to temperature.
5. Then reheat the joint and try again.

HAND SOLDERING TUTORIAL FOR FINE PITCH QFP DEVICES

Scope

This document is intended to help designers create their initial prototype systems using Silicon Lab's TQFP and LQFP devices where surface mount assembly equipment is not readily available. This application note assumes that the reader has at least basic hand soldering skills for through-hole soldering. The example presented will be the removal, cleanup and replacement of a TQFP with 48 leads and 0.5 mm lead pitch.

Safety

Work should be done in a well-ventilated area. Prolonged exposure to solder fumes and solvents can be hazardous. There should be no presence of sparks or flames when solvents are in use.

Materials

The right materials are key to a good solder job. The list below are the recommendations from Silicon Labs. Other materials may work, so the user should feel free to substitute and experiment. The use of organic solder is highly recommended.

Required

1. Wire wrap wire (30 gauge) *
2. Wire strippers for wire wrap wire *
3. Soldering station - variable temperature, ESD-safe. Should support temperatures 800°F (425°C). This example uses a Weller model EC1201A. The soldering wand should have a fine tip no more than 1 mm wide.
4. Solder - 10/18 organic core; 0.2" (0.5 mm) diameter

5. Solder flux - liquid type in dispenser
6. Solder wick - size C 0.075" (1.9 mm)
7. Magnifier - 4X minimum. An inexpensive headset OptiVISOR by Donegan Optical Co. is used for this example.
8. ESD mat or tabletop and ESD wrist strap - both grounded
9. Tweezers with pointed (not flat) tips
10. Isopropyl Alcohol
11. Small stiff bristle brush for cleaning (nylon or other non-metallic material). Cut off hair to approximately 0.25" (6 mm)

* Required for device removal only.

Optional

1. Board vise to hold printed circuit board
2. Dental pick (90 degree bend)
3. Compressed dry air or nitrogen to dry boards

4. Optical inspection stereo microscope 30-40X

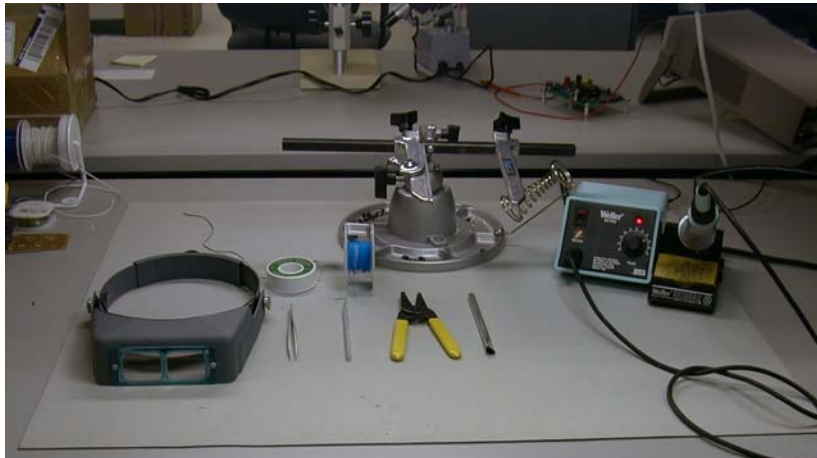


Figure 1. Some of the materials to get started...



Figure 2. clock-wise from left: 4X magnifying headset, solder wick, wire wrap wire, stiff cleaning brush, wire strippers, and pointed tweezers



Figure 3. Solder wick and wire wrap wire



Figure 3. Isopropyl Alcohol



**Figure 4. ESD safe soldering station with fine tip wand.
This one is Weller model EC1201A**

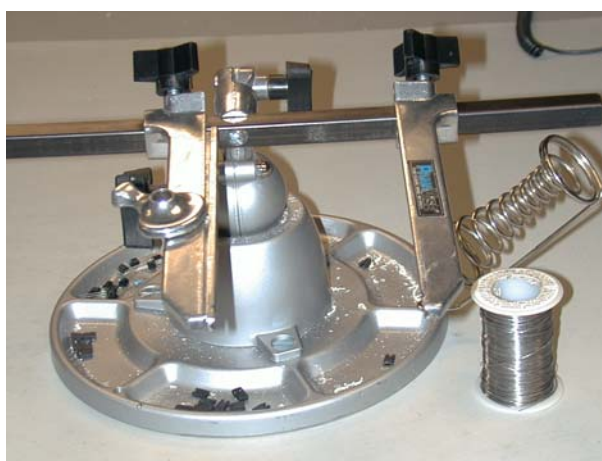


Figure 5. Optional equipment includes a PCB vise and an inspection microscope 7-40X

Procedure

The following procedures cover the replacement of a TQFP 48 pin device with 0.5 mm lead pitch. The lead shape is the standard gullwing associated with JEDEC standard QFPs. This procedure section is divided into three parts:

A. Part Removal

B. Board Cleanup

C. Soldering a new device.

If you are soldering parts to a new printed circuit board, skip part A and refer to the new board cleanup section in part B.

A. Part Removal

Preparation:

- Board with IC to be removed is mounted in a holder or vise. A PCB holder/vise is optional but it is required that the PCB is held steady for the part removal.
- The soldering station is warmed up to 800°F (422°C) and the solder tip is clean.
- ESD precautions have been taken.

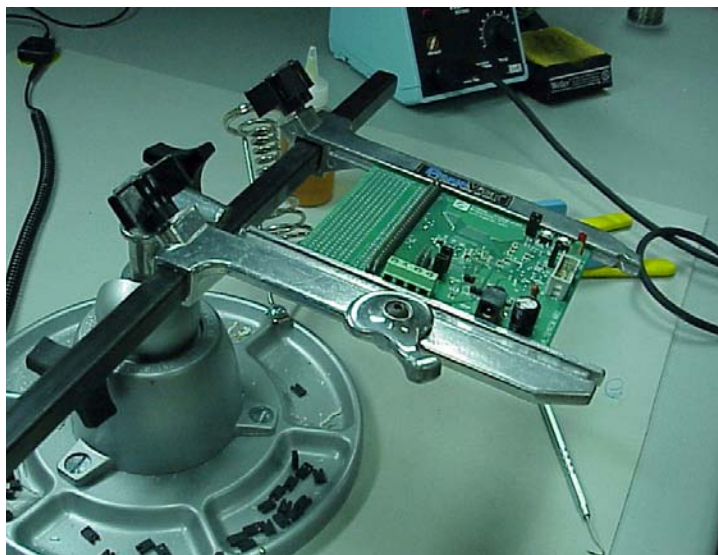


Figure 6. Ready to get started

Begin by wetting all the leads with flux to enhance the initial solder wicking cleanup. Wick up solder as much as possible from the QFP leads. Be careful not to scorch the PCB board with prolonged solder heat.

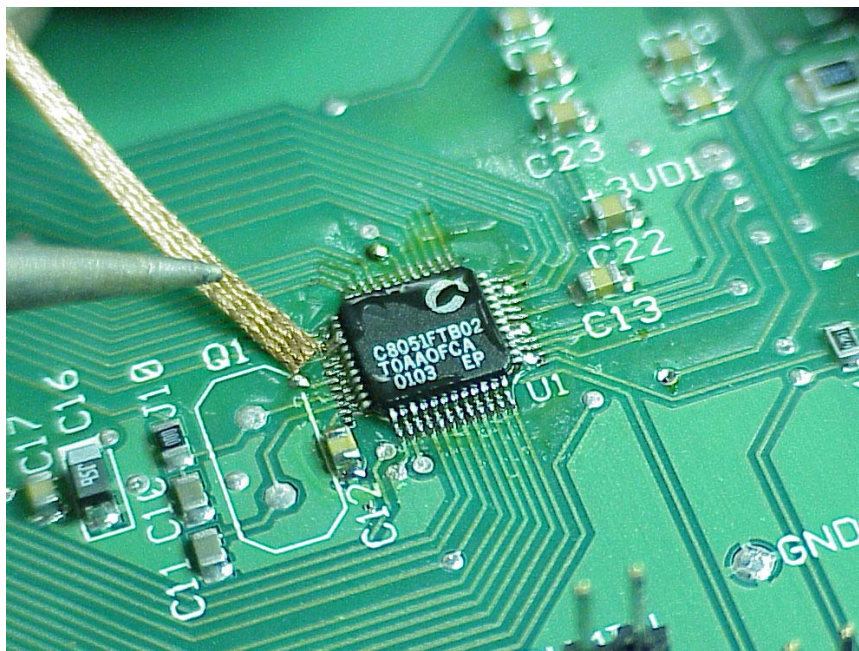


Figure 7. Apply flux; wick excess solder from pins

Next, strip off approximately 3 inches of insulation from a piece of the 30 gauge wire wrap wire. Cut the wire at a comfortable 12 inch length or so.

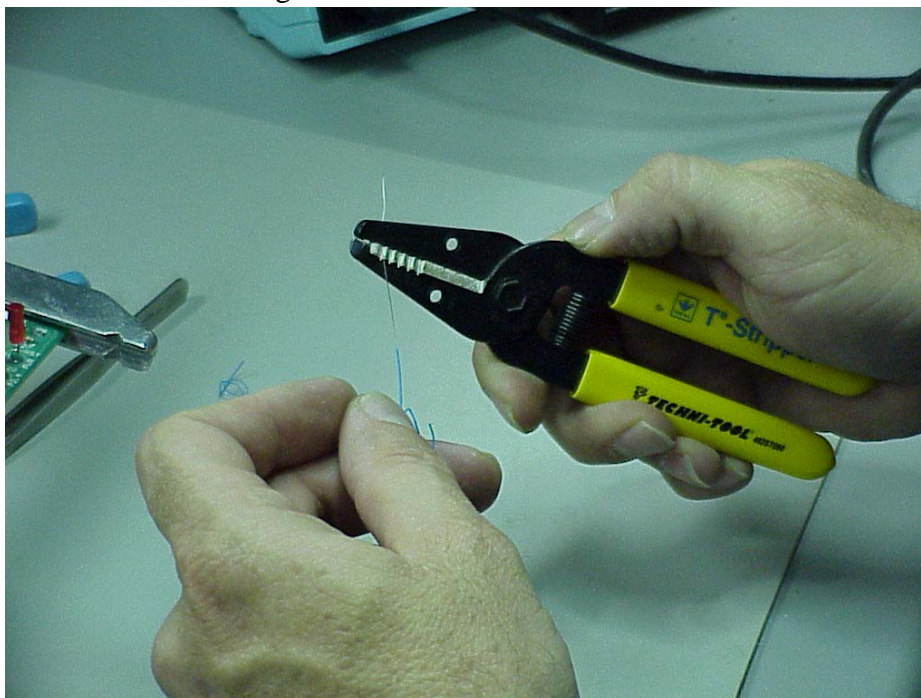


Figure 8. Wire stripping

Feed the wire behind and under the leads on one side of the IC as shown in Figure 9.

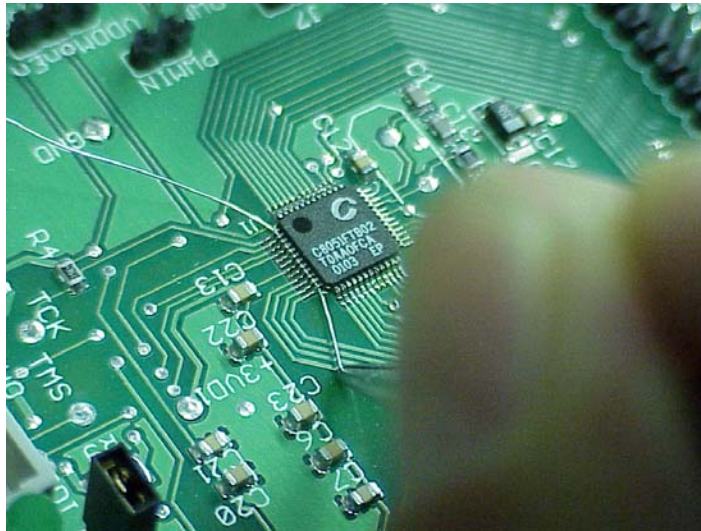


Figure 9. Feeding wire under QFP leads

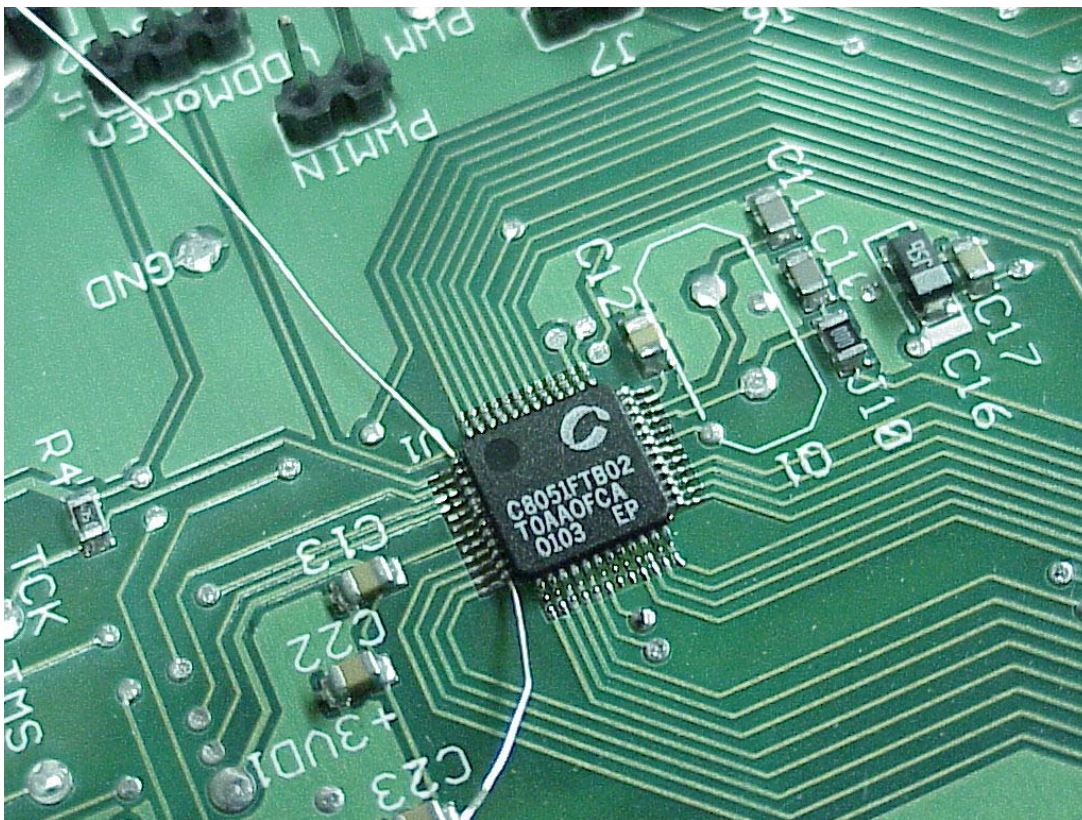


Figure 9. Wire with one side anchored to nearby component

Solder tack (anchor) one end of the 3 inch wire to a nearby via or component on the PCB. The anchor point should be in a location similar to that should in Figure 10.

Dispense a small amount of liquid flux across the leads.

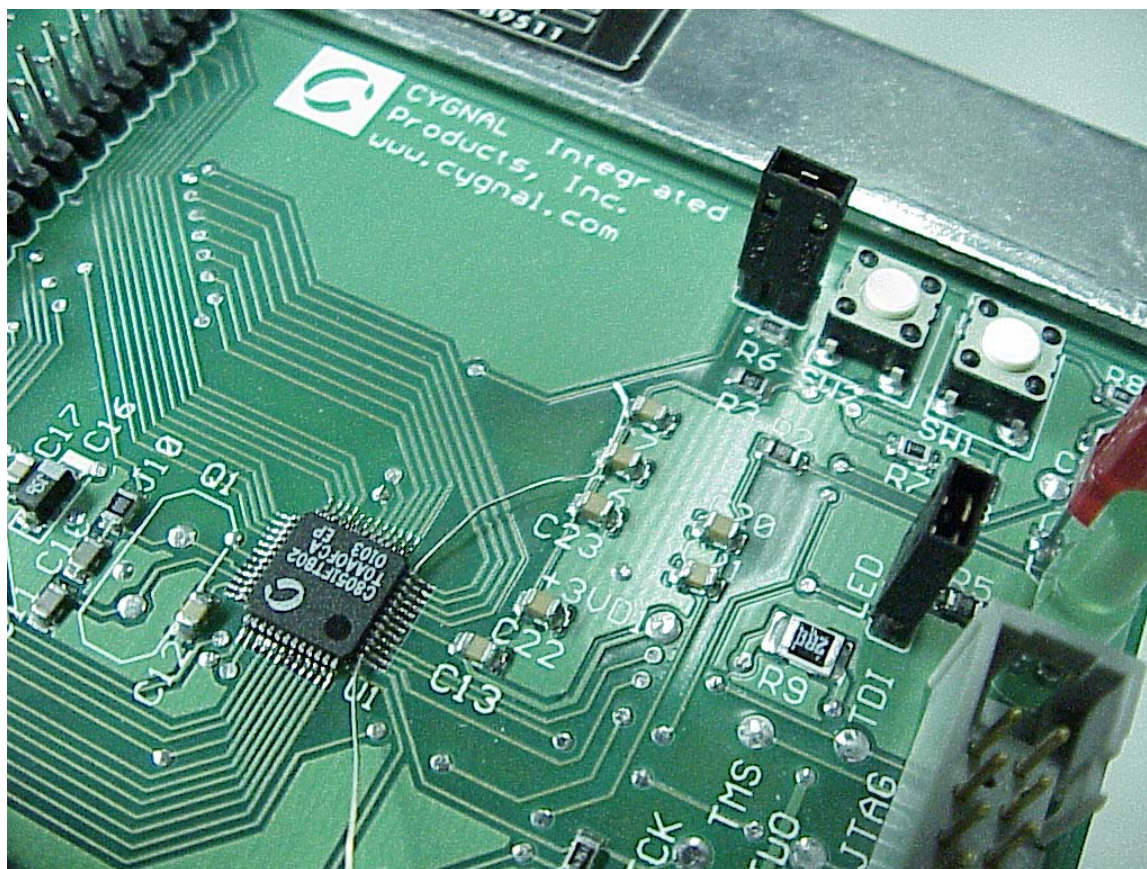


Figure 10. Bus wire is anchored on C6

Hold the loose (non-anchored) end of the wire with tweezers in close proximity to the device as shown in Figure 11.

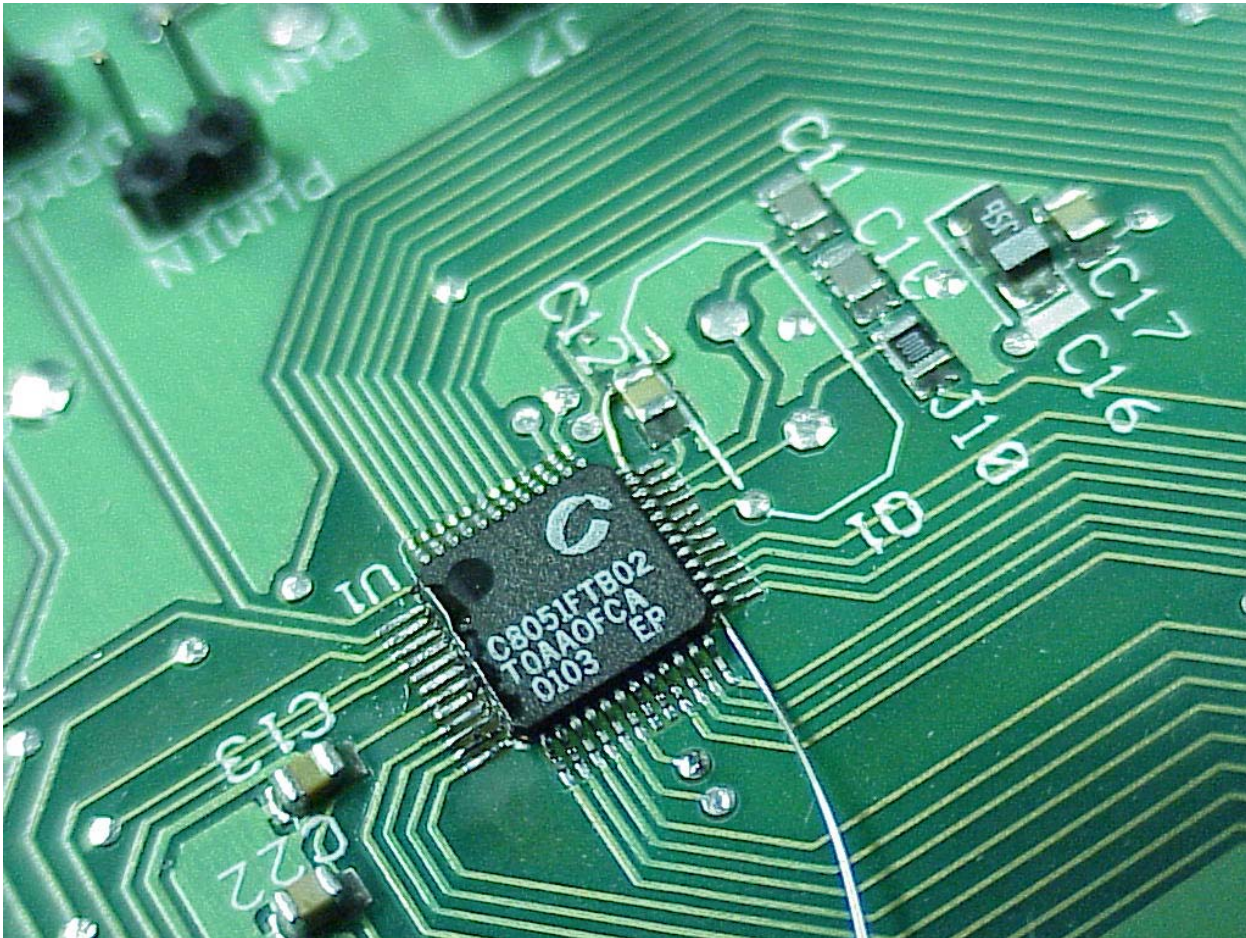


Figure 11. Side 2 anchored and ready for solder heat

You will now need to simultaneously apply solder heat and pull the wire away from the QFP, pulling at a slight upward angle from the board surface. Apply solder heat beginning at the lead closest to your tweezers. As the solder melts, gently pull the wire away from the QFP while continuing to move the solder heat from pin to pin to the right. You should not pull very hard. Pull as the solder melts. Do not leave the solder heat on any lead for more than necessary. The first lead will take the longest to heat, and after the wire gets hot, solder on the other leads will melt quickly. Excessive heat will damage the IC device and the PCB pad. The removal of 12 pins from a 48TQFP should take about 5 seconds total. Signs of excessive heat are:

- Melted plastic on the IC device
- PCB pads that lift off
- Brown scorch marks on the PCB

With one side of the QFP completed, repeat the same procedure on the other three sides of the QFP. Cut off the dirty part of the wire wrap wire or use a new piece for each side. Dispense flux again for each side.

Note that in the following pictures, the old IC device is not being saved. There is slightly more heat being applied here than necessary to speed up the process. This result is some melted plastic and missing gull-wing leads. These are visible in the pictures that follow. If you are trying to save the IC being removed, then you must be very careful to apply as little heat as possible during the removal process such that the QFP leads remain intact in the plastic QFP body. This will require some experimentation with solder heat settings and timing.

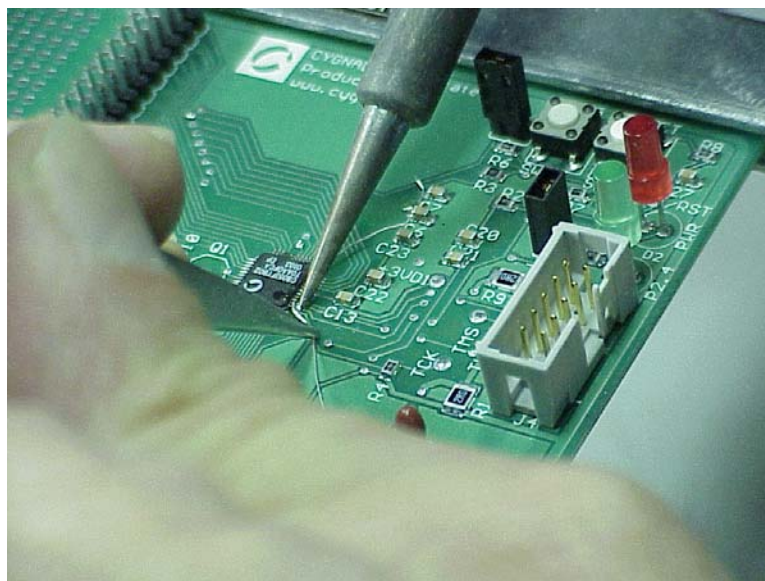


Figure 12. Hold tweezers close to device

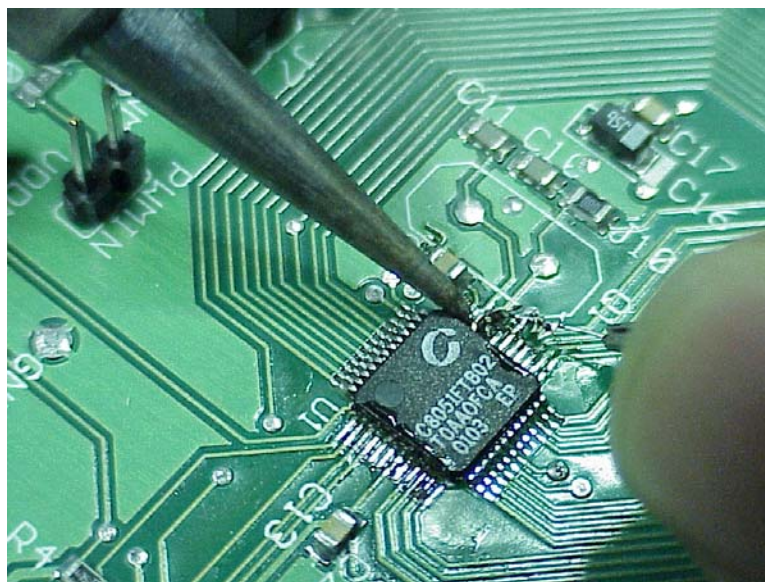


Figure 14. Side 2 almost complete

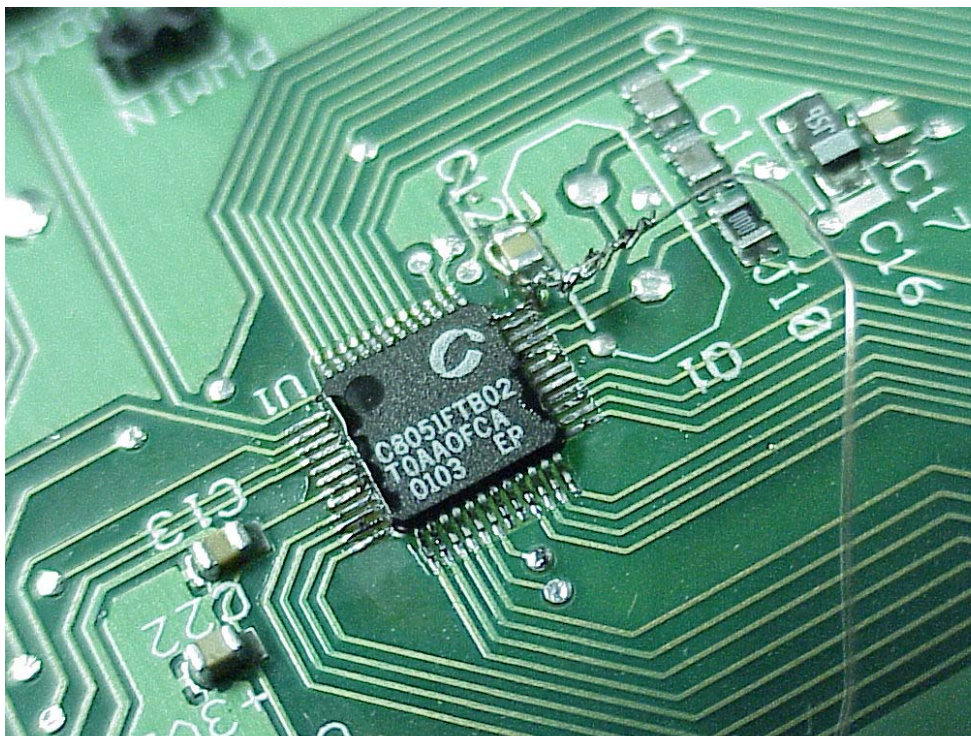


Figure 15. Side 2 is done

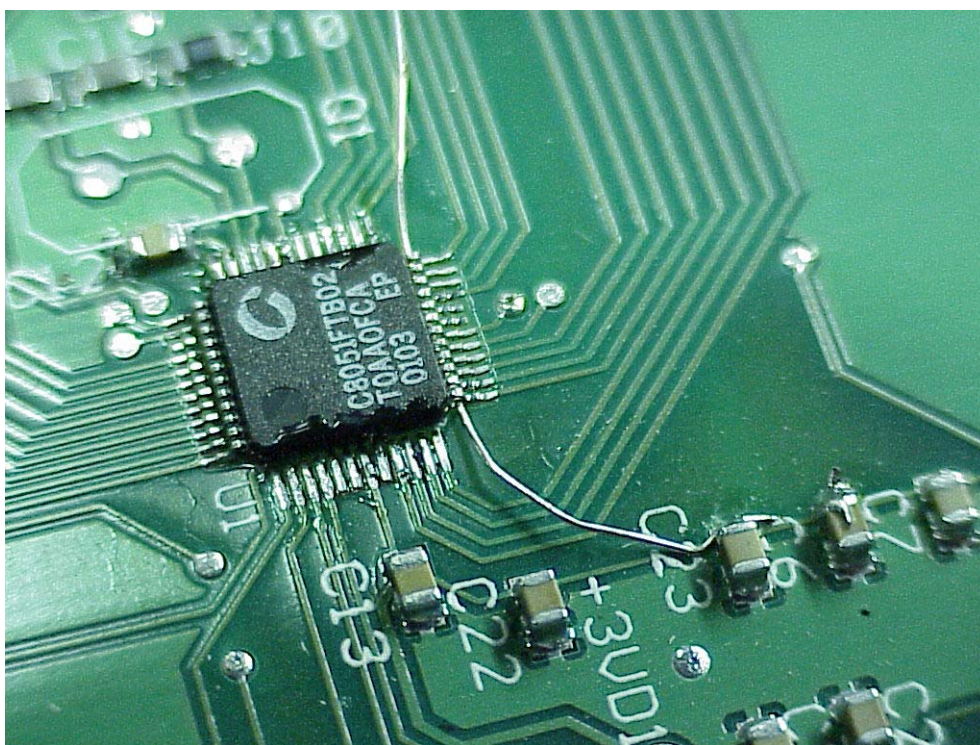


Figure 16. Side 3 anchored and ready

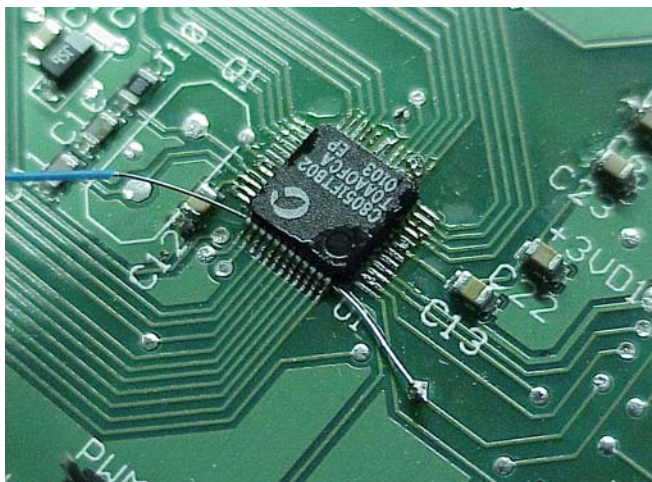


Figure 17. Side 4 anchored to a via

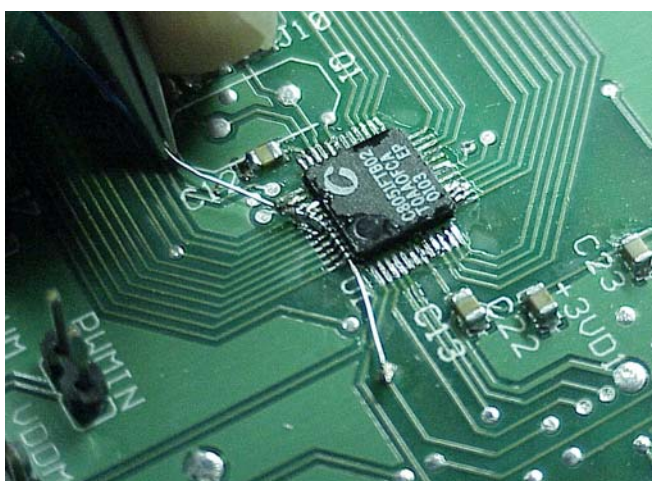


Figure 18. Side 4 removal started

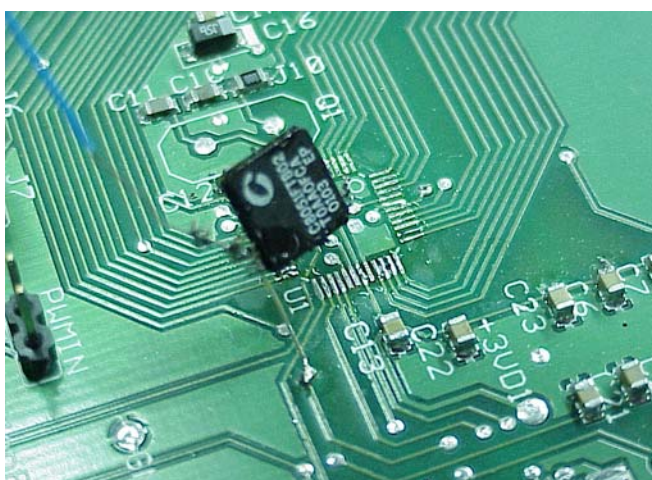


Figure 19. QFP removal a second before completion

B. Board Cleanup

New PCBs

For mounting a device to a new PCB, the amount of cleanup should be minimal. On a new PCB, there should be no solder on the pads. Brushing the pads with isopropyl alcohol (Figure 33) and drying the board should be enough preparation to begin the mounting procedure.

Reworked PCBs

The following section is the cleanup sequence that follows the QFP removal in the previous section. After removing the device, the solder pads will need cleanup. The idea is to clean the pads so that they are flat and free of solder and flux. Solder wick the pads until they are flat and dull. A clean pad appearance should be a dull silver color.

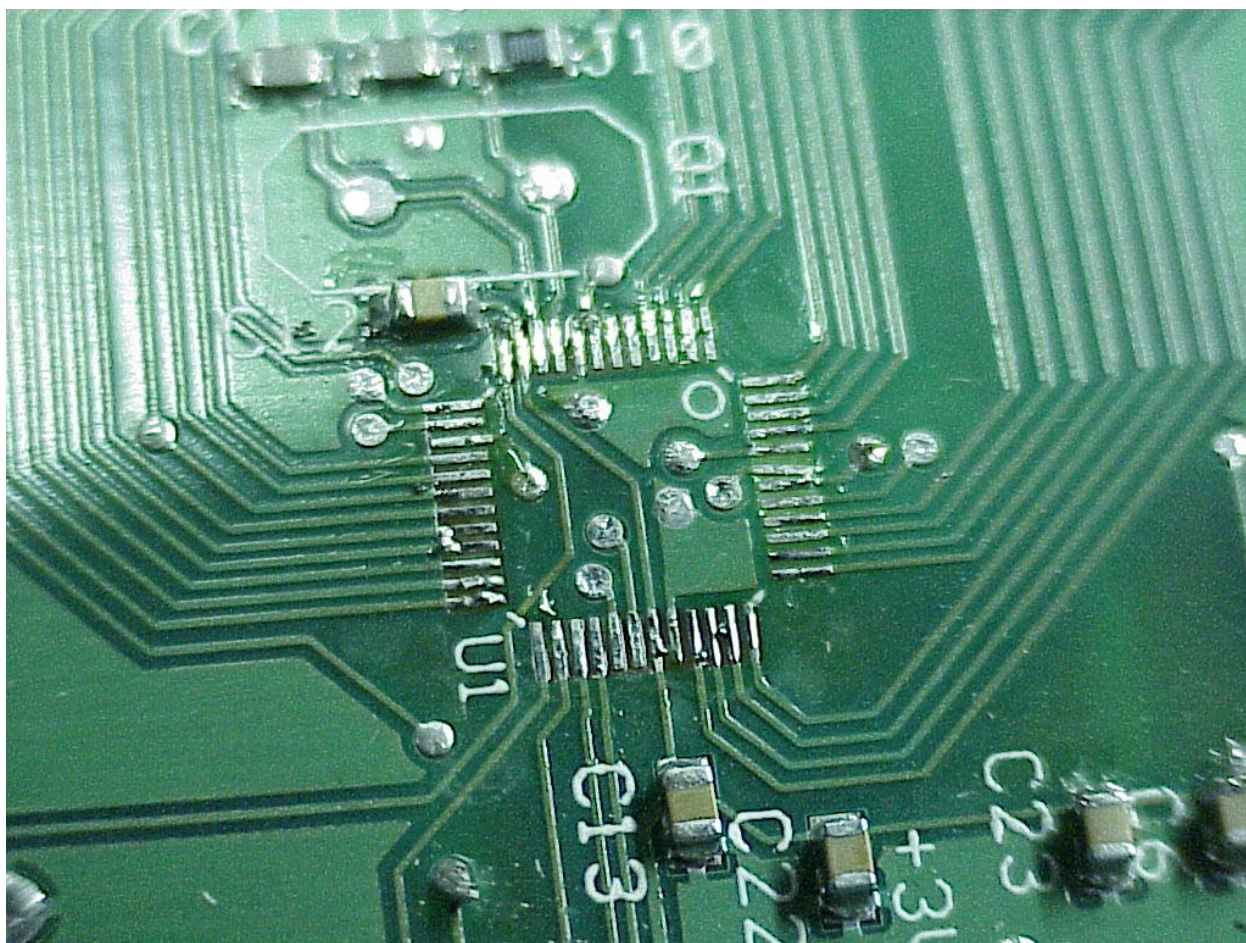


Figure 20. Pads after QFP removal procedure

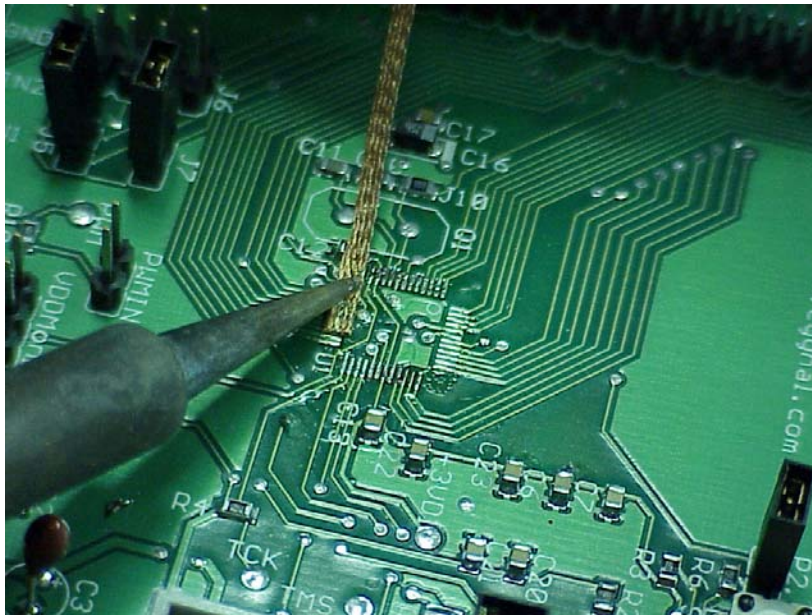


Figure 22. Repeat for all pads

If any pads become loose from the PCB, use a dental pick or other pointed object to re-align the pad (Figure 23 and Figure 24).

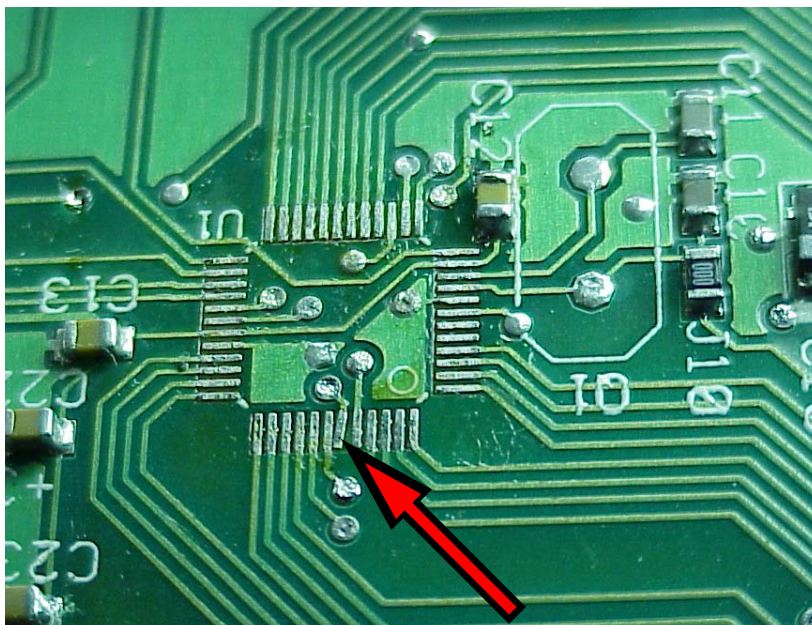


Figure 23. Clean pads but one pad is slightly crooked

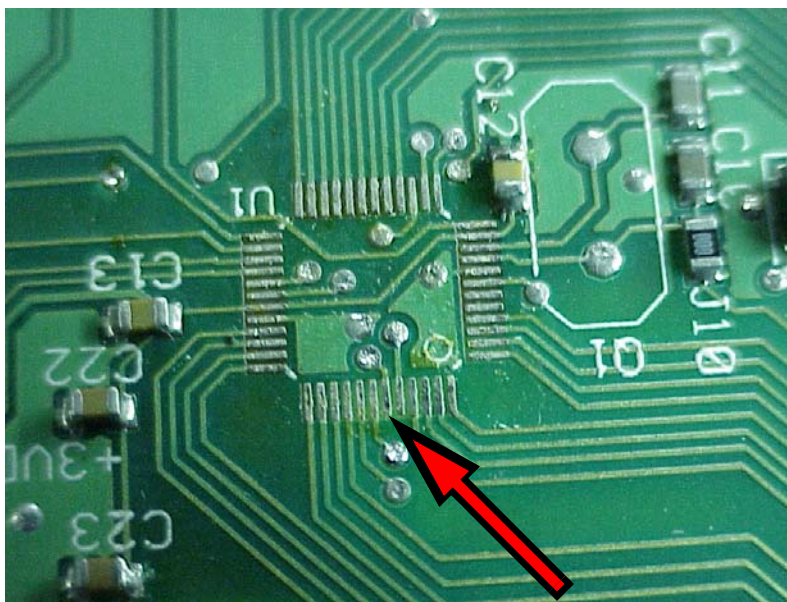


Figure 24. Pad straightened out

B. Soldering a new QFP

The pads on the PCB should be clean and free of any solder.

Carefully place the new QFP device on the PCB using tweezers or another safe method. Make sure the part is not dropped as the leads can be easily damaged.

Align the part over the pads using a small pick or similar tool to push the part. Get the alignment as accurate as you can. Also, make sure that the part is oriented correctly (pin 1 orientation).

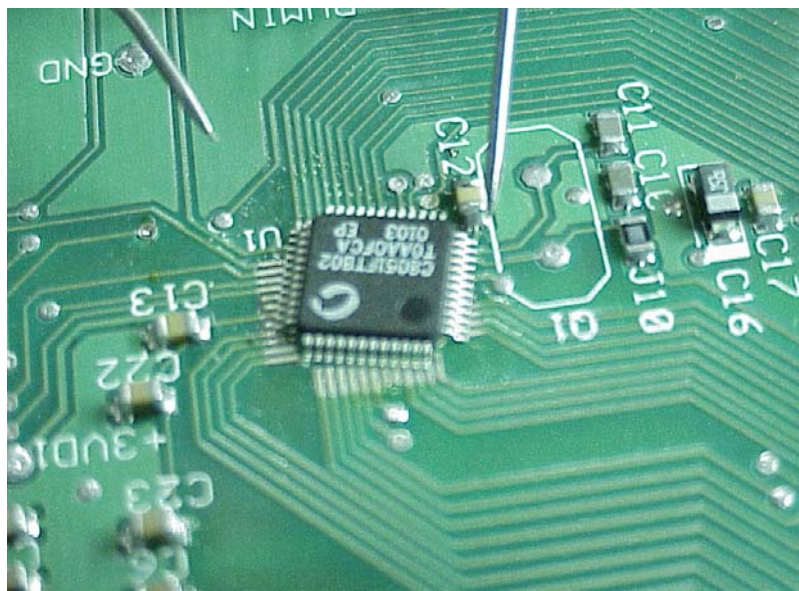


Figure 25. New QFP near pads, ready for alignment



Figure 26. QFP aligned

Adjust the soldering station temperature to 725°F (385°C). Put a small amount of solder on the tip of the solder iron. While holding down the aligned QFP with a pick or other pointed tool, add a small amount of solder flux to the corner leads in two opposite corners. While still holding the part down with the pick, solder down two opposite corner leads on the QFP. Do not worry about excess solder or shorts between adjacent leads at this time. The idea is to anchor down the aligned QFP with solder so it does not move.

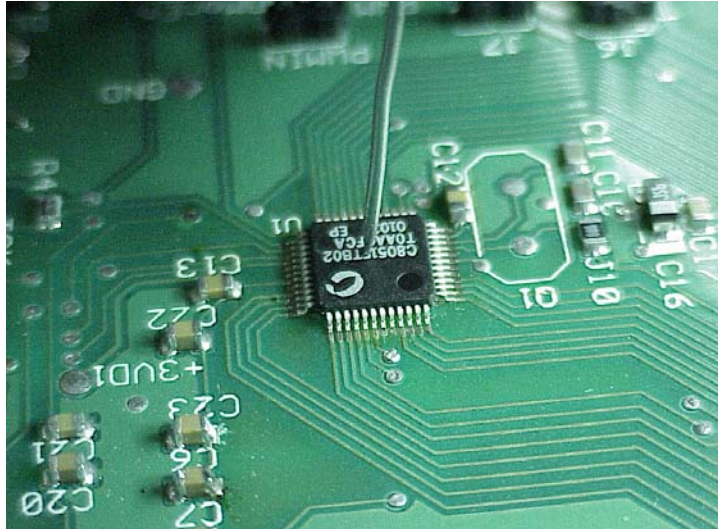


Figure 27. Aligned QFP ready for solder anchoring

Re-check the QFP alignment after soldering the corners. If necessary, make adjustments or remove and start over to get good QFP to PCB alignment.

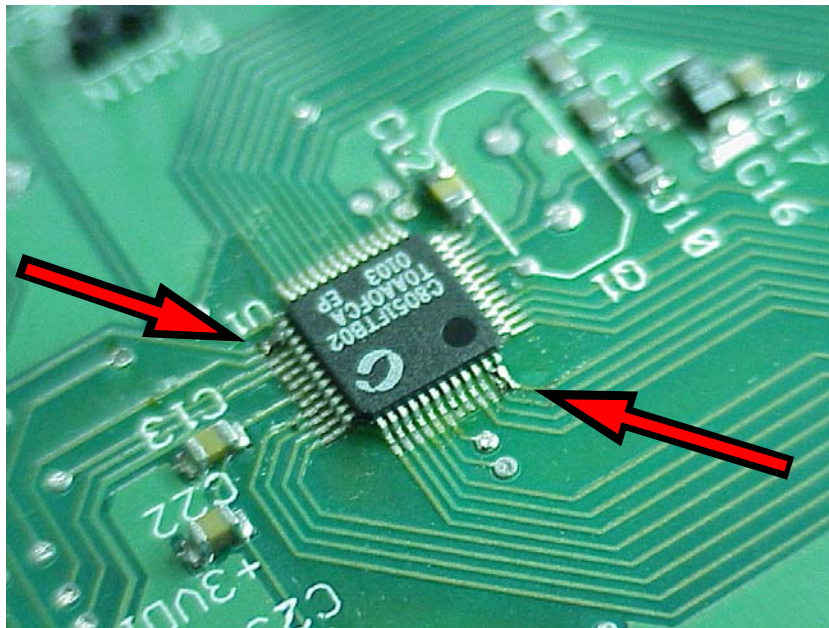


Figure 28. Aligned QFP with corners soldered down

Now you are ready to solder all the leads. Add solder to the tip of the soldering iron. Dispense flux over all the leads to keep them wet.

Touch the solder iron tip to the end of each QFP lead until the solder is seen running up the lead. Repeat for all the leads. Add small amounts of solder as needed to the soldering iron tip. Again, do not worry if you see some solder bridging as you will clean that up in the next step.

When soldering, keep the soldering iron tip parallel with the pins being soldered to prevent excessive solder shorts.

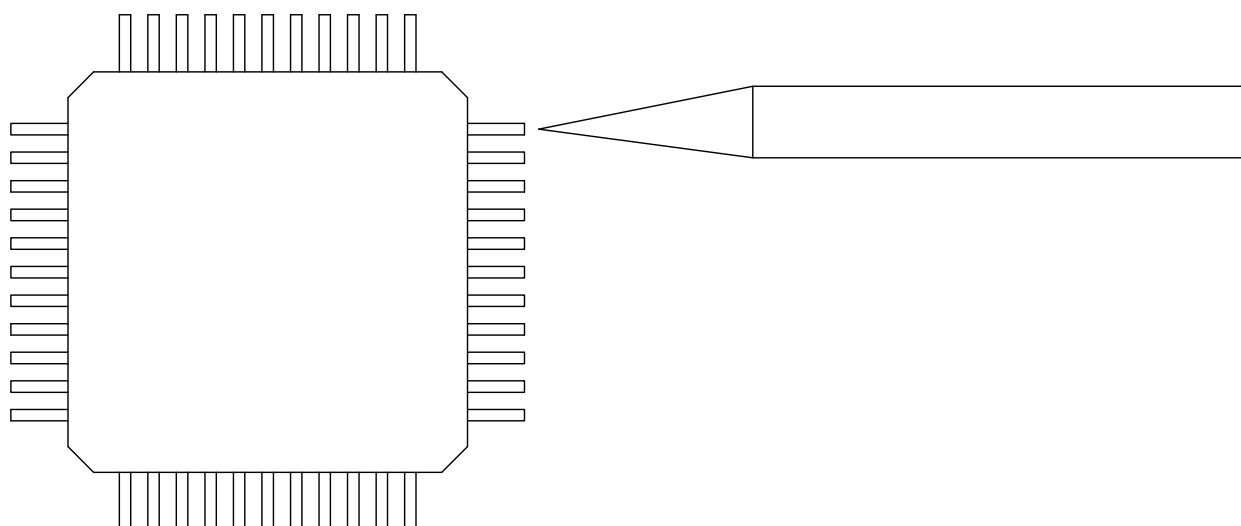


Figure 29. Keep iron tip parallel to pins being soldered

After soldering all the leads, wet all the leads with flux to enhance the solder wicking cleanup. Wick up solder where needed to eliminate any shorts/bridging.

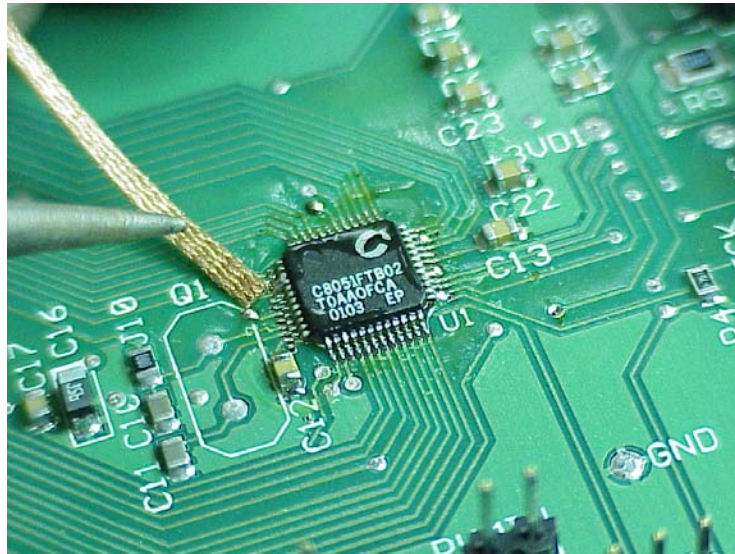


Figure 30. Wicking Solder #1

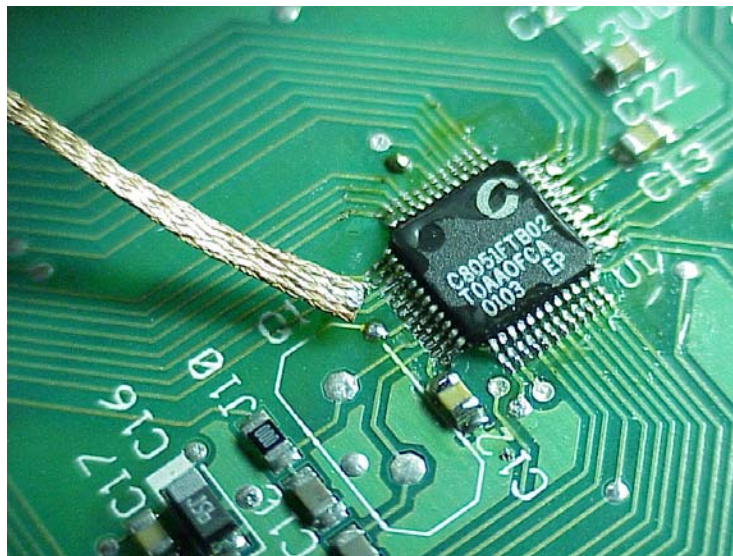


Figure 31. Wicking Solder #2

Hand inspect the board using 4X magnification (or higher) for shorts or marginal solder joints. Solder joints should have a smooth melt transition between each device pin and the PCB. Rework any pins as needed

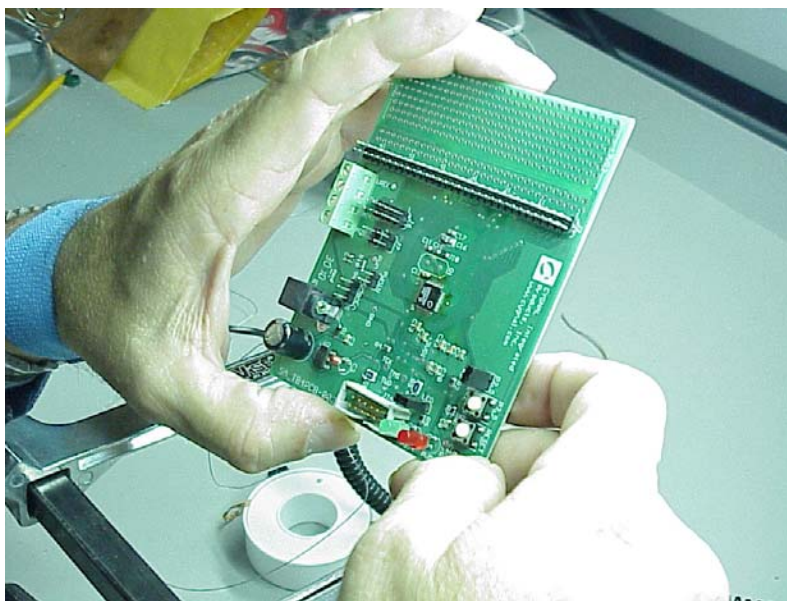
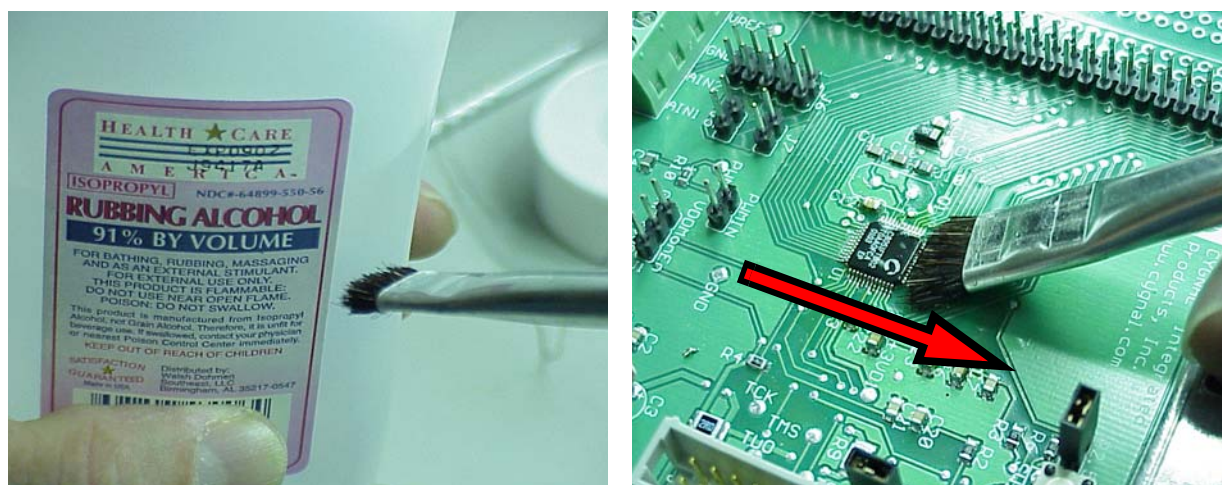


Figure 32. Visual Inspection

After the inspection passes, it is time to clean the flux off the board. Dip the stiff bristle brush into alcohol and wipe in the direction of the leads. Use moderate, but not excessive pressure. Use liberal amounts of alcohol and brush well between the QFP leads until the flux disappears.



**Figure 33. Isopropyl Alcohol and stiff brush used for cleanup.
Brush only in direction of leads**

Dry the board with compressed dry air or nitrogen. If this is not available, let the board dry for 30 minutes or more to let the alcohol evaporate under the QFP. The QFP leads should look bright and there should be no flux residue.

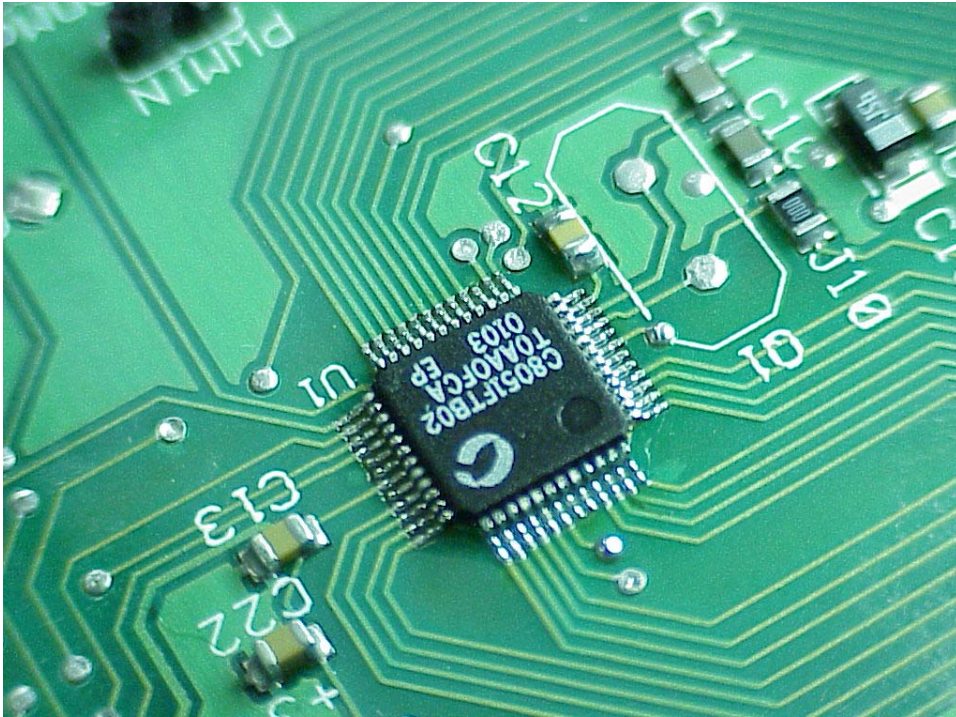


Figure 34. Clean and Pristine

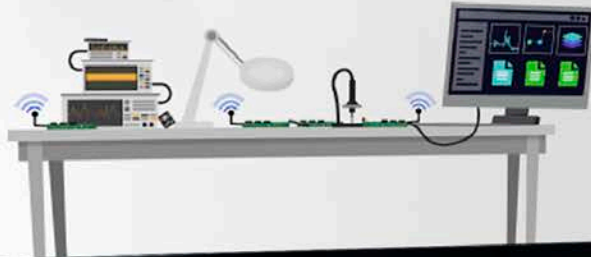
Re-inspect the board for workmanship. Rework any leads if needed.



**Figure 35. Stereo zoom inspection station (7X to 40X magnification)
helps to inspect solder joint workmanship**

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Soldering Guidelines

Solder0 R0.1

EE400/1
Design

Revision History

Rev.	Date	Contributor	
0.1	September 2005	L. Wyard-Scott	Updates to reflect changed Capstone Design Course format and new de/soldering equipment.
0.0	January 2004	V.J. Sieben, L. Wyard-Scott, E. Tiong	Creation.

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Chapter 1

Soldering Technique

This guide is intended to give an introduction to basic soldering technique. If the reader desires to pursue advanced soldering techniques, there are several books as well as technical institutions that offer detailed courses in the area of soldering.

1.1 Required Tools

Before discussing soldering techniques, one should must set up a “soldering work station”. The following is a list of tools for a typical soldering station. See Appendix [A](#) for pictures of the various parts listed below.

1. **Variable temperature soldering iron:** used for applying heat to joints during the soldering process.
2. **Damp sponge:** for cleaning soldering iron tip.
3. **Rosin-core solder:** to electrically and mechanically bond a component to the PCB.
4. **Wire cutters or side cutter:** for trimming component leads and stripping insulation from wires.
5. **Needle nose pliers:** for holding, placing and shaping components.
6. **Desoldering pump and/or desoldering braid:** for removing solder.
7. **Scotch tape and/or a “Third Hand”:** for securing components.

8. **Safety glasses:** for eye protection. These are mandatory in the lab.
9. **Magnifier:** to provide more detail during intricate work. A magnifying glass is convenient, but an illuminated magnifier is better.
10. **Light source:** to prevent eye-strain.
11. **Ventilation:** to extract and dispel fumes generated during the soldering process.
12. **Flux:** to clean components and PCB pads.
13. **Acid brush:** to assist in the removal of flux residue.

Prior to soldering it is a good idea to have all components organized as it will make populating the PCB more efficient. Make a BOM (bill of materials) for the PCB, and ensure before soldering that the components have been collected. The schematic and PCB layout will also be referred to when populating the board.

1.2 Important Soldering Tips

The following tips provide a quick guideline on how to make proper joints.

Cleanliness: All parts, including the soldering iron tip, must be clean and free from grease, oxidation and contamination. Solder does not flow over contaminated areas; moreover, solder is repelled by dirt. Severe contamination is evident when solder begins to “bead”. A common source of contamination is oxidation. Old components and copper boards will often have an oxide layer that prevents a good solder joint. Ensure all components have shiny leads and the PCB has clean traces. An abrasive such as a blue or pink eraser, emery paper, or steel wool can be used to remove the oxidized layer from the PCB board and components.

Tinning: In addition to being clean, the soldering iron tip must also be tinned (coated with solder). Tinning the tip allows solder to flow on the components more quickly rather than the soldering iron tip itself. Tinning involves adding a few millimetres of solder to the tip and then wiping and rotating the tip on the damp sponge to reveal a shiny surface on the tip of the soldering iron: a thin layer of solder will coat or “tin” the tip of the soldering iron. **When done soldering,**

tinning the iron is required to protect the tip from oxidation thereby dramatically increasing its life.

Temperature: Ensure that both the component leads and the PCB's copper layer are heated at the same time. The soldering iron tip should contact both the component and the PCB pad. This will ensure that each surface is relatively close in temperature resulting in a good joint. If there is a temperature difference between the two surfaces, the solder will form a "dry" joint. Soldering irons are typically set around 650 Fahrenheit, depending on the lead-tin ratio of the solder being used. Too much heat causes excessive "sputtering" of flux, and too little doesn't melt the solder in a timely manner.

Duration: The duration that the iron is in contact with the component and PCB is dependent on the size of the joint and your soldering iron temperature. For the typical PCB through-hole joint, it should take a few seconds to heat the joint and apply the solder. This will require practice, so don't expect to be fast if you are a beginner. Excessive heat (several seconds in duration) will damage sensitive semiconductors. If this is a concern, use a heat sink attached to the component leads: sometimes as simple as an alligator clip. These concerns can sometimes be avoided by soldering sockets instead of the semiconductor itself.

Adequate solder coverage: If too little solder is applied, the joint will not make a secure connection and will cause erratic behaviour. However, if too much solder is applied, the joint may bridge with adjacent joints resulting in electrical shorts. How much solder to apply comes with experience. Figs. 1.4 through 1.7 show good and bad solder joints.

Handling: Most modern electronics systems contain static-sensitive devices. Use proper handling procedures to minimize the likelihood of damage: grounding wrist-straps, grounded soldering irons, grounding mats, etc.

1.3 Precautions

Soldering Irons get very hot (600-800°F, 315-425°C), please ensure you follow precautions during use. Basic safety precautions are listed below.

- Never leave your iron turned on while unattended.

- Turn the soldering iron off when it is not being used. If the iron is left on for long periods of idle time, the soldering iron tip will be destroyed through oxidation.
- Eye protection must always be worn when soldering. Hot flux can spit up and into an unprotected eye. **In the Capstone Design Lab, use of eye protection is mandatory.**
- If the cord of the soldering iron is damaged, inform the lab staff who will ensure it is replaced.
- Never set the soldering iron down on anything other than an iron stand.
- To prevent burning your fingers, use needle nose pliers, heat resistant gloves, or a third hand tool to hold small pieces.
- Familiarize yourself with the safe handling of all materials used during the soldering process. This includes solder, flux, alcohol, and desoldering braid. Each has a Material Safety Data Sheet (MSDS) and can be found in the lab or online. “Safe Operating Procedures” are found posted on the wall close to the soldering facilities.

1.4 How to Solder Through-Hole Components

Most of the soldering done in the Capstone Design Lab is through-hole. A through-hole joint is a type of soldering joint in which the component joins with the PCB pad through a physical hole in the board. The following steps will illustrate how to make a proper through hole solder joint on a PCB.

1. Ensure that the printed circuit board and all components are clean. Cleaning can be achieved with a mild abrasive and/or the application of flux.
2. Plug in the soldering iron, turn it on, and let it warm up for 2–3 minutes.
3. Wet the soldering station sponge with the water provided in the lab. Do not wet the sponge in the bathroom or the water fountain.
4. Clean the tip of the soldering iron and tin it with solder.

5. Insert the component into the holes. Ensure that the component is secure by taping the component or by using a third hand. Optionally, the component leads can be clinched as shown in Fig. 1.1. This technique, however, is not recommended for two-sided boards as the flow of solder to the component side is restricted.

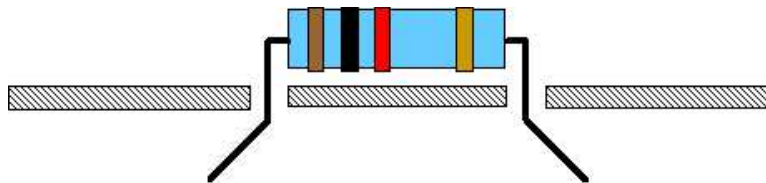


Figure 1.1: Clinched Component Leads

6. Apply the soldering iron tip to one side of joint making contact with the component lead and the board copper foil, ensuring that both are heated up to the same temperature as shown in Fig. 1.2 and Fig 1.3. Notice the tinned tip in Fig. 1.3.
7. Slowly add a few millimetres of solder to the other side of the joint. DO NOT apply solder to the soldering iron tip. If enough heat was applied to the PCB pad and component wire, the solder will flow freely onto the joint.

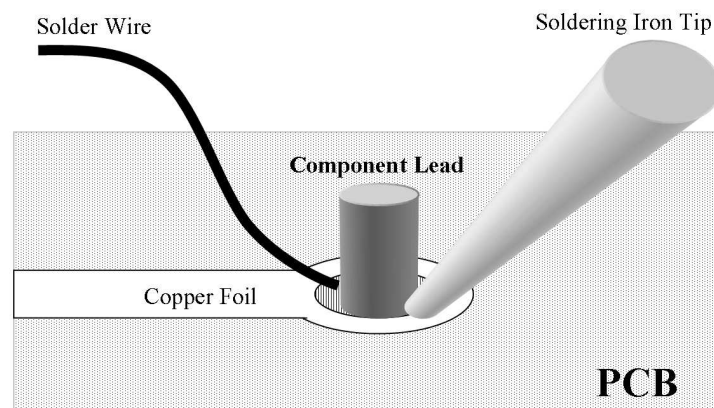


Figure 1.2: Method of Soldering Through Hole Joints

8. Remove the solder when the joint is suitably covered as shown in



Figure 1.3: Method of Soldering Through Hole Joints, [8]

Fig. 1.4. The goal is to get the joint to be a “fillet”: a curve as shown in Fig. 1.4.

9. If the PCB is double-sided, the solder should flow through the hole around the component lead and make a bond on the component side of the board (opposite to the side that the solder was applied). If this “wicking” does not occur, the hole may be undersized, clinching could be blocking the solder’s path, or the component lead is not clean.
10. Remove the soldering iron and allow the joint to cool naturally.

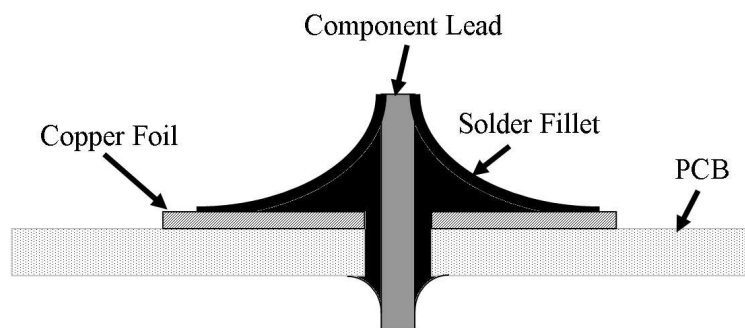


Figure 1.4: Good Solder Joint - Solder Fillet

11. Cut the lead of the component, if necessary.

Fig. 1.6 and Fig. 1.7 below are pictures showing good and bad solder joints.



Figure 1.5: Good Solder Joint, [8]

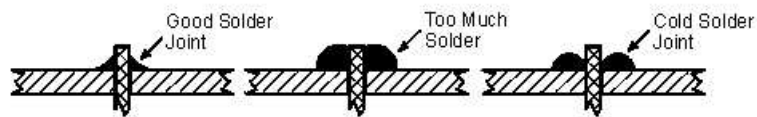


Figure 1.6: Joint Examples, [3]

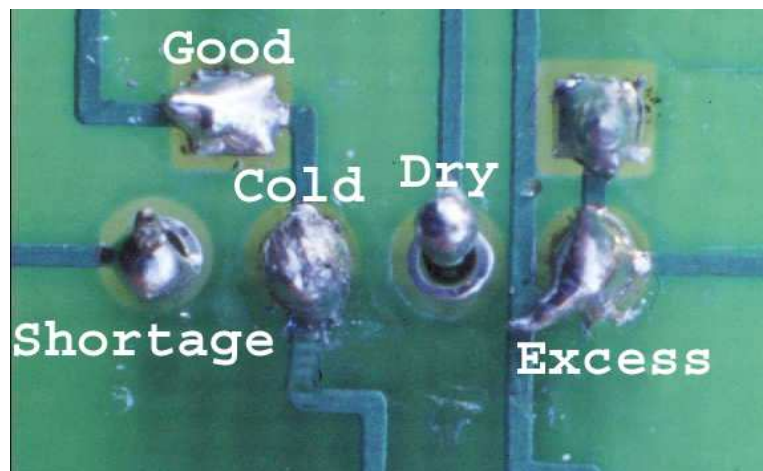


Figure 1.7: Joint Examples, [2]

1.5 How to Solder Surface-Mount Components

Surface mount soldering requires more experience and skill than through hole. It is recommended that one practices with through-hole prior to attempting any surface mount soldering. As the name suggests, surface mount involves soldering a component to either the top or bottom surface of a PCB. Depending on the footprint, the pads are usually spaced closer together (finer pitch), making the soldering more susceptible to solder bridges, etc.

Figs. 1.8 and 1.9 show examples of good surface-mount solder joints.

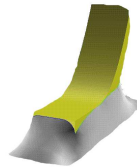


Figure 1.8: Surface Mount Good Solder Joint, [6]

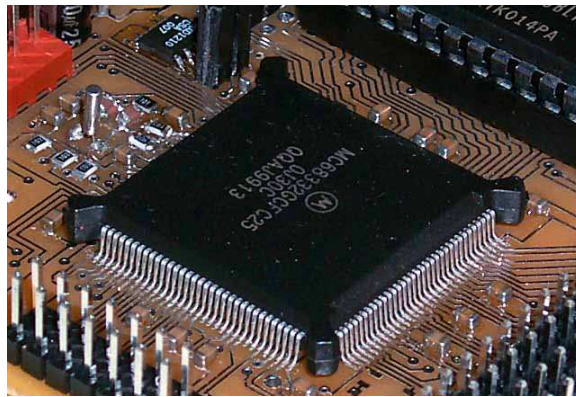


Figure 1.9: Surface Mount IC with Good Solder Joints, [5]

The actual soldering of the joints is similar to the through-hole method. One difficulty, however, is maintaining the part's alignment on the PCB pads. A good technique is outlined here:

1. Align the component on the PCB pads. This can be aided with the use of tweezers and dental picks.
2. Secure the component to the PCB by applying a small amount of pressure onto the top of the component using a small slot screwdriver.

An index finger resting on the end of the screwdriver provides enough force to secure the device.

3. Solder one of the corner component leads to the PCB pad.
4. Align the remaining pads and solder the opposite corner PCB pad.
5. Solder the remaining pads in a pattern that does not build-up too much heat in the device.

1.6 Wire Connectors and Headers

When PCBs are manufactured they often have connectors to peripheral devices. These connectors are like other components in how they are soldered onto the PCB. However, the plug that matches the connector usually also requires some soldering. **Please note that with very few exceptions, the wire used for cabling is stranded (rather than solid-core) due to its higher strength and flexibility.** Below are procedures for a few of the more common plug types.

1.6.1 Crimp Connectors and Pins

1. Strip off about 1cm of the wire insulation.
2. Place the exposed wire into the crimp-style connector or pin. The wire should just barely show coming out the other side. Some crimp pins have two crimping areas – one for the stripped wire, and the other for the wire *with* the insulation.
3. Crimp the connector with the appropriate crimping tool. Note that the connectors are colour coded to settings on the crimping tool, try and match the correct colour.
4. As added insurance, apply solder to the joint to solidify the connection.

Before crimping all pins destined for a connector housing, start with one and ensure that it fits successfully into the housing. If the crimp is made too tightly, or otherwise mis-shaped, the pin may no longer fit.

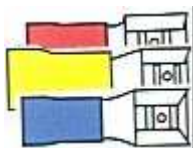


Figure 1.10: Colour Coded Crimp Connectors



Figure 1.11: Crimp connector without shrink wrap, [\[1\]](#)

1.6.2 DB Connectors (Solder Cup Type)

1. Strip off about 5mm of the wire insulation.
2. Tin the wire.
3. Slide shrink wrap on the wire.
4. Place the wire into the DB - connector solder end.
5. Apply the soldering iron tip to the connector and wire.
6. Apply a few millimetres of solder until the joint is adequately covered.
7. Let the joint cool.
8. Slide the shrink wrap over the joint and heat the shrink wrap with a heat gun (or other heat source) until the wrap shrinks around the joint.

1.6.3 Joining Two Wires

1. Slide shrink wrap on one of the wires.
2. Tin or coat each wire with some solder.
3. Join the wires in a way that provides a good mechanical connection (such as twisting together) and apply the soldering iron tip and some solder.

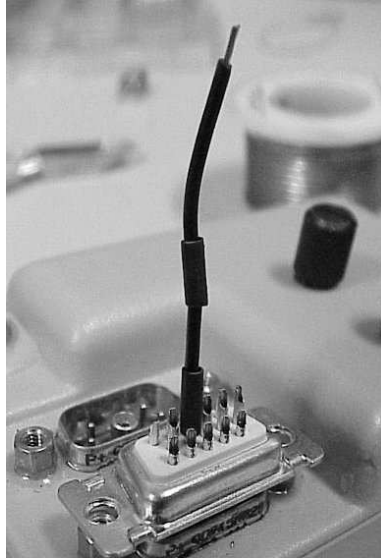


Figure 1.12: DB Connector with shrink wrap, [7]

4. Let the joint cool.
5. Slide shrink wrap over the joint and heat the shrink wrap with a heating gun or a heat source until it the the wrap shrinks around the joint.



Figure 1.13: Two wire joint insulated by shrink wrap, [4]

1.7 Testing Connections

After completely soldering a component to a PCB, it is good practice to ensure connectivity between the component wire leads and the PCB pads they are soldered to. A DMM (Digital Multi-Meter) is sufficient to deter-

mine connectivity; many DMMs include an audible connectivity setting, but failing this, measure the joint resistance.

1.8 Milled Board Soldering

In-lab manufacture of PCBs uses a technique known as “milling”. The milling technique involves cutting out the PCB tracks and pads from the copper-clad board.

Due to its construction, a milled PCB is susceptible to solder-bridging across the milled grooves, particularly when an excess of solder is used. Finding a short caused by a bridge is a difficult task, particularly when many solder joints exist. To this end, make a limited number of solder connections and then test for bridges using a multimeter.

1.9 Post-Soldering Cleanup

1.9.1 PCB Cleanup

The flux left behind by rosin-core solders, or perhaps as part of the cleaning process, needs to be removed from the PCB. Due to the flux’s sticky nature, dirt gathers and contributes to short-circuiting problems. The most frustrating part of this situation is that a short does not necessarily occur immediately. Weeks, or even years later, a short can develop.

To remove flux, alcohol is used. Apply the alcohol liberally and then brush away with an acid brush, starting at the center of the PCB and working out toward the edges. This is a time-consuming task, but a clean board is well-worth the effort.

1.9.2 Work Area Cleanup

The importance of keeping your work area clean cannot be emphasized enough. When clear of obstructions and garbage, handling a hot soldering iron is safer. The soldering process itself involves chemicals and substances which are known to have ill-effects in humans. Wiping-down the work-area surfaces with a moist paper towel will help reduce some contamination. When you are done soldering, **wash your hands with soap and water** to get rid of contamination. The primary concern here is accidental ingestion of the chemicals. For more information, please refer to the Safe Operating Procedures, posted in the lab’s soldering area.

Chapter 2

Desoldering Technique

Desoldering may be required for several reasons:

- a component may have failed
- a wrong part was installed;
- a design modification necessitates a change; or
- if a board contains expensive components that can be salvaged.

Whatever the reason, there are three common techniques to remove solder from a joint: using a desoldering pump, a desoldering wick, or desoldering iron.

Regardless of the method used, if it is permissible to destroy the part during removal, then a lot of time and effort can be saved. For instance, using wire cutters to trim off all the pins of a through-hole IC so they can be removed individually makes the removal process much easier. In most cases, avoiding damage to the PCB is of paramount importance.

2.1 Solder Pump/Sucker

A desoldering pump is exactly what it sounds like: a pump that sucks up solder. Usually the pump is spring-loaded and provides a recoil when released. The four steps below outline how to desolder a joint using a desoldering pump.

1. Prime the desoldering pump. This involves depressing the desoldering pump spring. The pump will click when correctly depressed.

2. Heat the joint from one side with the soldering iron tip. Wait 1-2 seconds until the solder begins to melt from the soldering iron heat.
3. Put the pump tip on the other side of the joint. Don't be afraid to actually touch the joint.



Figure 2.1: Desoldering with a Solder Pump, [8]

4. Press the desoldering pump spring-release button to suck up the solder.

This procedure should be repeated if the joint has a significant amount of solder. If done correctly the joint should eventually look as shown in Fig. 2.2 shown below.



Figure 2.2: Clean Joint from Desoldering with a Solder Pump, [8]

2.2 Desoldering Braid/Wick

A desoldering braid removes solder from a joint using a technique known as “wicking”. Desolder braid is a piece of material that sponges up molten solder by capillary action that draws solder away from the joint the braid. The following procedure outlines the basic steps involved in desoldering a joint using desoldering braid.

1. Place the desoldering braid over the joint.
2. Press the desoldering braid onto the joint with the soldering iron tip. This will apply heat to the desoldering braid and the joint allowing the molten solder to flow.
3. Wait for the solder to melt. The solder should flow onto the braid and away from the joint.



Figure 2.3: Desoldering with a Solder Wick, [8]

4. Cut off the solder coated portion of the desoldering braid. **There should be no copper visible in the portion that is removed: braid is very expensive.**

2.3 Desoldering Iron

Using a desoldering iron, available with higher-end soldering stations, is similar to using a solder sucker. The desoldering iron is essentially a soldering iron with a built-in vacuum.

1. Make contact between the iron and the joint to be desoldered, ensuring the vacuum opening is not blocked.
2. Once the solder on the joint has become molten, depress the button on the iron to activate the vacuum.

It is very important for the life of the desoldering iron that the vacuum assembly be cleaned after every session of use. Please ask the lab personnel for a description of the cleaning procedure.

As with a normal soldering iron, the desoldering iron tip should be tinned before and after every use.

2.4 Removing Components Effectively

To remove a component with little or no damage to the PCB or component takes practice and **patience**. Often when removing a component, PCB pads and tracks may be damaged by “lifting” off the board. Below are some tips that may be useful when removing components from a PCB.

- Desolder all joints pertaining to a component prior to removal. It may be necessary to go over the joints several times before all the solder is removed. Practice patience.
- Use pliers and *gently* pull on components while applying heat to the joints. The assistance of a friend can help with this.
- Do not pull with force, because the PCB pads and tracks will be damaged.
- Do not try and remove components by prying them.
- Do not try to push the component out of the holes with the soldering tip. This will certainly lift the copper pad off of the PCB and ruin the iron tip.
- In order to get better thermal conductivity between the iron and the solder joint, it is sometimes effective to *add* a small amount of solder.

Chapter 3

Glossary

BOM: Bill of Materials, which contains a list of all components and values contained on a particular PCB. Used as a “shopping list”.

Desoldering Braid: A material used to remove solder with capillary action.

Desoldering Pump: A device used to remove solder with a swift vacuum action.

Flux: Cleans the surfaces that are being heated by bringing contaminants to the surface. Most solders include flux in their core. For excessive contamination use a flux pen.

Footprint: The spacing pattern or layout of pads for a particular component or integrated chip, as used on a PCB.

PCB (Printed Circuit Board): A fibreglass board upon which copper traces are laminated to make connections between various components. The copper traces serve as flat wires connecting various components.

Shrink Wrap: A tube that fits over a wire, that when heated shrinks to provide insulation and support for the joints.

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Appendix A

Pictures of Tools

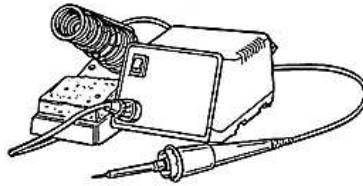


Figure A.1: Soldering Iron



Figure A.2: Solder Wire



Figure A.3: Desolder Pump



Figure A.4: Desolder Braid



Figure A.5: Third Man

Soldering

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1 Soldering Printed Circuit Boards.....	3
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Introduction

Soldering is a process used for joining metal parts to form a mechanical or electrical bond. It typically uses a low melting point metal alloy (solder) which is melted and applied to the metal parts to be joined and this bonds to the metal parts and forms a connection when the solder solidifies. It is different to welding in that the parts being joined are not melted and are usually not the same material as the solder.

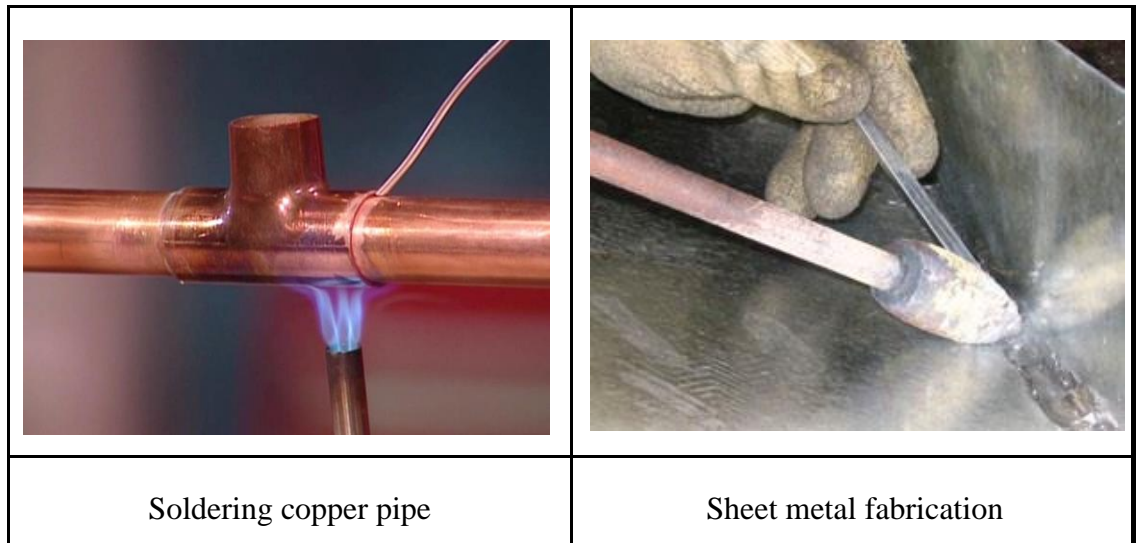


Figure 1 – Different Types of Soldering

Soldering is a common practice for assembling electrical components and wiring. Although it can be used for plumbing, sheet metal fabrication or automotive radiator repair the techniques and materials used are different to those used for electrical work. This document is intended to provide guidance on the safe working methods and proper tools and techniques for soldering of electrical components.

1 Soldering Printed Circuit Boards

Soldering may be used to join wires or attached components to a printed circuit board (PCB). Wires, component leads and tracks on circuit boards are mostly made of copper. The copper is usually covered with a thin layer of tin to prevent oxidization and to promote better bonding to other parts with solder. When soldering bare copper wires they are often “tinned” by applying molten solder before making a joint.

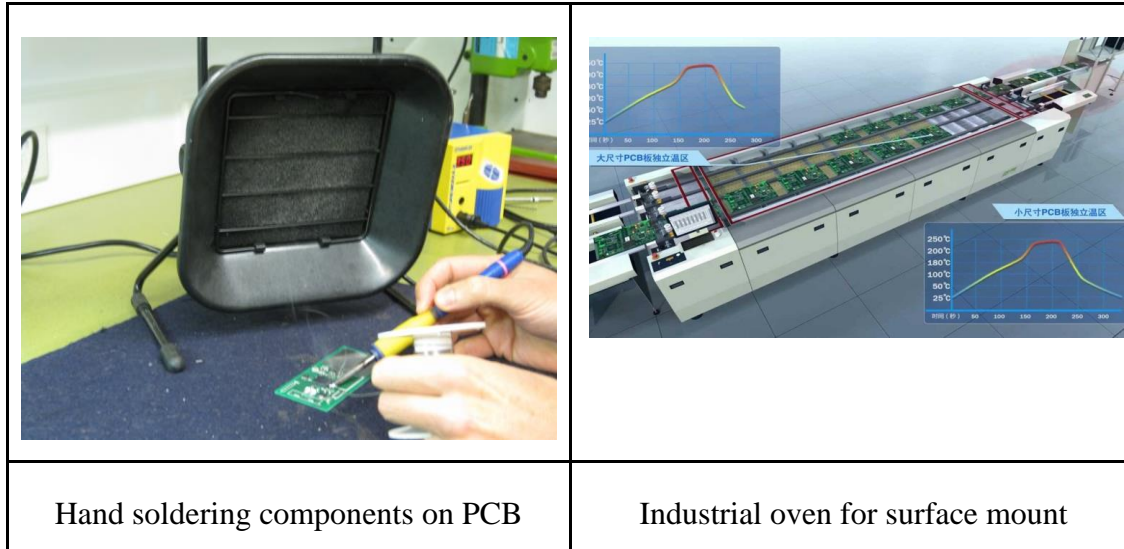


Figure 2 – Different Types of PCB Soldering

2 Types of Solder

There are different types of solder used for electrical work. They are broadly classified as tin/lead solders or lead free solders. Tin/lead solders have been used for many years because of their ease of use however they have been phased out of commercial use due to the harmful effects on humans and the environment. Tin/lead solder is still available and is used by “hobbyists” and other non-commercial users as it is still easier to use than lead free types. When using tin/lead (or leaded) solder there are additional safety precautions that must be observed.



	
<p>Different gauges of solder wire</p>	<p>Solder composition is labelled (Lead free on left)</p>

Figure 3 – Different Types of Solder

3 Types of PCB

Printed circuit boards (PCBs) are populated by electronic components and these may be “surface mount” or “through-hole” types.

3.1 Through-Hole Components

As the description “through-hole” suggests, the leads of the component are passed through holes in the PCB and then soldered to a “pad” on the reverse side of the PCB. Soldering is accomplished by heating the component lead and PCB pad with a soldering iron and melting solder wire into the joint. This type of construction was common from the 1960’s until early 2000’s and is still used by hobbyists and in small scale production where manual assembly is preferred.

3.2 Surface Mount Components

Commercial circuits are mostly of the surface mount type as these are cheaper to make, more compact and easier to automate assembly. For surface mount construction the component’s pads are on the same side of the PCB as the component and the component connections sit onto these pads. Soldering is accomplished by applying solder paste onto component pads on the PCB, placing the component onto the paste and then heating the entire assembly to melt the solder. Commercial assembly uses ovens to heat the boards. Hobbyists can also use surface mount components and soldering can be accomplished by applying solder paste and melting with a hot plate, small oven or soldering iron. Some surface mount joints can be soldered using a soldering iron and solder wire.

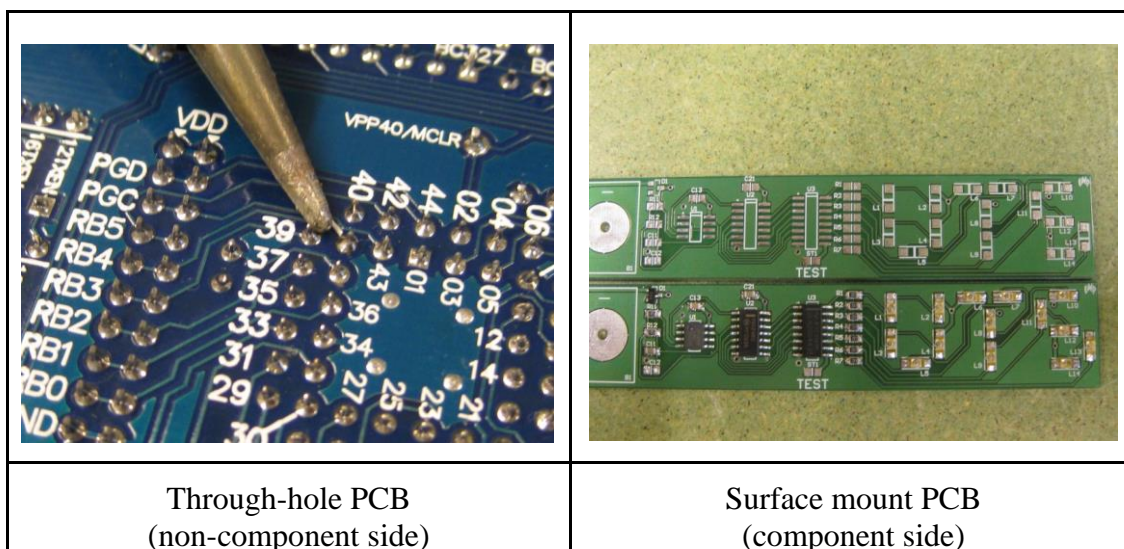


Figure 4 – Different Types of PCB

4 Flux

For electrical soldering both solder wire and solder paste contain flux. This helps to clean the surfaces being soldered and prevent oxidization of the hot solder. The composition of the flux will vary depending on whether it is in a paste or wire, leaded or unleaded solder. Solder wire usually contains a flux called “rosin”. Most fluxes will produce fumes when the solder is heated and these fumes are likely harmful to your health. For occasional soldering it may be sufficient to have a well-ventilated workspace but for longer or repeated exposure a fume extractor should be used. Solder flux can also cause solder to spatter and eye protection should be worn when soldering.

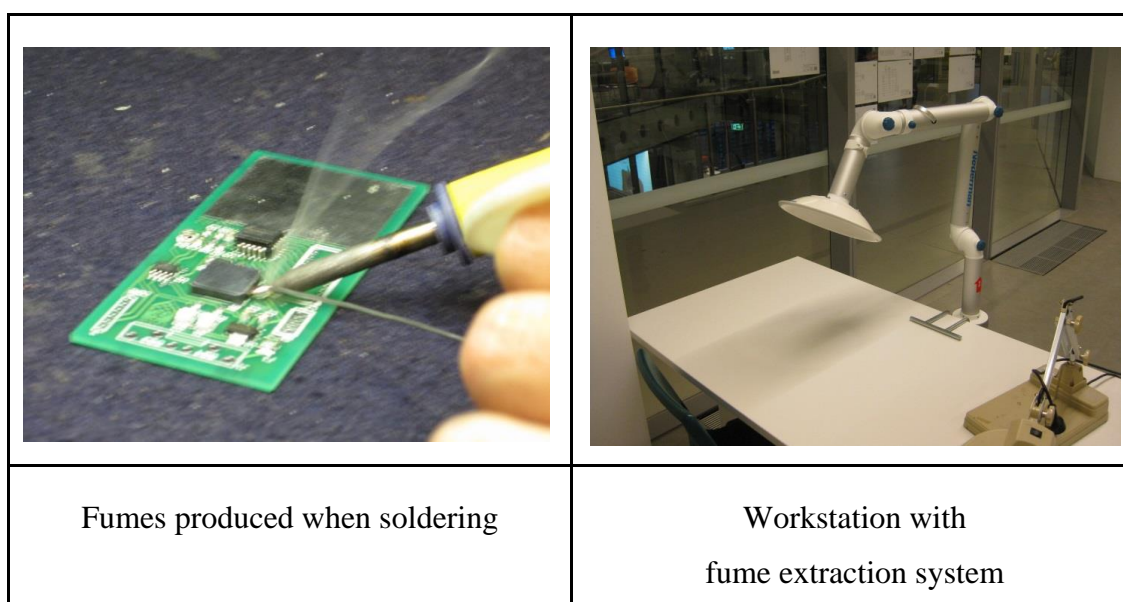


Figure 5 – Fumes and Fume Extraction Systems

5 Soldering Irons

Soldering irons come in many varieties and sizes. Soldering irons may be electric, gas powered or externally heated. Most common types are electric. Simple electric soldering irons have no controls and you simply plug them in and wait for them to heat up. Their temperature is regulated by the power of the heating element and heat loss to the environment. Some soldering irons have temperature controls which allow the user to set a desired operating temperature for the soldering iron. This is useful if the soldering iron is being used for different types of solders which have different melting points or if the soldering iron is being used for other purposes such as heating heatshrink. It also introduces a problem if the user does not set an appropriate temperature for the work, solder can be overheated and decompose. Hotter is not better! A temperature of around 320 °C works well for 60/40 leaded solder. Some temperature controlled soldering irons use interchangeable tips to change the temperature at which they operate.


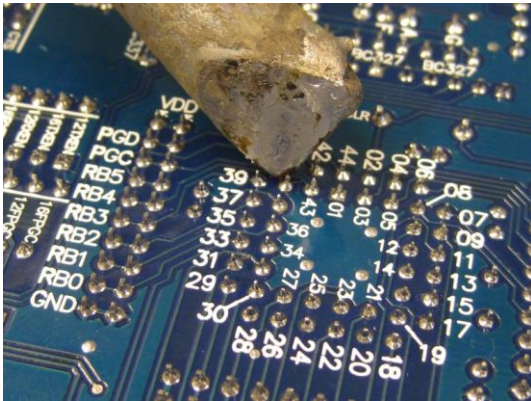
	
A range of electric soldering irons	Choose an iron appropriate for your task!

Figure 6 – Types of soldering irons

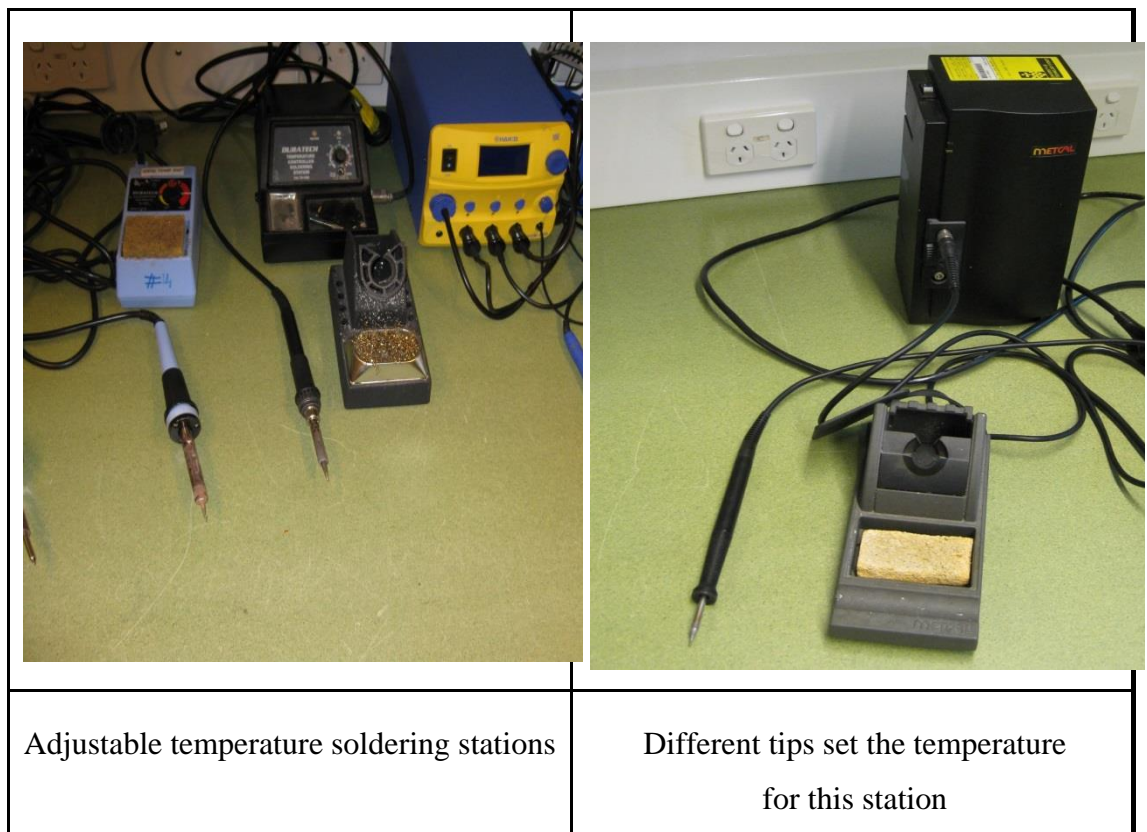


Figure 7 – Types of soldering stations

5.1 Tips

Heat is transferred from the tip of the soldering iron to the joint by thermal conduction enabled by metal to metal contact between the tip and joint. The tips of soldering irons come in various shapes and sizes to enable the best contact to be made. Most tips are either conical or chisel shapes. The shape is largely a personal preference and you can use whichever type works best for you. The size of the tip should be selected to allow the tip to be placed against the joint being soldered without interfering with adjacent parts. The tip should be large enough to conduct sufficient heat into the joint to allow the solder to melt and flow properly. The choice of tip size is not a precise calculation and a “normal” size tip will work for most joints on a PCB.

5.2 Tip Contamination and Cleaning

The thermal conduction from the tip to the joint may be inhibited by contamination on the tip. This contamination can be formed by burnt solder flux or oxidized solder. To make best thermal contact the tip should be cleaned using a tip cleaner(!). Two types are a wet sponge or a brass wire wool. The wet sponge removes the contaminated material when the tip is wiped across it, the water in the sponge cools the solder and the mechanical abrasion removes the contamination leaving a thin coating of clean solder on the tip. This method can cause the tip temperature to dip momentarily. The brass wire wool type removes the contamination by mechanical abrasion and bonding contaminated solder to the brass. The tip is pushed into the brass wool and when it is withdrawn the tip is clean with a thin coating of solder. You must not “wipe” the tip on the brass wool type because the springiness of the brass wool may flick molten solder which may cause burns to people or objects. You should never “flick” excess solder from the soldering iron as this may also cause burns or damage.



Figure 8 – Dirty tip and brass wool cleaner

6 Ovens and Hot Plates

For surface mount soldering the heat is usually applied to the whole PCB and all components soldered at the same time. For commercial work this is done in large ovens, often with conveyors to move the boards through the oven. For small scale work simple infrared ovens are available. Another technique uses a hotplate. The same considerations for temperature apply, although because the heat source does not come into contact with the solder or flux, contamination is less likely. Time and temperature are considerations with these methods as the components are exposed to the high temperature for the period required for the solder paste to melt and flow.

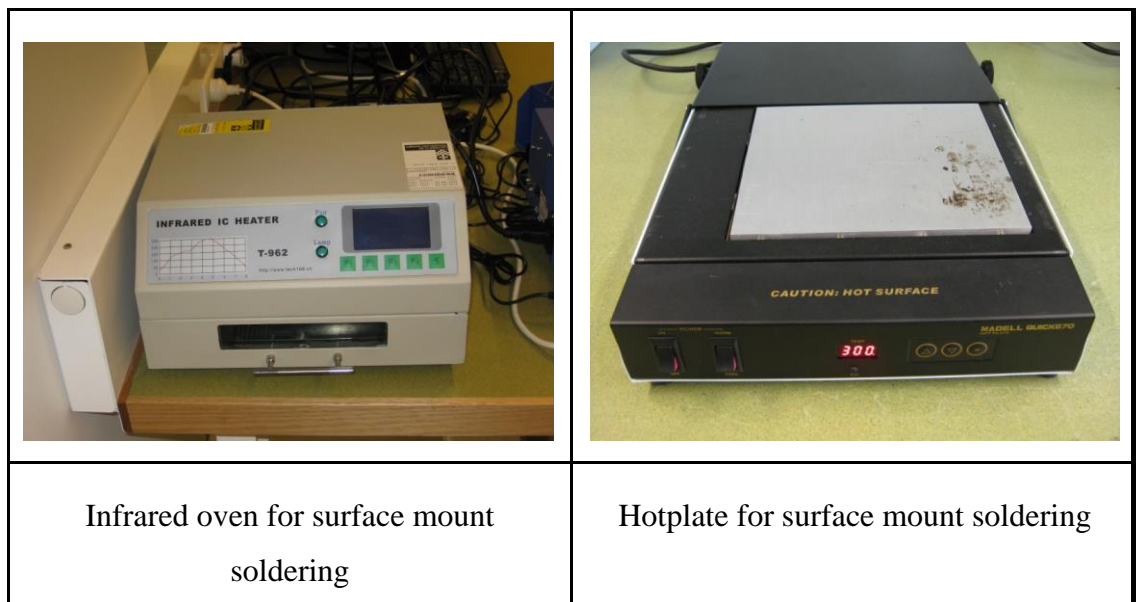


Figure 9 – Oven and hot plate used for surface mount soldering

7 Desoldering

If a part that has been soldered needs to be replaced it needs to be “de-soldered”. Depending on the part and type of joint it may be possible to simply re-melt the solder and remove the part, or it may be necessary to remove the solder from the joint so the part can be freed. Some methods for removing solder are solder wick, solder sucker or de-soldering tool. Solder wick is a copper braid which is applied to the joint and heated with a soldering iron. As the solder in the joint is melted it is drawn into the solder wick like a sponge and is removed from the joint. A solder sucker is a spring loaded syringe or rubber bulb. The tip of the solder sucker is placed near the joint as the joint is melted by a soldering iron. When the sucker is operated a vacuum is created which draws the molten solder from the joint into the body of the sucker. A de-soldering tool is a type of soldering iron with a hollow tip and is connected to a pump or vacuum source. The tip of the de-soldering tool is placed onto the joint, typically over a component lead, and once the solder has melted the pump is operated to draw the molten solder away.

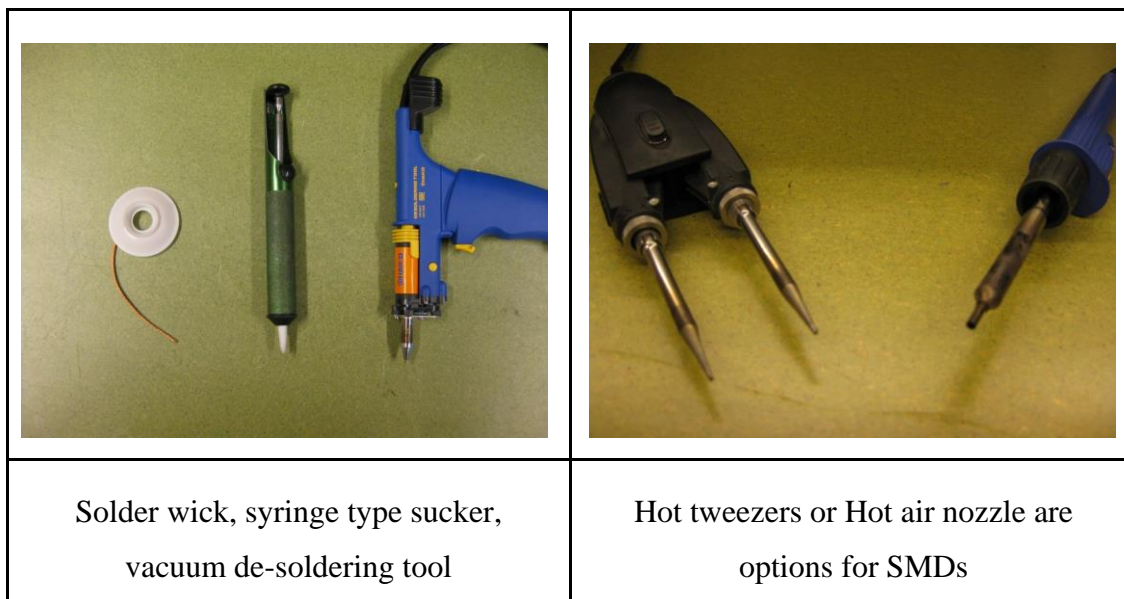


Figure 10 – Desoldering tools and tweezers for surface mount devices

8 Hazards involved in soldering

8.1 Heat

Although solder has a relatively low melting point this temperature is more than high enough to cause serious burns to people or objects. It is important to hold the soldering iron only by the insulated handle, never touch the heating element or tip when the soldering iron is on. The soldering iron will remain hot for some time after it is turned off so always check that it has cooled down before touching it, e.g. if changing the tip. When you are not soldering always keep the soldering iron in a proper holder so that you don't touch it accidentally and it doesn't heat or burn other objects such as the benchtop. Don't hold parts being soldered with your hands as these will also be heated when being soldered. Don't flick molten solder from the soldering iron or wipe the tip on brass wool type tip cleaners.

If using a hot plate for surface mount soldering do not touch the hot plate. Use utensils such as pliers to place and remove PCB's from the hotplate. If using hot air tools for soldering, de-soldering or rework, do not direct the hot air stream onto yourself or other people. If using an oven allow the PCB to cool before handling or use utensils. Don't place hot PCB's on temperature sensitive surfaces.

If burns occur they should be treated by holding under cold running water for several minutes and assistance sought if burns are severe. Incidents should be reported.

8.2 Toxic materials

Leaded solder contains lead which is a harmful material. Use of this type of solder will probably involve handling it and your skin may become contaminated by it. Although it is unlikely that the lead can be absorbed directly through your skin it may be ingested indirectly if it is transferred by handling food whilst your skin is contaminated. Always wash your hands thoroughly before eating or handling food.

Solder flux creates fumes when heated during soldering which may be harmful if inhaled. Use a fume extractor to avoid inhaling fumes.

8.3 Spattering

Solder and flux can spit or spatter when heated. Always wear eye protection (safety glasses) when soldering.

8.4 Electrical Safety

Electric soldering irons are plugin appliances and must have a current safety test tag. The test will confirm that the soldering iron conforms to electrical safety standards and has not been damaged at the time of the test. Before use you should visually check that the soldering iron does not have damage such as melted insulation on the lead, broken or cracked handle or exposed conductors. Don't use damaged equipment and report the damage.

For electrical safety the exposed metal parts such as the tip and heating element are earthed. Don't solder on any live equipment as contact with the earthed tip may cause damage to the equipment or soldering iron.



SMD Soldering

Information & Instructions

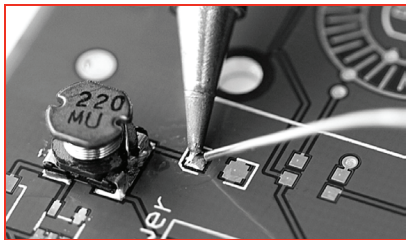


This is a walkthrough of a SMD Soldering Workshop. The following information and instructions can be used as a simple method for soldering SMD components. The recipient of this information should acknowledge the danger of soldering (*written on the back page of this pamphlet*) before attempting to solder.

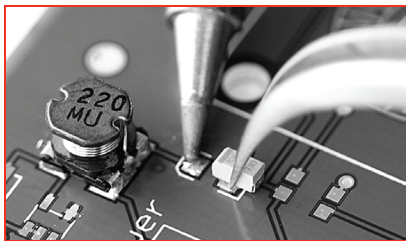
Recommended Tools:

- Soldering Iron
- Solder
- Tweezers
- Solder Wick
- Flux Pen

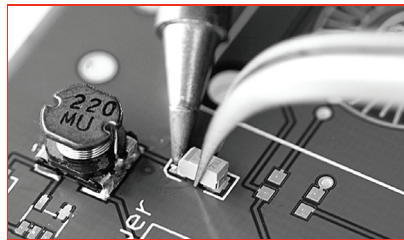
- 1 Add solder to one pad.



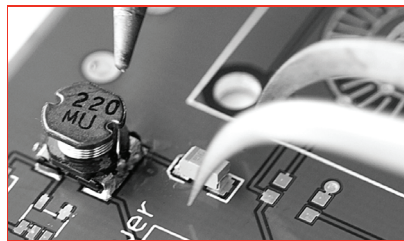
- 2 While that pad is molten, slide the component into place. Do not push down from the top - slide the component into the blob of solder horizontally.



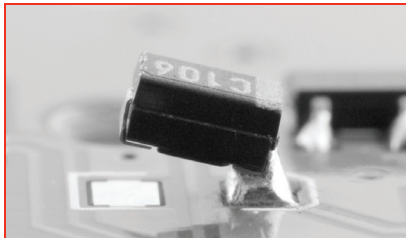
- 3 Align the component while connection is still molten.



- 4 Once you have good alignment, continue to hold the component in place, and remove your iron. Continue to hold component for 1-2 seconds while the solder joint solidifies.



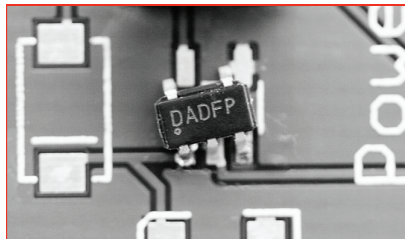
- ⑤ From above, the alignment looked good. From the side, you can see the rear pad is hovering slightly above the PCB. This can lead to problems on multi-pin components (open connections). Be sure the component is flush up against the PCB before soldering more connections. Re-grip the component, re-heat pad 1 and push the component flush against the PCB.



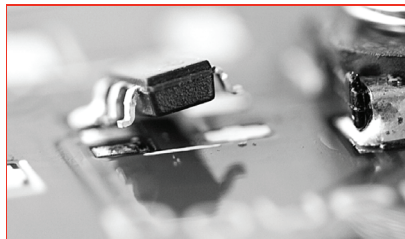
- ⑥ This is how a tantalum capacitor should look after making both solder connections.



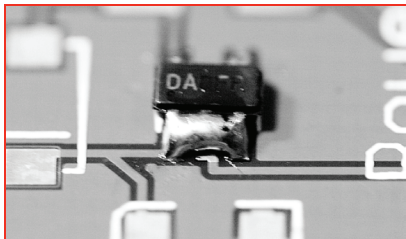
- ⑦ If alignment is not good, do not solder more than 1 pad! Re-heat the joint, re-adjust component until aligned correctly, then move on to soldering other connections.



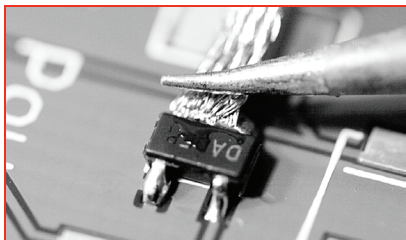
- ⑧ This is bad. It would be nearly impossible to finish the connections on this part. Make sure you have the component flush against the PCB.



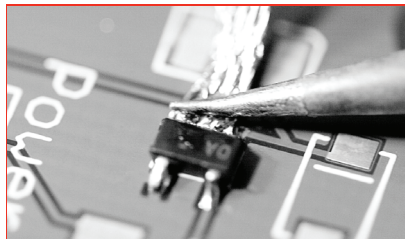
- 9 If you solder multiple pins together, don't worry about it! It can be easily fixed. Do not worry about jumpers! There are actually three pins under that blob.



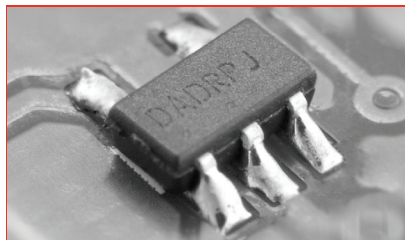
- 10 Pull out some solder wick. Put a small amount of solder on the end of your iron (this will transfer heat from iron to wick to the jumper). Sandwich the wick in between the iron and the solder jumper.



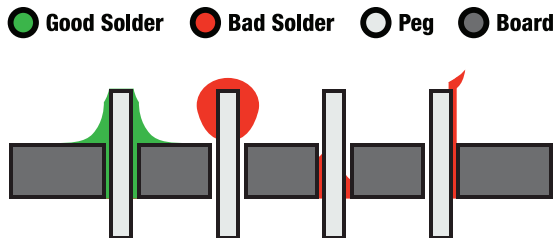
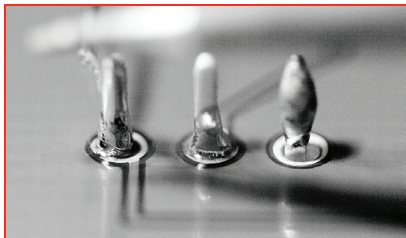
- 11 Hold still for 2-3 seconds. You will see solder start to flow up the wick. Once the excess solder has flowed into the wick, carefully lift up the wick and your iron in one fluid motion.



- 12 Nice and clean!



- 13** Bad bad bad. There was not enough solder for the connection on the left. Middle pin is lacking solder and should have been heated for longer. Right pin has had solder applied by an iron rather than applied to two metal contacts (the board and the pin).



TIPS & TRICKS



- A** Solder flows smooth all the way to the bottom.



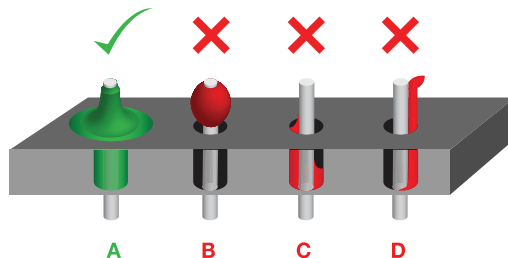
- B** **Error:** Solder balls up on top of pad, not connecting pin to pad.
Solution: Flux then wick. If you wick too much add solder.



- C** **Error:** Too little solder makes for weak connection.
Solution: Flux then add solder.



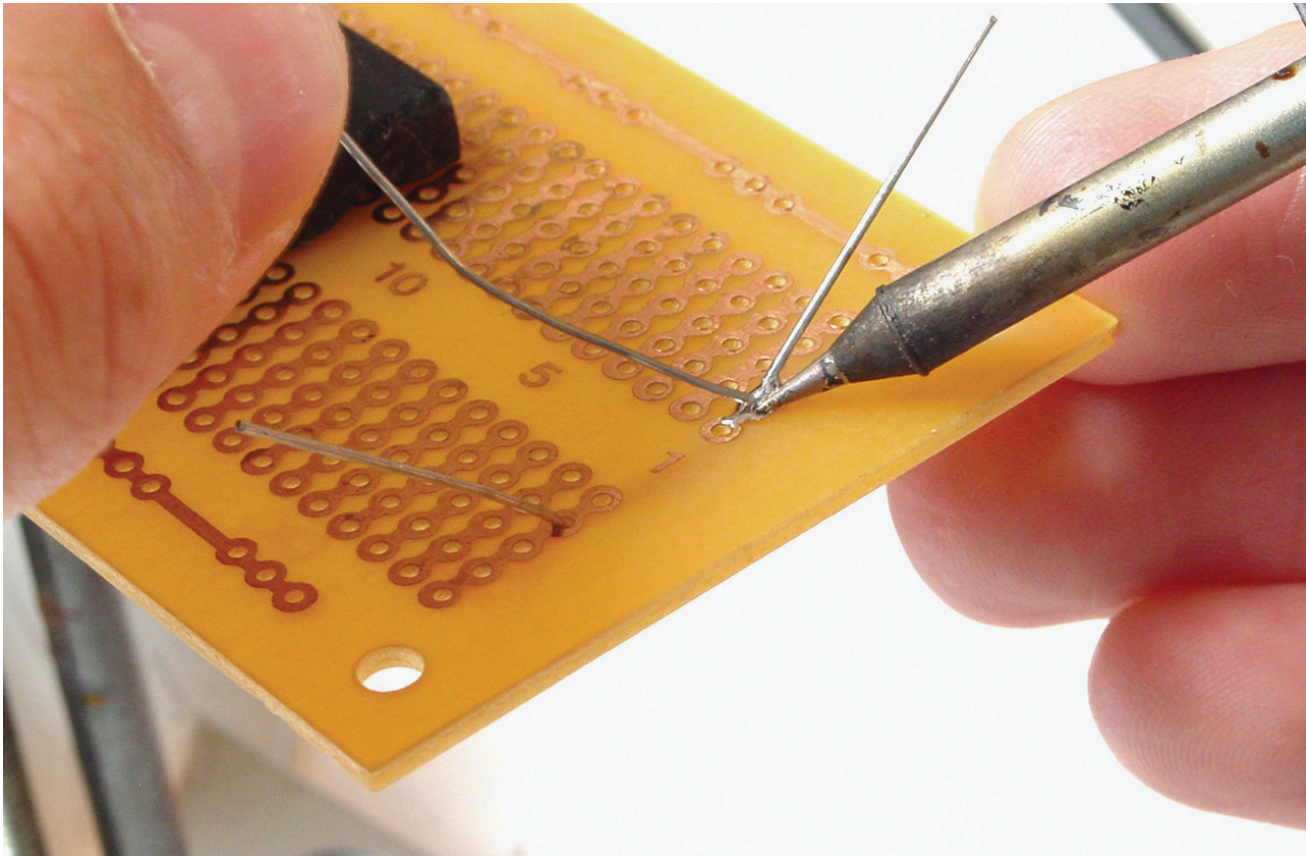
- D** **Error:** Bad Connection... and ugly... oh so ugly.
Solution: Flux then add solder.



Safety Issues

Soldering


The tip of the iron is normally 700 °F, hot enough to melt metal. It is normal for the handle of the soldering iron to heat up a bit. Hold it like a pencil and move your hand further away from the tip if the heat is uncomfortable. The solder smokes because the rosin inside the solder is burning off - it's not harmful.



Soldering and Desoldering

Step-by-step instructions
for making (and unmaking)
the perfect solder joint.

By Joe Grand

 The two key parts of soldering are good heat distribution and cleanliness of the soldering surface and component. With practice, you'll become comfortable and experienced with the process.

In this primer, I'll explain how to solder a component onto a printed circuit board (PCB). I'll also provide desoldering tips and show you how to remove a surface-mount component from a printed circuit board using a Chip Quik kit. And I'll show you how to remove a component by removing the solder in a way that won't damage the components or the circuit board.

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Photography by Joe Grand

Tools of the Trade

Soldering iron You could pay as little as \$10 or as much as \$1,000 for a soldering iron. I recommend a fine-tip, 700°F, 50W soldering stick iron. A good general-purpose iron for hardware hacking is the Weller W60P Controlled-Output Soldering Iron, which sells for under \$70.

Solder Should be thin gauge (0.032" or 0.025" diameter) 60/40 rosin core.

Desoldering tool (aka solder sucker) A manual vacuum device that pulls up hot solder, useful for removing components from circuit boards. I like the one RadioShack sells (#64-2098, \$10).

IC extraction tool Helps lift integrated circuits from the board during removal/desoldering.

Chip Quik SMD Removal Kit Allows you to remove surface mount components quickly and easily. Chipquik.com offers the kit for \$16.

Sandpaper A very fine-grit sandpaper is useful for removing oxidation from component and circuit board surfaces.

Desoldering braid Woven metal material used to wick up melted solder.

Small, flat-tip screwdriver Comes in handy for removing some types of components.

Needlenose pliers, wire cutters, and vise These common tools will make your job easier.

The Chip Quik SMD Removal Kit

The Chip Quik SMD Removal Kit allows you to quickly and easily remove surface-mount components such as PLCC, SOIC, TSOP, QFP, and discrete packages. The main component of the kit is a low-melting-temperature solder (requiring less than 300°F) that reduces the overall melting temperature of the solder on the SMD pads. Essentially, this enables you to just lift the part right off the PCB.

INCLUDES

- » Alcohol pads for cleaning the circuit board after device removal
- » A special low-melting-temperature alloy
- » Standard no-clean flux
- » Application syringe



Desoldering Tips

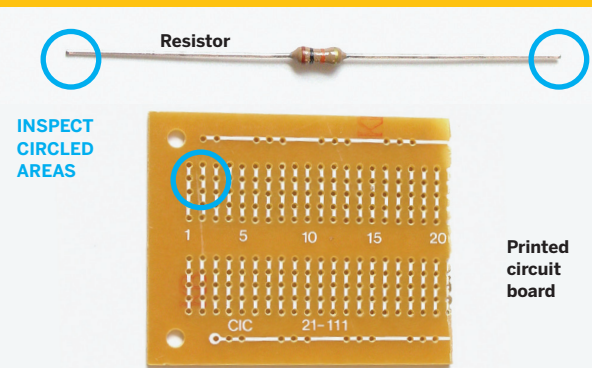
FOR STANDARD THROUGH-HOLE COMPONENTS

- » First grasp the component with a pair of needlenose pliers. Heat the pad beneath the lead you intend to extract and pull gently. The lead should come out. Repeat for the other lead.
- » If solder fills in behind the lead as you extract it, use a spring-loaded solder sucker to remove the excess solder.

FOR THROUGH-HOLE ICs OR MULTI-PIN PARTS

- » Use a solder sucker or desoldering braid to remove excess from the hole before attempting to extract the part.
- » You can use a small, flat-tip screwdriver or IC extraction tool to help loosen the device from the holes.
- » Be careful to not overheat components, since they can become damaged and may fail during operation.

BEFORE YOU START



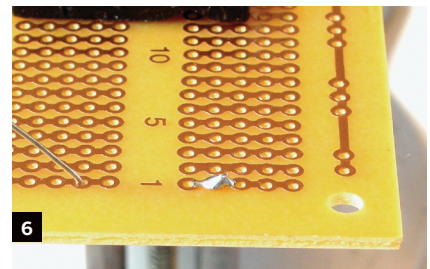
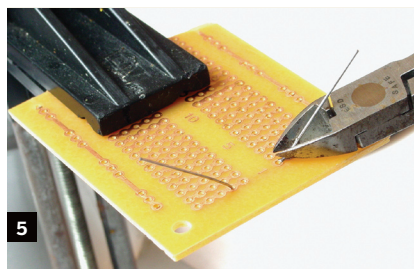
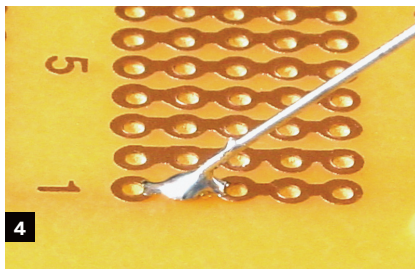
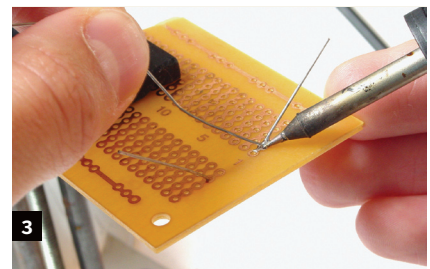
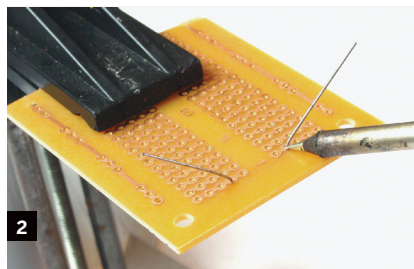
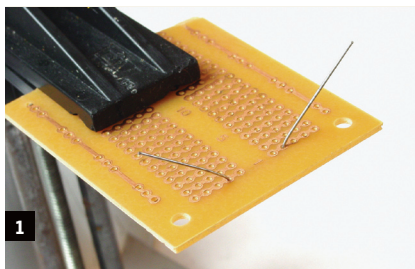
BEFORE YOU START

Inspect the leads or pins for oxidation. If the metal surface is dull, sand with fine sandpaper until shiny. In addition, use the sandpaper to clean the oxidation and excess solder from the soldering iron tip to ensure maximum heat transfer.

This simple example shows the step-by-step process to solder a through-hole component to a printed circuit board (PCB). I used a piece of prototype PCB and a single resistor.



DANGER: It's important to consider safety precautions. Improper handling of the soldering iron can lead to burns or other physical injuries. Wear safety goggles and other protective clothing when working with solder tools. With temperatures hovering around 700°F, the tip of the soldering iron, molten solder, and flux can quickly sear through clothing and skin. Keep all soldering equipment away from flammable materials and objects. Be sure to turn off the iron when it's not in use and store it properly in its stand.



1. Bend and insert the component leads into the desired holes on the PCB. Flip the board to the other side. Slightly bend the lead you'll be soldering to prevent the component from falling out when the board is turned upside down.

2. To begin the actual soldering process, allow the tip of your iron to contact both the component lead and the pad on the circuit board for about 1 second before feeding solder to the connection. This will allow the surface to become hot enough for solder to flow smoothly.

3. Next, apply solder sparingly and hold the iron in place until solder has evenly coated the surface. Ensure that the solder flows all around the 2 pieces (component lead and PCB pad) that you're fastening together.

Don't put solder directly onto the hot iron tip before it has made contact with the lead or pad; doing so can cause a cold-solder joint (a common mistake that can prevent your hack from working properly). Soldering is a function of heat, and if the pieces aren't heated uniformly, solder may not spread as desired. A cold-solder joint will loosen over time and can build up corrosion.

4. When it appears that the solder has flowed properly, remove the iron from the area and wait a few seconds for the solder to cool and harden. Do not attempt to move the component during this time.

The solder joint should appear smooth and shiny, resembling the image above. If your solder joint has a dull finish, reheat the connection and add more solder.

5. Once the solder joint is in place, snip the lead to the desired length. Usually, you'll simply cut the remaining portion of the lead that isn't part of the actual solder joint. This prevents any risk of short circuits between leftover component leads on the board.

6. Here's a completed soldering example.

DESOLDERING

SMD REMOVAL WITH CHIP QUIK

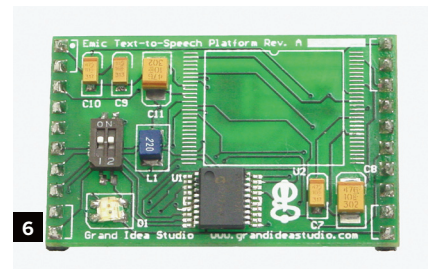
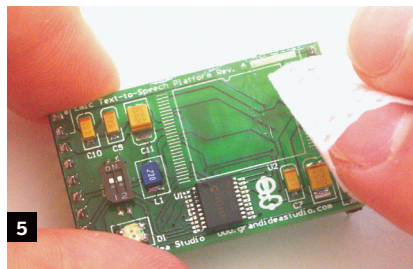
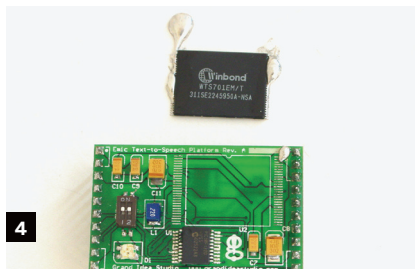
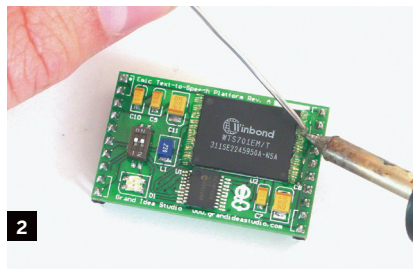
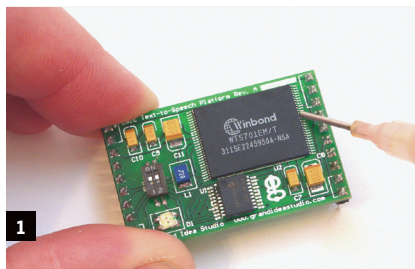
BEFORE YOU START

Use a rubbing alcohol pad to remove any residue from the solder pads. Verify that the solder pads are clean and free of cuts or solder jumps before proceeding. Desoldering, or removing a soldered component from a circuit board, is typically trickier than soldering because you can easily damage the device, the circuit board, or surrounding components. For surface mount devices (SMDs) with more than a few pins, the easiest method to remove the part is the Chip Quik SMD Removal Kit, as shown in the following step-by-step example.

PLEASE READ through this example completely before attempting SMD removal on an actual device. When removing the device, be careful not to scratch or damage any of the surrounding components or pull up any PCB traces.

THREE PRIMARY FUNCTIONS OF FLUX

- » Cleans metal surfaces to assist the flow of *filler metals* (solder) over *base metals* (device pins).
- » Assists with heat transfer from heat source (soldering iron) to metal surface (device pins).
- » Helps in the removal of *surface metal oxides* (created by oxygen in the air when the metal reaches high temperatures).



1. The first step is to assemble the syringe, which contains the no-clean flux. Simply insert the plunger into the syringe and push down to dispense the compound. The flux should be applied evenly across all the pins on the package you'll be removing. (Flux is a chemical compound used to assist in the soldering or removal of electronic components or other metals.)

2. Once the flux is evenly spread over the pins of the target device, the next step is to apply the special Chip Quik alloy to the device. This step is just like soldering: apply heat to the pins of the device and the alloy at the same time. The alloy has a melting point of approximately 300°F, which is quite low. You shouldn't have to heat the alloy with the soldering iron for very long before it begins to melt. The molten alloy should flow around and under

the device pins. Starting at one end of the device, simply heat and apply the alloy. Repeat for the other side(s) of the device.

3. Flux will help ensure a nice flow of the alloy onto the device pins. Make sure the alloy has come in contact with every single pin by gently moving the soldering iron around the edges of the device. Avoid touching nearby components on the PCB with the soldering iron.

4. Now that the alloy has been properly applied to all pins of the device, it's time to remove the device from the board. After making sure that the alloy is still molten by reheating all of it with the soldering iron, gently slide the component off the board. You can use a small, jeweler's flat-tip screwdriver to help with the task. If the device is stuck, reheat the alloy and wiggle

the part back and forth to help the alloy flow underneath the pads of the device and loosen the connections.

5. The final step in the desoldering process is to clean the circuit board. This step is important because it will remove any impurities left behind from the Chip Quik kit and get you ready for the next step.

First, use the soldering iron to remove any stray alloy left on the device pads or anywhere else on the circuit board. Next, apply a thin, even layer of flux to all of the pads that the device was just soldered to. Use the included alcohol swab or a flux-remover spray to remove the flux and clean the area.

6. The desoldering process is now complete. The surface-mount device has been removed and the circuit board cleaned.